MITSUBISHI 8-BIT SINGLE-CHIP MICROCOMPUTER 740 FAMILY / 740 SERIES

7531 Group

User's Manual



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REVISION DESCRIPTION LIST

7531 GROUP USER'S MANUAL

Rev. No.	Revision Description	Rev. date	
1.0	First Edition		
2.0	The contents of revision are mainly as follows;	990924	
	CHAPTER 1 HARDWARE		
	3.1 Electrical characteristics		
	3.2 Typical characteristics		
	3.6 Mask ROM confirmation form		
	3.7 Mark specification form		
2.1	Updated as follows:	991109	
	Page1-2; Power dissipation to 25 mW		
	Page 1-14, Fig.13; Start address of Interrupt vector area to FFEc16		
	Pages 3-6, 3-14, 3-22; Parameter to Linearity error from former Absolute accuracy		
2.2	Page 1-3: Operating temperature range; Note deleted	000614	
	Page 1-9: Fig. 8 "Under development" revised		
	Page 1-29: Fig. 31 Note revised		
	Page 1-32: Description revised; $\overline{\text{RESET}}$ "L" pulse width 2 $\mu s \to 15 \ \mu s$		
	Page 1-36: Fig. 42 Rd resistor connected to XOUT pin eliminated		
	Page 2-42: Fig. 2.3.20 Note added		
	Page 2-58: Fig. 2.5.2 revised		
	Page 3-7: Table 3.1.6 tw($\overline{\text{RESET}}$) revised; 2 $\mu\text{s} \to 15~\mu\text{s}$		
	Table 3.1.7 tw(RESET) revised;		
	$2~\mu s \rightarrow 45~\mu s$ at VCC = 2.2 to 5.5 V, 35 μs at VCC = 2.4 to 5.5 V		
	Page 3-15: Table 3.1.15 tw($\overline{\text{RESET}}$) revised; 2 $\mu s \to$ 15 μs		
	Table 3.1.16 $tw(\overline{RESET})$ revised; 2 $\mu s \rightarrow 35 \mu s$		
	Page 3-23: Table 3.1.24 tw($\overline{\text{RESET}}$) revised; 2 $\mu s \rightarrow$ 15 μs		
	Table 3.1.25 $tw(\overline{RESET})$ revised; 2 $\mu s \rightarrow 35 \mu s$		
	Page 3-34: Description revised; Non-linearity error \rightarrow Linearity error		
	Fig. 3.2.19 revised; Non-linearity error → Linearity error		
	Page 3-35: Fig. 3.2.20 revised; Non-linearity error \rightarrow Linearity error		
	Page 3-36: Fig. 3.2.21 revised; Non-linearity error → Linearity error		
2.3	Pages 1-32, 1-36, 2-42, 3-34: Character fonts errors revised	000905	

Preface

This user's manual describes Mitsubishi's CMOS 8-bit microcomputers 7531 Group.

After reading this manual, the user should have a through knowledge of the functions and features of the 7531 Group, and should be able to fully utilize the product. The manual starts with specifications and ends with application examples.

For details of software, refer to the "740 FAMILY SOFTWARE MANUAL."

For details of development support tools, refer to the "Mitsubishi Microcomputer Development Support Tools" Hompage (http://www.tool-spt.mesc.co.jp/index_e.htm).

BEFORE USING THIS MANUAL

This user's manual consists of the following three chapters. Refer to the chapter appropriate to your conditions, such as hardware design or software development. Chapter 3 also includes necessary information for systems development. You must refer to that chapter.

1. Organization

CHAPTER 1 HARDWARE

This chapter describes features of the microcomputer and operation of each peripheral function.

CHAPTER 2 APPLICATION

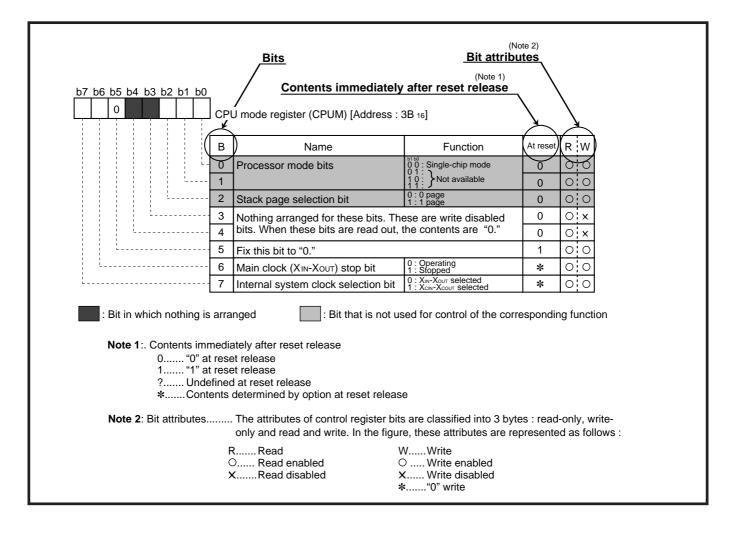
This chapter describes usage and application examples of peripheral functions, based mainly on setting examples of relevant registers.

CHAPTER 3 APPENDIX

This chapter includes necessary information for systems development using the microcomputer, such as the electrical characteristics, the list of registers, the Mask ROM confirmation form (for mask ROM version), the ROM programming confirmation form (for One Time PROM version), and the Mark specification form which are to be submitted when ordering.

2. Structure of register

The figure of each register structure describes its functions, contents at reset, and attributes as follows:



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ROM PROGRAMMING METHOD
FUNCTIONAL DESCRIPTION SUPPLEMENT

DESCRIPTION/FEATURES/APPLICATION/PIN CONFIGURATION

DESCRIPTION

The 7531 Group is the 8-bit microcomputer based on the 740 family core technology.

The 7531 Group has a serial I/O, 8-bit timers, and an A-D converter, and is useful for control of home electric appliances and office automation equipment.

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ГС	м	ıv	П	С;	3

Basic machine-language instructi The minimum instruction execution (ct. 9 M. In addition fragrance for	on time 0.50 μs
(at 8 MHz oscillation frequency for speed mode)	the shortest instruction, in high-
'	01/ to 401/ h. to
Memory size ROM	
RAM	256 to 384 bytes
Programmable I/O ports	29
	(25 in 32-pin version)
Interrupts	12 sources, 8 vectors
(11 sourc	es, 8 vectors for 32-pin version)
• Timers	8-bit X 3
Serial I/O1	8-bit X 1
	(UART)
Serial I/O2	8-bit × 1
	(Clock-synchronized)
A-D converter	10-bit X 8 channels
	(6 channels for 32-pin version)
Clock generating circuit	Built-in type
(connect to external ceramic reso	nator or quartz-crystal oscillator

■ Watchdog timer 16-bit X 1
Power source voltage
At 8 MHz XIN oscillation frequency at ceramic oscillation
4.0 to 5.5 V
At 4 MHz XIN oscillation frequency at ceramic oscillation
At 2 MHz XIN oscillation frequency at ceramic oscillation
2.2 to 5.5 V
At 4 MHz XIN oscillation frequency at RC oscillation
4.0 to 5.5 V
At 2 MHz XIN oscillation frequency at RC oscillation
2.4 to 5.5 V
At 1 MHz XIN oscillation frequency at RC oscillation
Power dissipation
 ◆ Operating temperature range –20 to 85 °C
(–40 to 85 $^{\circ}\text{C}$ or –40 to 125 $^{\circ}\text{C}$ for extended operating temperature version)

APPLICATION

Office automation equipment, factory automation equipment, home electric appliances, consumer electronics, car, etc.

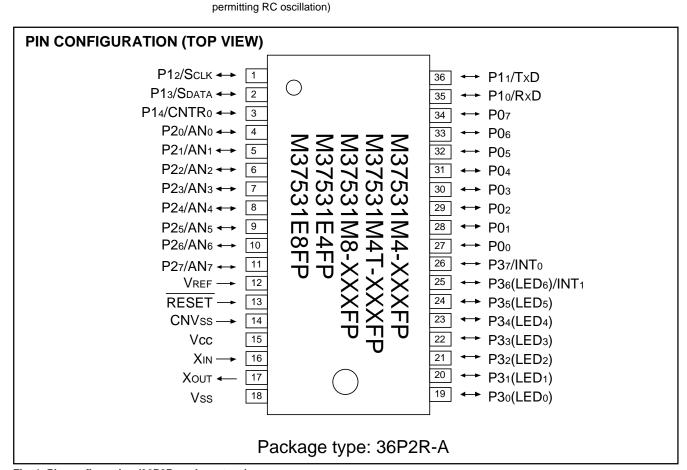


Fig. 1 Pin configuration (36P2R package type)

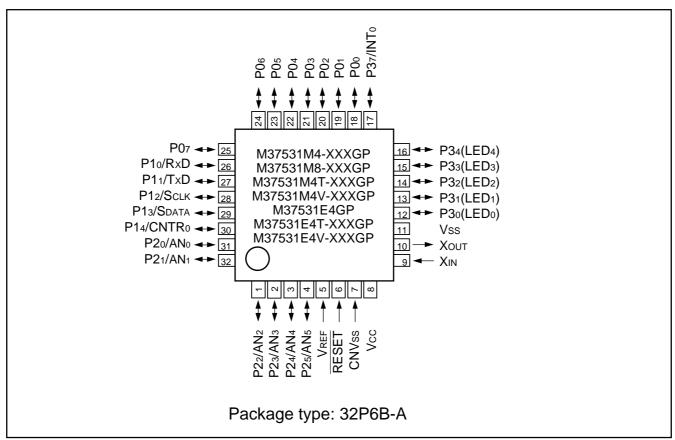


Fig. 2 Pin configuration (32P6B package type)

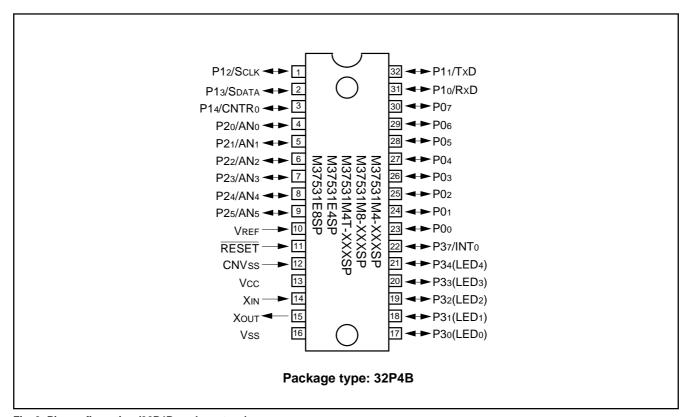


Fig. 3 Pin configuration (32P4B package type)

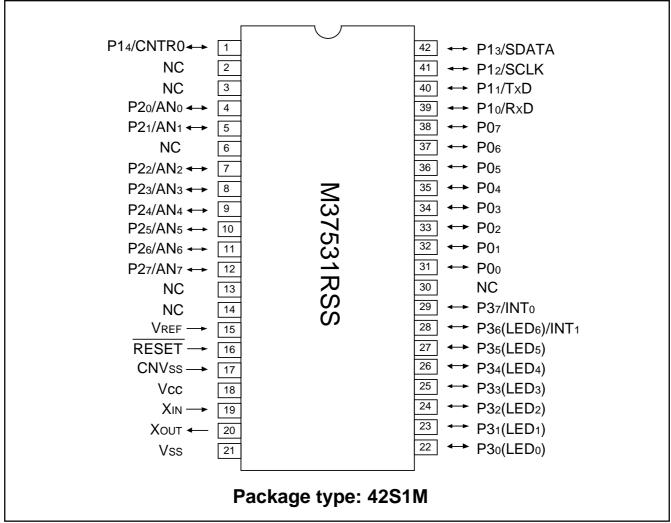


Fig. 4 Pin configuration (42S1M package type)

FUNCTIONAL BLOCK

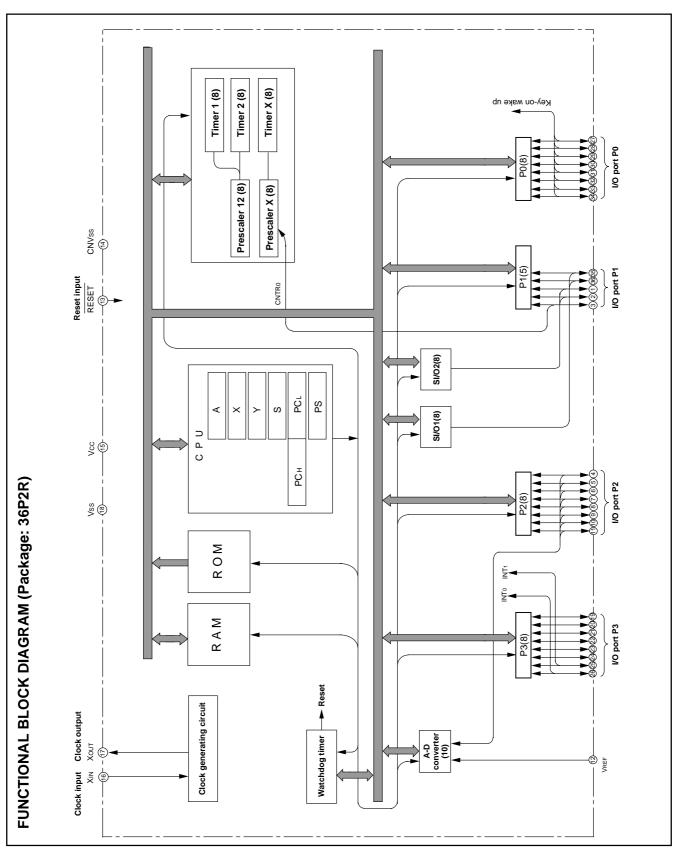


Fig. 5 Functional block diagram (36P2R package)

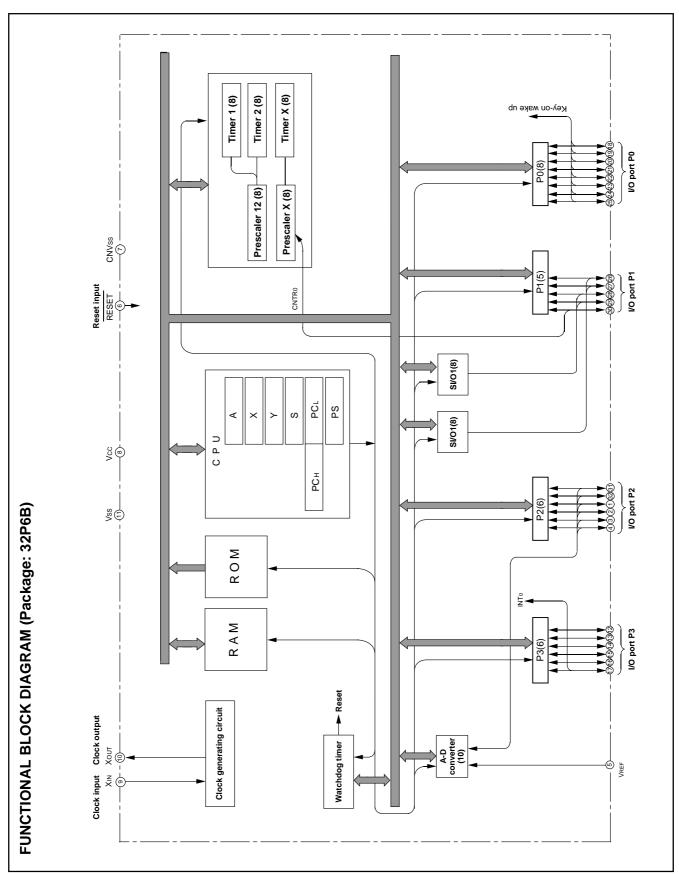


Fig. 6 Functional block diagram (32P6B package)

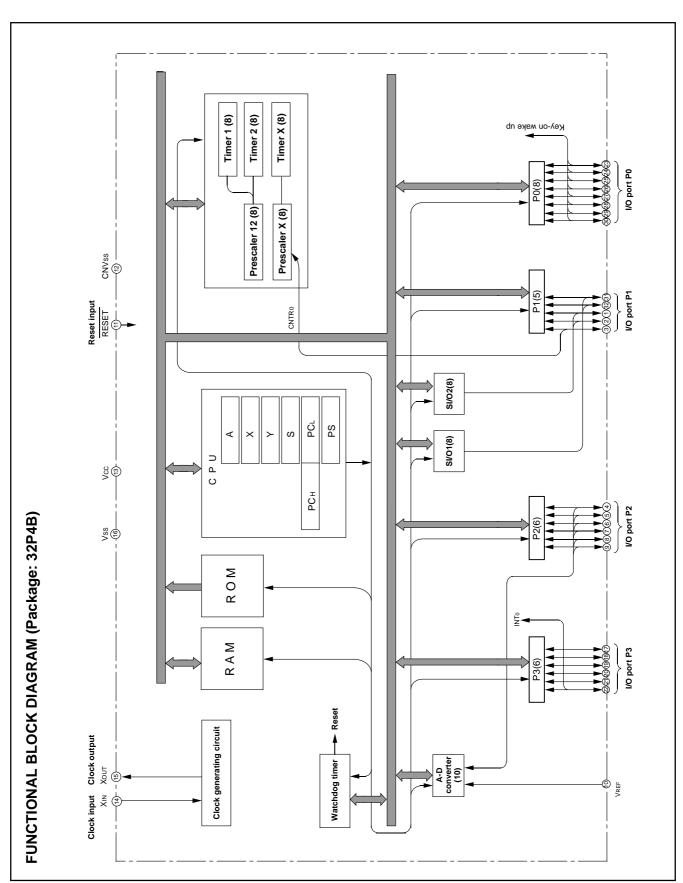


Fig. 7 Functional block diagram (32P4B package)

PIN DESCRIPTION

PIN DESCRIPTION

Table 1 Pin description

Pin	Name	Function	Function expect a port function				
Vcc, Vss	Power source (Note 1)	•Apply voltage of 2.2–5.5 V to Vcc, and 0 V to Vss.					
VREF	Analog reference voltage	•Reference voltage input pin for A-D converter					
CNVss	CNVss	•Chip operating mode control pin, which is always connected to Vss.					
RESET	Reset input	•Reset input pin for active "L"					
XIN	Clock input	•Input and output pins for main clock generating circuit					
		•Connect a ceramic resonator or quartz crystal oscillator between	n the XIN and Xouт pins.				
Хоит	Clock output	•For using RC oscillator, short between the XIN and XOUT pins, ar	nd connect the capacitor and resistor				
		•If an external clock is used, connect the clock source to the Xin բ	oin and leave the Xout pin open.				
P00-P07	I/O port P0	•8-bit I/O port.	•Key-input (key-on wake up				
		•I/O direction register allows each pin to be individually programmed as either input or output.	interrupt input) pins				
		CMOS compatible input level					
		CMOS 3-state output structure					
		•Whether a built-in pull-up resistor is to be used or not can be determined by program.					
P1o/RxD	I/O port P1	•5-bit I/O port	•Serial I/O1 function pin				
P11/TxD		•I/O direction register allows each pin to be individually pro-					
P12/SCLK		grammed as either input or output.	•Serial I/O2 function pin				
P13/SDATA		•CMOS compatible input level					
P14/CNTR0		•CMOS 3-state output structure	•Timer X function pin				
50 (41)	1/0 / 50 (1) / 0)	•CMOS/TTL level can be switched for P10, P12 and P13	<u> </u>				
P20/AN0- P27/AN7	I/O port P2 (Note 2)	•8-bit I/O port having almost the same function as P0	•Input pins for A-D converter				
		•CMOS compatible input level					
	I/O nort D2 (Note 2)	•CMOS 3-state output structure					
P30-P35	I/O port P3 (Note 3)	•8-bit I/O port					
		•I/O direction register allows each pin to be individually programmed as either input or output. •CMOS compatible input level (CMOS/TTL level can be switched for P36 and P37).					
		CMOS 3-state output structure	1101 F36 and F37).				
		•					
DO-/INIT	_	P36 to P36 can output a large current for driving LED. Whether a built in pull up reciptor is to be used or not can be	Laterman discount i				
P36/INT ₁ P37/INT ₀	2.4 to 5.5 V for the co	Whether a built-in pull-up resistor is to be used or not can be determined by program.	•Interrupt input pins				

Notes 1: Vcc = 2.4 to 5.5 V for the extended operating temperature version (-40 to 85 °C) and the extended operating temperature 125 °C version (-40 to 125 °C).

^{2: 6-}bit I/O port (P20-P25) for the 32-pin version.

^{3: 6-}bit I/O port (P30-P34, P37/INT0) for the 32-pin version.

GROUP EXPANSION

Mitsubishi plans to expand the 7531 group as follow:

Memory type

Support for Mask ROM version, One Time PROM version, and Emulator MCU .

Memory size

Package

32P4B	32 pin plastic molded SDIP
32P6B-A	0.8 mm-pitch plastic molded LQFP
36P2R-A	0.8 mm-pitch plastic molded SSOP
42S1M	42 pin shrink ceramic PIGGY BACK

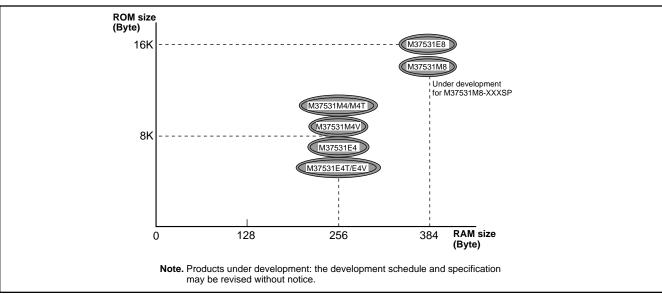


Fig. 8 Memory expansion plan

Currently supported products are listed below.

Table 2 List of supported products

Product	(P) ROM size (bytes) ROM size for User ()	RAM size (bytes)	Package	Remarks
M37531M4-XXXSP			32P4B	Mask ROM version
M37531M4T-XXXSP				Mask ROM version (extended operating temperature version)
M37531E4SP				One Time PROM version (blank)
M37531M4-XXXFP				Mask ROM version
M37531M4T-XXXFP			36P2R-A	Mask ROM version (extended operating temperature version)
M37531E4FP	-			One Time PROM version (blank)
M37531M4-XXXGP	8192 (8062)	256		Mask ROM version
M37531M4T-XXXGP	6192 (6002)		32P6B-A	Mask ROM version (extended operating temperature version)
M37531M4V-XXXGP	-			Mask ROM version (extended operating temperature 125 °C version)
M37531E4GP	-			One Time PROM version (blank)
M37531E4T-XXXGP				One Time PROM version (shipped after programming, extended
	-			operating temperature version)
M37531E4V-XXXGP				One Time PROM version (shipped after programming, extended
				operating temperature 125 °C version)
M37531M8-XXXSP			32P4B	Mask ROM version
M37531E8SP	-	384	32P4B	One Time PROM version (blank)
M37531M8-XXXFP	16384 (16254)		36P2R-A 32P6B-A	Mask ROM version
M37531E8FP	-			One Time PROM version (blank)
M37531M8-XXXGP	1			Mask ROM version
M37531RSS			42S1M	Emulator MCU

FUNCTIONAL DESCRIPTION

FUNCTIONAL DESCRIPTION Central Processing Unit (CPU)

The 7531 group uses the standard 740 family instruction set. Refer to the table of 740 family addressing modes and machine instructions or the 740 Family Software Manual for details on the instruction set. Machine-resident 740 family instructions are as follows:

The FST and SLW instructions cannot be used.

The MUL and DIV instructions cannot be used.

The WIT and STP instructions can be used.

The central processing unit (CPU) has the six registers.

Accumulator (A)

The accumulator is an 8-bit register. Data operations such as data transfer, etc., are executed mainly through the accumulator.

Index register X (X), Index register Y (Y)

Both index register X and index register Y are 8-bit registers. In the index addressing modes, the value of the OPERAND is added to the contents of register X or register Y and specifies the real address. When the T flag in the processor status register is set to "1", the value contained in index register X becomes the address for the second OPERAND.

Stack pointer (S)

The stack pointer is an 8-bit register used during sub-routine calls and interrupts. The stack is used to store the current address data and processor status when branching to subroutines or interrupt routines. The lower eight bits of the stack address are determined by the contents of the stack pointer. The upper eight bits of the stack address are determined by the Stack Page Selection Bit. If the Stack Page Selection Bit is "0", then the RAM in the zero page is used as the stack area. If the Stack Page Selection Bit is "1", then RAM in page 1 is used as the stack area.

The Stack Page Selection Bit is located in the SFR area in the zero page. Note that the initial value of the Stack Page Selection Bit varies with each microcomputer type. Also some microcomputer types have no Stack Page Selection Bit and the upper eight bits of the stack address are fixed. The operations of pushing register contents onto the stack and popping them from the stack are shown in Figure 10.

Program counter (PC)

The program counter is a 16-bit counter consisting of two 8-bit registers PCH and PCL. It is used to indicate the address of the next instruction to be executed.

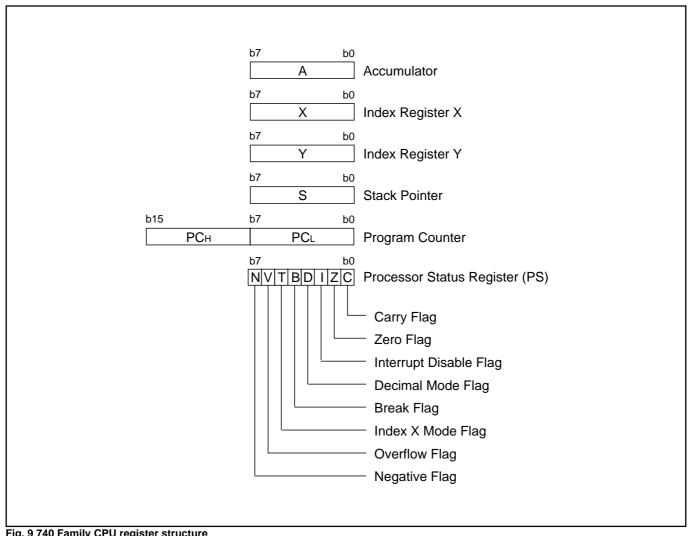


Fig. 9 740 Family CPU register structure

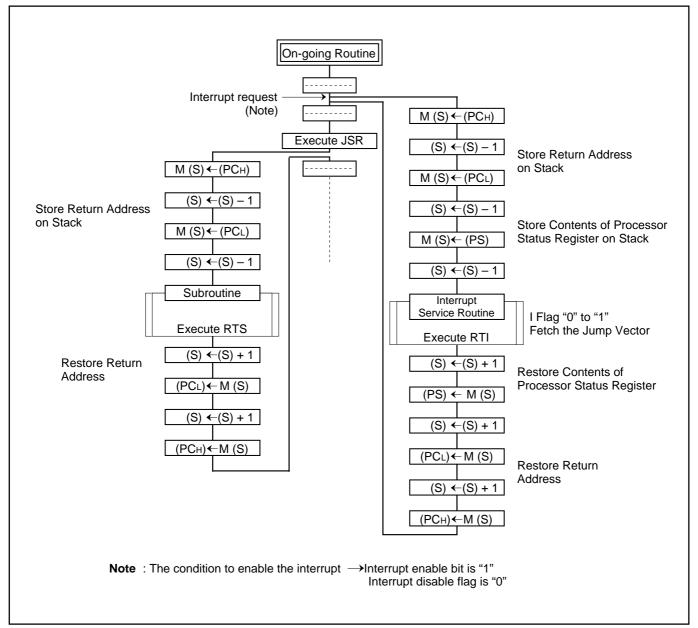


Fig. 10 Register push and pop at interrupt generation and subroutine call

Table 3 Push and pop instructions of accumulator or processor status register

	Push instruction to stack	Pop instruction from stack
Accumulator	PHA	PLA
Processor status register	PHP	PLP

FUNCTIONAL DESCRIPTION

Processor status register (PS)

The processor status register is an 8-bit register consisting of flags which indicate the status of the processor after an arithmetic operation. Branch operations can be performed by testing the Carry (C) flag, Zero (Z) flag, Overflow (V) flag, or the Negative (N) flag. In decimal mode, the Z, V, N flags are not valid.

After reset, the Interrupt disable (I) flag is set to "1", but all other flags are undefined. Since the Index X mode (T) and Decimal mode (D) flags directly affect arithmetic operations, they should be initialized in the beginning of a program.

(1) Carry flag (C)

The C flag contains a carry or borrow generated by the arithmetic logic unit (ALU) immediately after an arithmetic operation. It can also be changed by a shift or rotate instruction.

(2) Zero flag (Z)

The Z flag is set if the result of an immediate arithmetic operation or a data transfer is "0", and cleared if the result is anything other than "0".

(3) Interrupt disable flag (I)

The I flag disables all interrupts except for the interrupt generated by the BRK instruction.

Interrupts are disabled when the I flag is "1".

When an interrupt occurs, this flag is automatically set to "1" to prevent other interrupts from interfering until the current interrupt is serviced.

(4) Decimal mode flag (D)

The D flag determines whether additions and subtractions are executed in binary or decimal. Binary arithmetic is executed when this flag is "0"; decimal arithmetic is executed when it is "1". Decimal correction is automatic in decimal mode. Only the ADC and SBC instructions can be used for decimal arithmetic.

(5) Break flag (B)

The B flag is used to indicate that the current interrupt was generated by the BRK instruction. The BRK flag in the processor status register is always "0". When the BRK instruction is used to generate an interrupt, the processor status register is pushed onto the stack with the break flag set to "1". The saved processor status is the only place where the break flag is ever set.

(6) Index X mode flag (T)

When the T flag is "0", arithmetic operations are performed between accumulator and memory, e.g. the results of an operation between two memory locations is stored in the accumulator. When the T flag is "1", direct arithmetic operations and direct data transfers are enabled between memory locations, i.e. between memory and memory, memory and I/O, and I/O and I/O. In this case, the result of an arithmetic operation performed on data in memory location 1 and memory location 2 is stored in memory location 1. The address of memory location 1 is specified by index register X, and the address of memory location 2 is specified by normal addressing modes.

(7) Overflow flag (V)

The V flag is used during the addition or subtraction of one byte of signed data. It is set if the result exceeds +127 to -128. When the BIT instruction is executed, bit 6 of the memory location operated on by the BIT instruction is stored in the overflow flag.

(8) Negative flag (N)

The N flag is set if the result of an arithmetic operation or data transfer is negative. When the BIT instruction is executed, bit 7 of the memory location operated on by the BIT instruction is stored in the negative flag.

Table 4 Set and clear instructions of each bit of processor status register

	C flag	Z flag	I flag	D flag	B flag	T flag	V flag	N flag
Set instruction	SEC	-	SEI	SED	-	SET	_	_
Clear instruction	CLC	_	CLI	CLD	-	CLT	CLV	_

[CPU Mode Register] CPUM

The CPU mode register contains the stack page selection bit.

This register is allocated at address 003B₁₆.

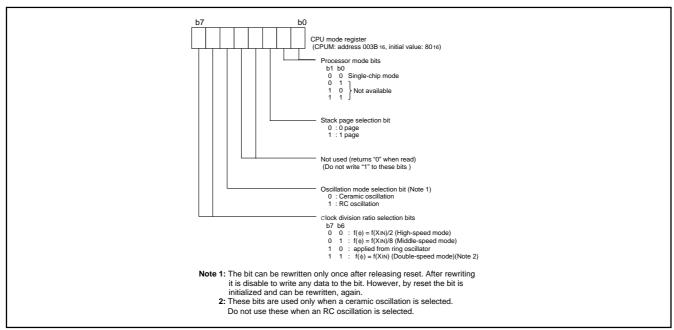


Fig. 11 Structure of CPU mode register

Switching method of CPU mode register

Switch the CPU mode register (CPUM) at the head of program after releasing Reset in the following method.

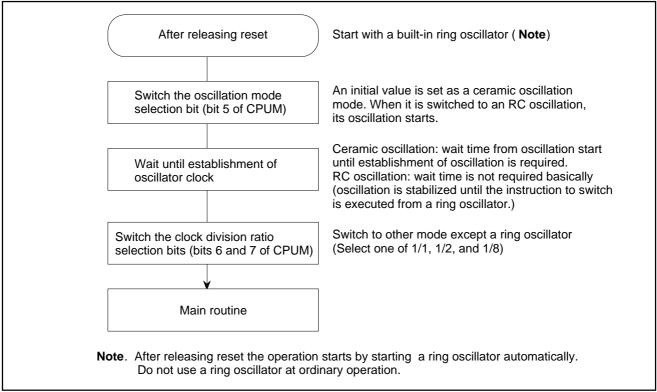


Fig. 12 Switching method of CPU mode register

FUNCTIONAL DESCRIPTION

Memory

Special function register (SFR) area

The SFR area in the zero page contains control registers such as I/O ports and timers.

RAM

RAM is used for data storage and for a stack area of subroutine calls and interrupts.

ROM

The first 128 bytes and the last 2 bytes of ROM are reserved for device testing and the rest is a user area for storing programs.

Interrupt vector area

The interrupt vector area contains reset and interrupt vectors.

Zero page

The 256 bytes from addresses 000016 to 00FF16 are called the zero page area. The internal RAM and the special function registers (SFR) are allocated to this area.

The zero page addressing mode can be used to specify memory and register addresses in the zero page area. Access to this area with only 2 bytes is possible in the zero page addressing mode.

Special page

The 256 bytes from addresses FF0016 to FFFF16 are called the special page area. The special page addressing mode can be used to specify memory addresses in the special page area. Access to this area with only 2 bytes is possible in the special page addressing mode.

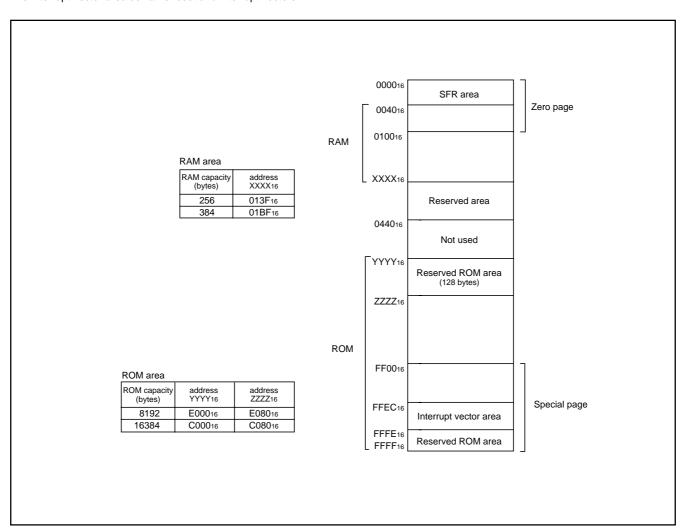


Fig. 13 Memory map diagram

000016	Port P0 (P0)	002016	
000116	Port P0 direction register (P0D)	002116	
000216	Port P1 (P1)	002216	
000316	Port P1 direction register (P1D)	002316	
000416	Port P2 (P2)	002416	
000516	Port P2 direction register (P2D)	002516	
000616	Port P3 (P3)	002616	
000716	Port P3 direction register (P3D)	002716	
000816		002816	Prescaler 12 (PRE12)
000916		002916	Timer 1 (T1)
000A16		002A ₁₆	Timer 2 (T2)
000B16		002B ₁₆	Timer X mode register (TM)
000C16		002C ₁₆	Prescaler X (PREX)
000D16		002D16	Timer X (TX)
000E16		002E ₁₆	Timer count source set register (TCSS)
000F16		002F ₁₆	
001016		003016	Serial I/O2 control register (SIO2CON)
001116		003116	Serial I/O2 register (SIO2)
001216		003216	
001316		003316	
001416		003416	A-D control register (ADCON)
001516		003516	A-D conversion register (low-order) (ADL)
001616	Pull-up control register (PULL)	003616	A-D conversion register (high-order) (ADH)
001716	Port P1P3 control register (P1P3C)	003716	
001816	Transmit/Receive buffer register (TB/RB)	003816	MISRG
001916	Serial I/O1 status register (SIO1STS)	003916	Watchdog timer control register (WDTCON)
001A ₁₆	Serial I/O1 control register (SIO1CON)	003A ₁₆	Interrupt edge selection register (INTEDGE)
001B ₁₆	UART control register (UARTCON)	003B ₁₆	CPU mode register (CPUM)
001C ₁₆	Baud rate generator (BRG)	003C ₁₆	Interrupt request register 1 (IREQ1)
001D ₁₆		003D ₁₆	
001E ₁₆		003E ₁₆	Interrupt control register 1 (ICON1)
001F ₁₆		003F16	

Fig. 14 Memory map of special function register (SFR)

FUNCTIONAL DESCRIPTION

I/O Ports

[Direction registers] PiD

The I/O ports have direction registers which determine the input/output direction of each pin. Each bit in a direction register corresponds to one pin, and each pin can be set to be input or output.

When "1" is set to the bit corresponding to a pin, this pin becomes an output port. When "0" is set to the bit, the pin becomes an input port. When data is read from a pin set to output, not the value of the pin itself but the value of port latch is read. Pins set to input are floating, and permit reading pin values.

If a pin set to input is written to, only the port latch is written to and the pin remains floating.

[Pull-up control] PULL

By setting the pull-up control register (address 001616), ports P0 and P3 can exert pull-up control by program. However, pins set to output are disconnected from this control and cannot exert pull-up control.

[Port P1P3 control] P1P3C

By setting the port P1P3 control register (address 0017₁₆), a CMOS input level or a TTL input level can be selected for ports P1₀, P1₂, P1₃, P3₆, and P3₇ by program.

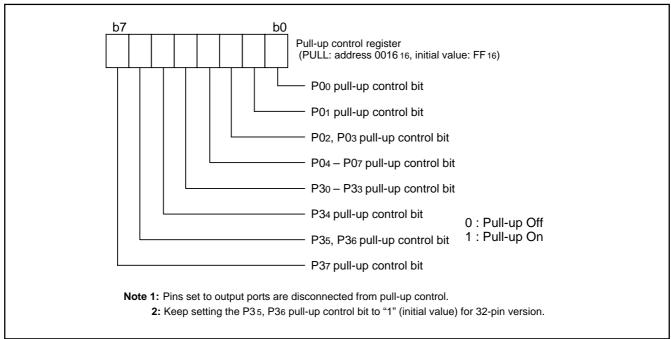


Fig. 15 Structure of pull-up control register

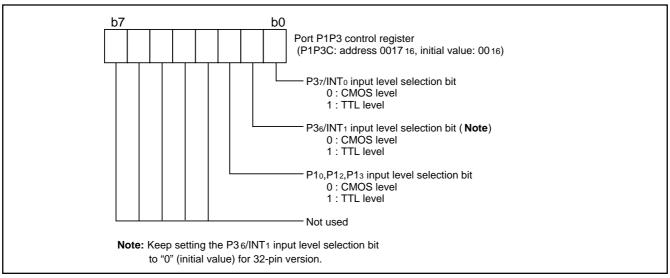


Fig. 16 Structure of port P1P3 control register

Table 5 I/O port function table

Pin	Name	Input/output	I/O format	Non-port function	Related SFRs	Diagram No.
P00-P07	I/O port P0	I/O individual bits	•CMOS compatible input level •CMOS 3-state output	Key input interrupt	Pull-up control register	(1)
P1o/RxD	I/O port P1		(Note 1)	Serial I/O1 function	Serial I/O1 control	(2)
P1 ₁ /TxD				input/output	register	(3)
P12/SCLK				Serial I/O2 function	Serial I/O2 control	(4)
P13/SDATA				input/output	register	(5)
P14/CNTR0				Timer X function input/output	Timer X mode register	(6)
P20/AN0- P27/AN7	I/O port P2 (Note 2)			A-D conversion input	A-D control register	(7)
P30-P35	I/O port P3					(8)
P36/INT1 P37/INT0	(Note 3)			External interrupt input	Interrupt edge selection register	(9)

Notes 1: Ports P10, P12, P13, P36, and P37 are CMOS/TTL level.

^{2:} The P26/AN6 and P27/AN7 pins do not exist for the 32-pin version.

^{3:} The P35 and P36/INT1 pins do not exist for the 32-pin version.

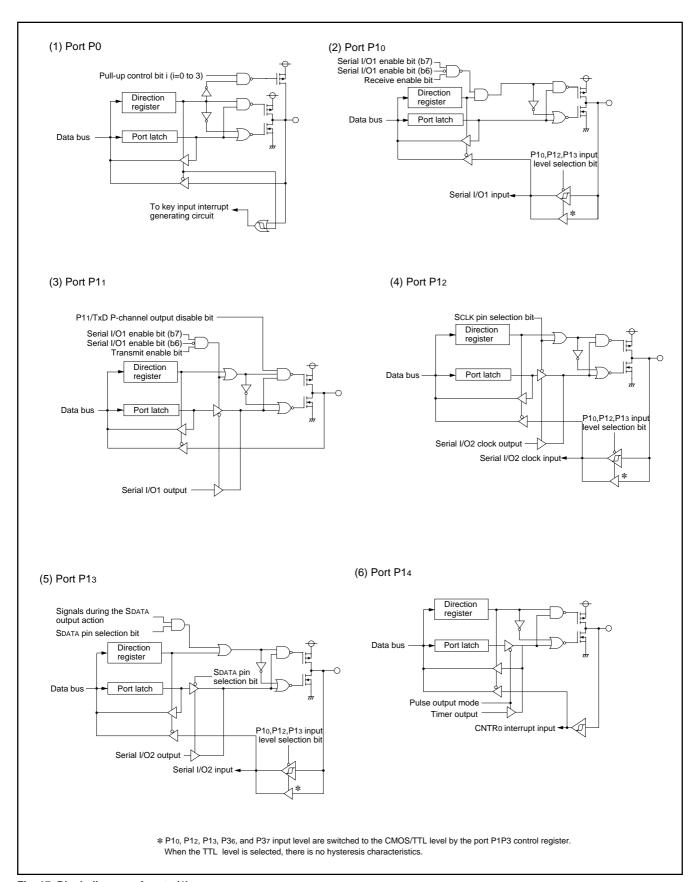


Fig. 17 Block diagram of ports (1)

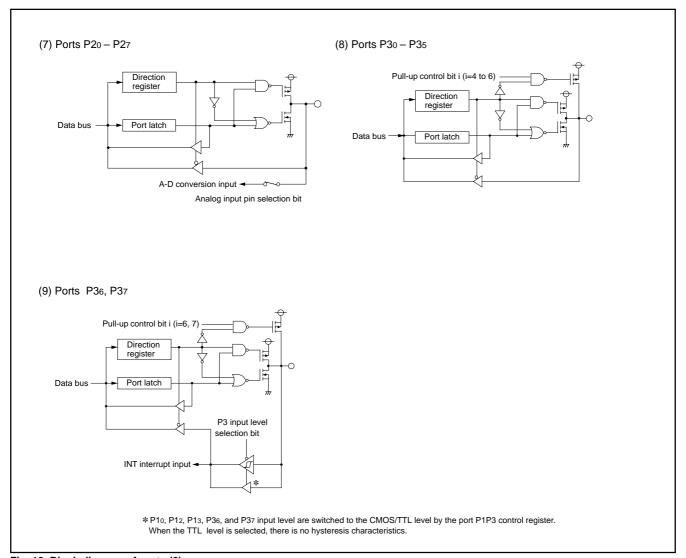


Fig. 18 Block diagram of ports (2)

FUNCTIONAL DESCRIPTION

Interrupts

Interrupts occur by 12 different sources: 4 external sources, 7 internal sources and 1 software source.

Interrupt control

All interrupts except the BRK instruction interrupt have an interrupt request bit and an interrupt enable bit, and they are controlled by the interrupt disable flag. When the interrupt enable bit and the interrupt request bit are set to "1" and the interrupt disable flag is set to "0", an interrupt is accepted.

The interrupt request bit can be cleared by program but not be set. The interrupt enable bit can be set and cleared by program.

It becomes usable by switching CNTR0 and AD conversion interrupt sources with bit 7 of the interrupt edge selection register, timer 2 and serial I/O2 interrupt sources with bit 6, timer X and key-on wake-up interrupt sources with bit 5, and serial I/O1 transmit and INT1 interrupt sources with bit 4.

The reset and BRK instruction interrupt can never be disabled with any flag or bit. All interrupts except these are disabled when the interrupt disable flag is set.

When several interrupts occur at the same time, the interrupts are received according to priority.

Interrupt operation

Upon acceptance of an interrupt the following operations are automatically performed:

- 1. The processing being executed is stopped.
- 2. The contents of the program counter and processor status register are automatically pushed onto the stack.
- The interrupt disable flag is set and the corresponding interrupt request bit is cleared.
- 4. Concurrently with the push operation, the interrupt destination address is read from the vector table into the program counter.

Notes on use

When the active edge of an external interrupt (INTo, INT1,CNTRo) is set, the interrupt request bit may be set.

Therefore, please take following sequence:

- 1. Disable the external interrupt which is selected.
- Change the active edge in interrupt edge selection register. (in case of CNTRo: Timer X mode register)
- 3. Clear the set interrupt request bit to "0".
- 4. Enable the external interrupt which is selected.

Table 6 Interrupt vector address and priority

	.	Vector addresses (Note 1) High-order Low-order			Remarks	
Interrupt source	Priority			Interrupt request generating conditions		
Reset (Note 2)	1	FFFD16	FFFC16	At reset input	Non-maskable	
Serial I/O1 receive	2	FFFB ₁₆	FFFA ₁₆	At completion of serial I/O1 data receive	Valid when serial I/O1 is selected	
Serial I/O1 transmit	3	FFF916	FFF816	At completion of serial I/O1 transmit shift or when transmit buffer is empty	Valid when serial I/O1 is selected	
INT ₁ (Note 3)				At detection of either rising or falling edge of INT1 input	External interrupt (active edge selectable)	
INT ₀	4	FFF7 ₁₆	FFF616	At detection of either rising or falling edge of INTo input	External interrupt (active edge selectable)	
Timer X	5	FFF516	FFF416	At timer X underflow		
Key-on wake-up				At falling of conjunction of input logical level for port P0 (at input)	External interrupt (valid at falling)	
Timer 1	6	FFF316	FFF216	At timer 1 underflow	STP release timer underflow	
Timer 2	7	FFF1 ₁₆	FFF016	At timer 2 underflow		
Serial I/O2	1			At completion of transmit/receive shift		
CNTR ₀	8	FFEF16	FFEE16	At detection of either rising or falling edge of CNTR ₀ input	External interrupt (active edge selectable)	
A-D conversion				At completion of A-D conversion		
BRK instruction	9	FFED ₁₆	FFEC ₁₆	At BRK instruction execution	Non-maskable software interrupt	

Note 1: Vector addressed contain internal jump destination addresses.

- 2: Reset function in the same way as an interrupt with the highest priority.
- 3: It is an interrupt which can use only for 36 pin version.

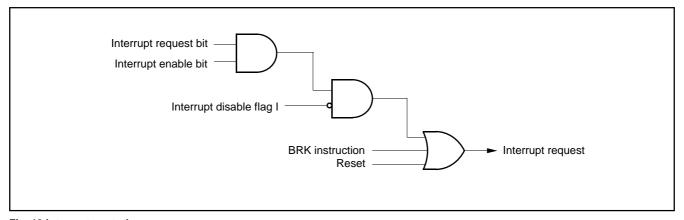


Fig. 19 Interrupt control

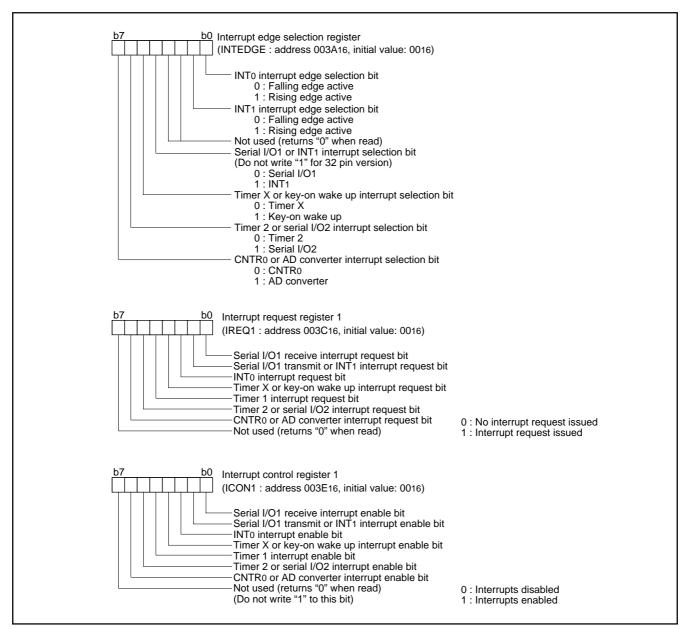


Fig. 20 Structure of Interrupt-related registers

FUNCTIONAL DESCRIPTION

Key Input Interrupt (Key-On Wake-Up)

A key-on wake-up interrupt request is generated by applying "L" level to any pin of port P0 that has been set to input mode.

In other words, it is generated when the AND of input level goes from "1" to "0". An example of using a key input interrupt is shown in Figure 21, where an interrupt request is generated by pressing one of the keys provided as an active-low key matrix which uses ports P00 to P03 as input ports.

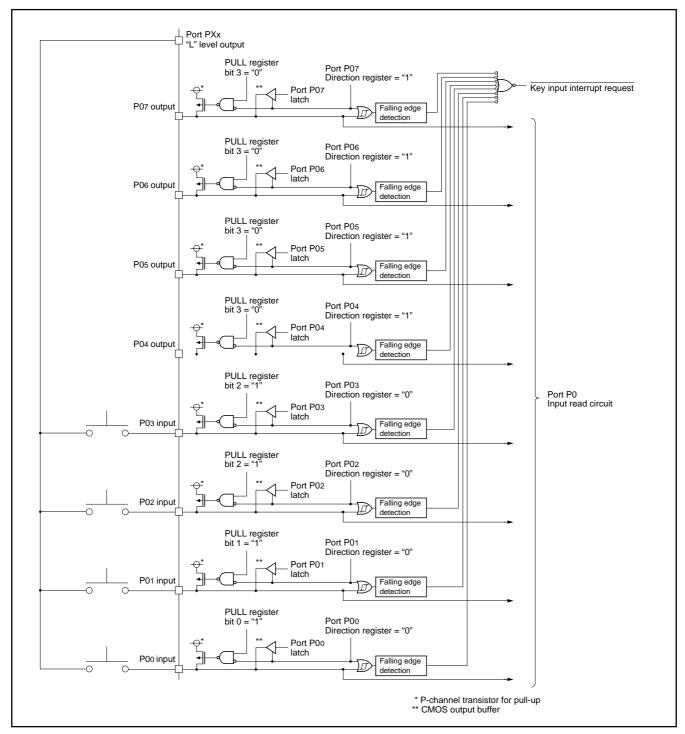


Fig. 21 Connection example when using key input interrupt and port P0 block diagram

Timers

The 7531 Group has 3 timers: timer X, timer 1 and timer 2.

The division ratio of every timer and prescaler is 1/(n+1) provided that the value of the timer latch or prescaler is n.

All the timers are down count timers. When a timer reaches "0", an underflow occurs at the next count pulse, and the corresponding timer latch is reloaded into the timer. When a timer underflows, the interrupt request bit corresponding to each timer is set to "1".

●Timer 1, Timer 2

Prescaler 12 always counts f(XIN)/16. Timer 1 and timer 2 always count the prescaler output and periodically sets the interrupt request bit

●Timer X

Timer X can be selected in one of 4 operating modes by setting the timer X mode register.

• Timer Mode

The timer counts the signal selected by the timer X count source selection bit

• Pulse Output Mode

The timer counts the signal selected by the timer X count source selection bit, and outputs a signal whose polarity is inverted each time the timer value reaches "0", from the CNTRo pin.

When the CNTR₀ active edge switch bit is "0", the output of the CNTR₀ pin is started with an "H" output.

At "1", this output is started with an "L" output. When using a timer in this mode, set the port P14 direction register to output mode.

• Event Counter Mode

The operation in the event counter mode is the same as that in the timer mode except that the timer counts the input signal from the CNTR₀ pin.

When the CNTR₀ active edge switch bit is "0", the timer counts the rising edge of the CNTR₀ pin. When this bit is "1", the timer counts the falling edge of the CNTR₀ pin.

• Pulse Width Measurement Mode

When the CNTRo active edge switch bit is "0", the timer counts the signal selected by the timer X count source selection bit while the CNTRo pin is "H". When this bit is "1", the timer counts the signal while the CNTRo pin is "L".

In any mode, the timer count can be stopped by setting the timer X count stop bit to "1". Each time the timer overflows, the interrupt request bit is set.

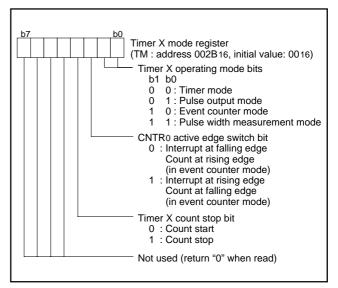


Fig. 22 Structure of timer X mode register

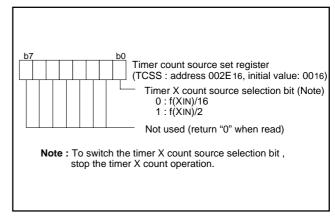


Fig. 23 Timer count source setting register

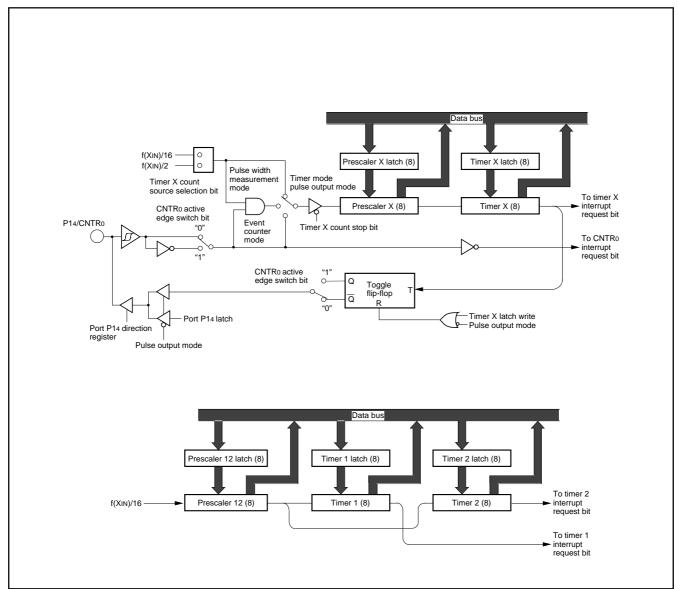


Fig. 24 Block diagram of timer X, timer 1 and timer 2

Serial I/O

●Serial I/O1

Serial I/O1 can be used as an asynchronous (UART) serial I/O. A dedicated timer (baud rate generator) is also provided for baud rate generation when serial I/O1 is in operation.

Eight serial data transfer formats can be selected, and the transfer formats to be used by a transmitter and a receiver must be identical. Each of the transmit and receive shift registers has a buffer register (the same address on memory). Since the shift register cannot be written to or read from directly, transmit data is written to the transmit

buffer, and receive data is read from the respective buffer registers. These buffer registers can also hold the next data to be transmitted and receive 2-byte receive data in succession.

By selecting "1" for continuous transmit valid bit (bit 2 of SIO1CON), continuous transmission of the same data is made possible.

This can be used as a simplified PWM.

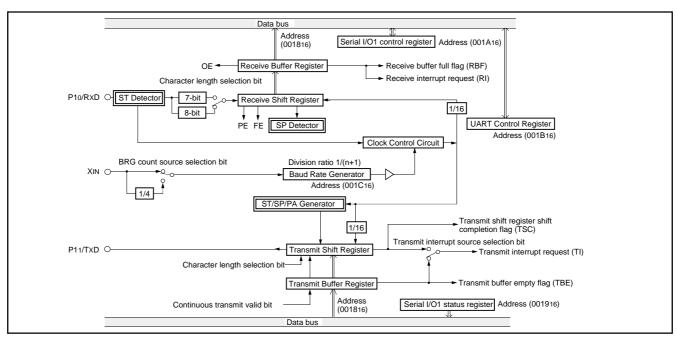


Fig. 25 Block diagram of UART serial I/O

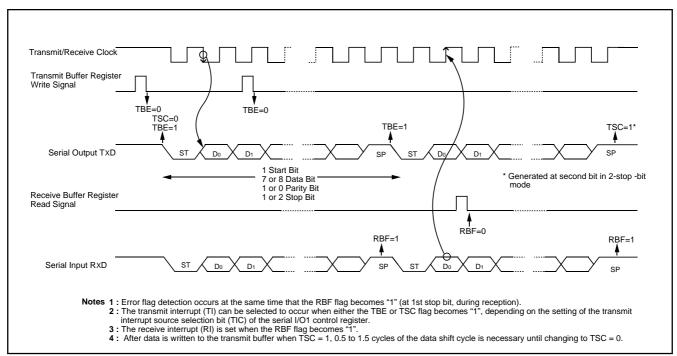


Fig. 26 Operation of UART serial I/O function

FUNCTIONAL DESCRIPTION

[Serial I/O1 control register] SIO1CON

The serial I/O1 control register consists of eight control bits for the serial I/O1 function.

[UART control register] UARTCON

The UART control register consists of four control bits (bits 0 to 3) which are valid when asynchronous serial I/O is selected and set the data format of an data transfer. One bit in this register (bit 4) is always valid and sets the output structure of the P11/TxD pin.

[Serial I/O1 status register] SIO1STS

The read-only serial I/O1 status register consists of seven flags (bits 0 to 6) which indicate the operating status of the serial I/O function and various errors.

The receive buffer full flag (bit 1) is cleared to "0" when the receive buffer is read.

If there is an error, it is detected at the same time that data is transferred from the receive shift register to the receive buffer, and the receive buffer full flag is set. A write to the serial I/O1 status register clears all the error flags OE, PE, FE, and SE (bit 3 to bit 6, respectively). Writing "11" to bits 7 and 6 of the serial I/O1 control register initializes this register.

All bits of the serial I/O1 status register are initialized to "8116" at reset

[Transmit/Receive buffer register] TB/RB

The transmit buffer and the receive buffer are located at the same address. The transmit buffer is write-only and the receive buffer is read-only. If a character bit length is 7-bit, the MSB of data stored in the receive buffer is "0".

[Baud Rate Generator] BRG

The baud rate generator determines the baud rate for serial transfer. The baud rate generator divides the frequency of the count source by 1/(n + 1), where n is the value written to the baud rate generator.

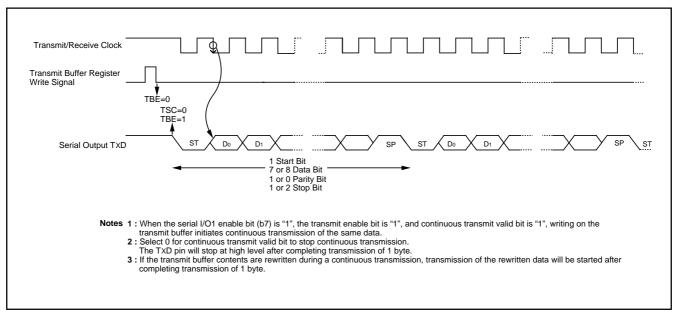


Fig. 27 Continuous transmission operation of UART serial I/O

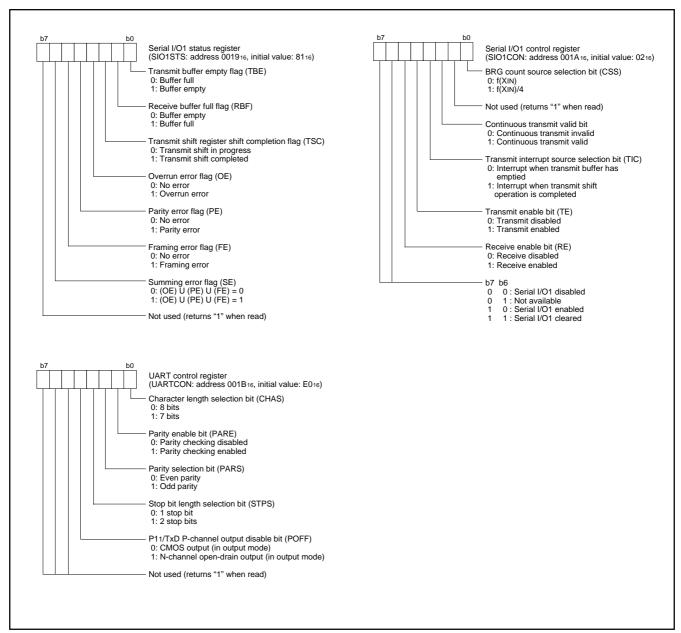


Fig. 28 Structure of serial I/O1-related registers (1)

FUNCTIONAL DESCRIPTION

●Serial I/O2

The serial I/O2 function can be used only for clock synchronous serial I/O.

For clock synchronous serial I/O2 the transmitter and the receiver must use the same clock. When the internal clock is used, transfer is started by a write signal to the serial I/O2 register.

[Serial I/O2 control register] SIO2CON

The serial I/O2 control register contains 8 bits which control various serial I/O functions.

- •Set "0" to bit 3 to receive.
- •At reception, clear bit 7 to "0" by writing a dummy data to the serial I/O2 register after completion of shift.
- •Bit 7 is set to "1" a half cycle (of the shift clock) earlier than completion of shift operation. Accordingly, when using this bit to confirm shift completion, a half cycle or more of the shift clock must pass after confirming that this bit is set to "1", before performing read/write to the serial I/O2 register.

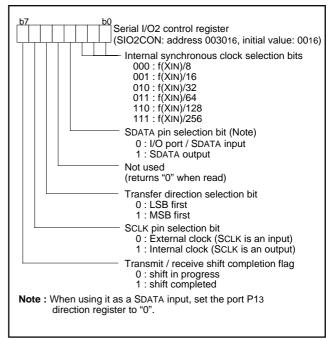


Fig. 29 Structure of serial I/O2 control registers

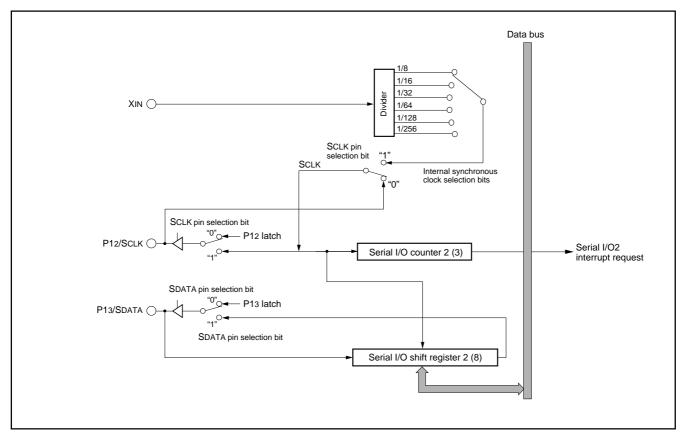


Fig. 30 Block diagram of serial I/O2

Serial I/O2 operation

By writing to the serial I/O2 register (address 003116) the serial I/O2 counter is set to "7".

After writing, the SDATA pin outputs data every time the transfer clock shifts from a high to a low level. And, as the transfer clock shifts from a low to a high, the SDATA pin reads data, and at the same time the contents of the serial I/O2 register are shifted by 1 bit.

When the internal clock is selected as the transfer clock source, the following operations execute as the transfer clock counts up to 8.

- Serial I/O2 counter is cleared to "0".
- Transfer clock stops at an "H" level.
- Interrupt request bit is set.
- Shift completion flag is set.

Also, the SDATA pin is in a high impedance state after the data transfer is complete (refer to figure 31).

When the external clock is selected as the transfer clock source, the interrupt request bit is set as the transfer clock counts up to 8, but external control of the clock is required since it does not stop. Notice that the SDATA pin is not in a high impedance state on the completion of data transfer.

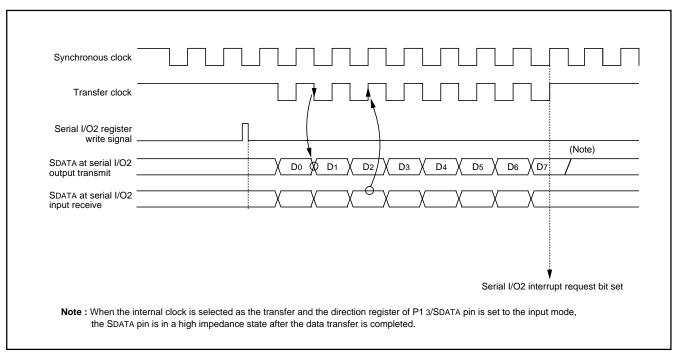


Fig. 31 Serial I/O2 timing (LSB first)

FUNCTIONAL DESCRIPTION

A-D Converter

The functional blocks of the A-D converter are described below.

[A-D conversion register] AD

The A-D conversion register is a read-only register that stores the result of A-D conversion. Do not read out this register during an A-D conversion.

[A-D control register] ADCON

The A-D control register controls the A-D converter. Bit 2 to 0 are analog input pin selection bits. Bit 4 is the AD conversion completion bit. The value of this bit remains at "0" during A-D conversion, and changes to "1" at completion of A-D conversion.

A-D conversion is started by setting this bit to "0".

[Comparison voltage generator]

The comparison voltage generator divides the voltage between Vss and VREF by 1024 by a resistor ladder, and outputs the divided voltages. Since the generator is disconnected from VREF pin and Vss pin, current is not flowing into the resistor ladder.

[Channel Selector]

The channel selector selects one of ports P27/AN7 to P20/AN0, and inputs the voltage to the comparator.

[Comparator and control circuit]

The comparator and control circuit compares an analog input voltage with the comparison voltage and stores its result into the A-D conversion register. When A-D conversion is completed, the control circuit sets the AD conversion completion bit and the AD interrupt request bit to "1". Because the comparator is constructed linked to a capacitor, set f(XIN) to 500 kHz or more during A-D conversion.

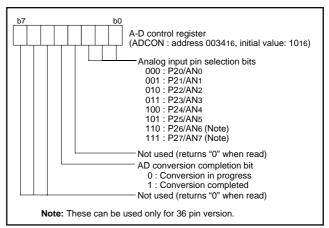


Fig. 32 Structure of A-D control register

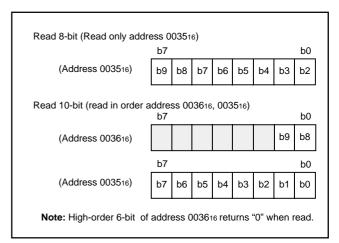


Fig. 33 Structure of A-D conversion register

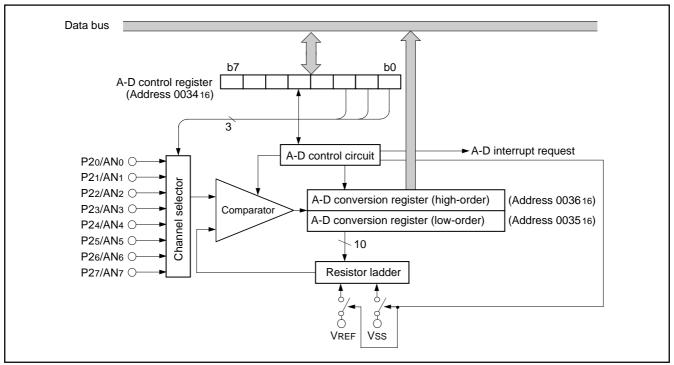


Fig. 34 Block diagram of A-D converter

Watchdog Timer

The watchdog timer gives a means for returning to a reset status when the program fails to run on its normal loop due to a runaway. The watchdog timer consists of an 8-bit watchdog timer H and an 8-bit watchdog timer L, being a 16-bit counter.

Standard operation of watchdog timer

The watchdog timer stops when the watchdog timer control register (address 003916) is not set after reset. Writing an optional value to the watchdog timer control register (address 003916) causes the watchdog timer to start to count down. When the watchdog timer H underflows, an internal reset occurs. Accordingly, it is programmed that the watchdog timer control register (address 003916) can be set before an underflow occurs.

When the watchdog timer control register (address 003916) is read, the values of the high-order 6-bit of the watchdog timer H, STP instruction disable bit and watchdog timer H count source selection bit are read.

Initial value of watchdog timer

By a reset or writing to the watchdog timer control register (address 0039₁₆), the watchdog timer H is set to "FF₁₆" and the watchdog timer L is set to "FF₁₆".

Operation of watchdog timer H count source selection bit

A watchdog timer H count source can be selected by bit 7 of the watchdog timer control register (address 003916). When this bit is "0", the count source becomes a watchdog timer L underflow signal. The detection time is 131.072 ms at f(XIN)=8 MHz.

When this bit is "1", the count source becomes $f(X_{IN})/16$. In this case, the detection time is 512 μ s at $f(X_{IN})=8$ MHz.

This bit is cleared to "0" after reset.

Operation of STP instruction disable bit

When the watchdog timer is in operation, the STP instruction can be disabled by bit 6 of the watchdog timer control register (address 0039₁₆).

When this bit is "0", the STP instruction is enabled.

When this bit is "1", the STP instruction is disabled, and an internal reset occurs if the STP instruction is executed.

Once this bit is set to "1", it cannot be changed to "0" by program. This bit is cleared to "0" after reset.

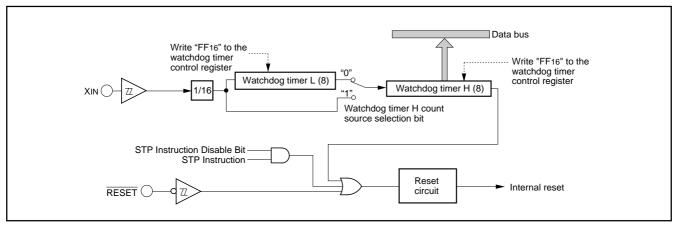


Fig. 35 Block diagram of watchdog timer

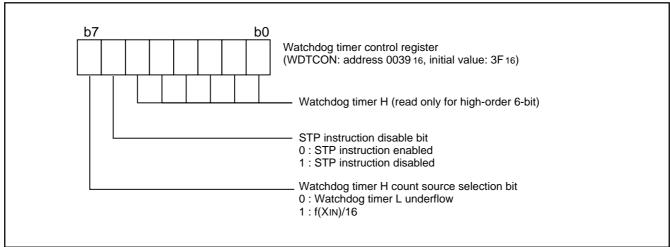


Fig. 36 Structure of watchdog timer control register

FUNCTIONAL DESCRIPTION

Reset Circuit

The microcomputer is put into a reset status by holding the $\overline{\text{RESET}}$ pin at the "L" level for the following interval or more according to the power source voltage and XIN is in stable oscillation.

After that, this reset status is released by returning the $\overline{\text{RESET}}$ pin to the "H" level. The program starts from the address having the contents of address FFFD16 as high-order address and the contents of address FFFC16 as low-order address.

When Vcc = 2.2 to 5.5 V, reset input "L" interval is 45 μ s or more When Vcc = 2.4 to 5.5 V, reset input "L" interval is 35 μ s or more When Vcc = 4.0 to 5.5 V, reset input "L" interval is 15 μ s or more

In the case of $f(\phi) \le 4$ MHz, the reset input voltage must be 0.8 V or less when the power source voltage passes 4.0 V.

In the case of $f(\phi) \le 2$ MHz, the reset input voltage must be 0.48 V or less when the power source voltage passes 2.4 V.

In the case of $f(\phi) \le 1$ MHz, the reset input voltage must be 0.44 V or less when the power source voltage passes 2.2 V.

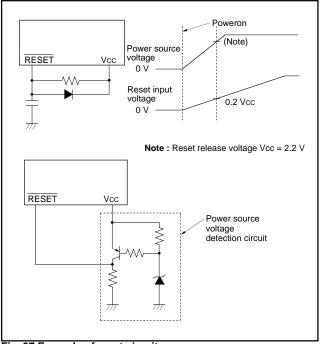


Fig. 37 Example of reset circuit

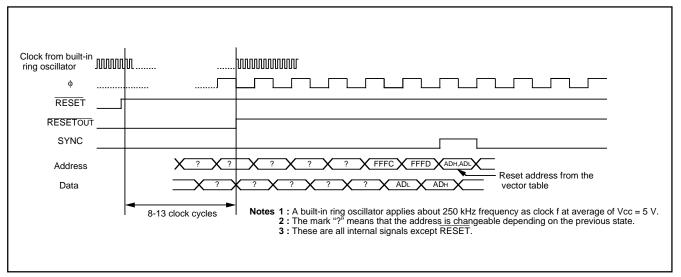


Fig. 38 Timing diagram at reset

	Address Register contents
(1) Port P0 direction register	000116 0016
(2) Port P1 direction register	000316 X X X 0 0 0 0
(3) Port P2 direction register	000516 0016
(4) Port P3 direction register	000716 0016
(5) Pull-up control register	001616 FF ₁₆
(6) Port P1P3 control register	001716 0016
(7) Serial I/O1 status register	001916 1 0 0 0 0 0 0
(8) Serial I/O1 control register	001A16 0216
(9) UART control register	001B ₁₆ 1 1 1 0 0 0 0
(10) Prescaler 12	002816 FF16
(11) Timer 1	002916 0116
(12) Timer 2	002A16 0016
(13) Timer X mode register	002B16 0016
(14) Prescaler X	002C16 FF16
(15) Timer X	002D16 FF16
(16) Timer count source set register	002E16 0016
(17) Serial I/O2 control register	003016 0016
(18) A-D control register	003416 1016
(19) MISRG	003816 0016
(20) Watchdog timer control register	003916 0 0 1 1 1 1 1
(21) Interrupt edge selection register	003A16 0016
(22) CPU mode register	003B ₁₆ 1 0 0 0 0 0 0
(23) Interrupt request register 1	003C16 0016
(24) Interrupt control register 1	003E16 0016
(25) Processor status register	(PS) X X X X X X 1 X
(26) Program counter	(PCH) Contents of address FFFD16
	(PCL) Contents of address FFFC16
	Note X : Undefined

Fig. 39 Internal status of microcomputer at reset

HARDWARE

FUNCTIONAL DESCRIPTION

Clock Generating Circuit

An oscillation circuit can be formed by connecting a resonator between XIN and XOUT, and an RC oscillation circuit can be formed by connecting a resistor and a capacitor.

Use the circuit constants in accordance with the resonator manufacturer's recommended values. No external resistor is needed between XIN and XOUT since a feed-back resistor exists on-chip.

Set the constants of the resistor and capacitor when an RC oscillator is used, so that a frequency variation due to LSI variation and resistor and capacitor variations may not exceed the standard input frequency.

Oscillation control

Stop mode

When the STP instruction is executed, the internal clock f stops at an "H" level and the XIN oscillator stops. At this time, timer 1 is set to "0116" and prescaler 12 is set to "FF16" when the oscillation stabilization time set bit after release of the STP instruction is "0". On the other hand, timer 1 and prescaler 12 are not set when the above bit is "1". Accordingly, set the wait time fit for the oscillation stabilization time of the oscillator to be used. f(XIN)/16 is forcibly connected to the input of prescaler 12. When an external interrupt is accepted, oscillation is restarted but the internal clock f remains at "H" until timer 1 underflows. As soon as timer 1 underflows, the internal clock f is supplied. This is because when a ceramic oscillator is used, some time is required until a start of oscillation. In case oscillation is restarted by reset, no wait time is generated. So apply an "L" level to the RESET pin while oscillation becomes stable.

• Wait mode

If the WIT instruction is executed, the internal clock f stops at an "H" level, but the oscillator does not stop. The internal clock restarts if a reset occurs or when an interrupt is received. Since the oscillator does not stop, normal operation can be started immediately after the clock is restarted. To ensure that interrupts will be received to release the STP or WIT state, interrupt enable bits must be set to "1" before the STP or WIT instruction is executed.

When the STP status is released, prescaler 12 and timer 1 will start counting clock which is XIN divided by 16, so set the timer 1 interrupt enable bit to "0" before the STP instruction is executed.

Note

For use with the oscillation stabilization set bit after release of the STP instruction set to "1", set values in timer 1 and prescaler 12 after fully appreciating the oscillation stabilization time of the oscillator to be used.

Switch of ceramic and RC oscillations

After releasing reset the operation starts by starting a built-in ring oscillator. Then, a ceramic oscillation or an RC oscillation is selected by setting bit 5 of the CPU mode register.

The bit 5 can be rewritten only once after releasing reset. However, after rewriting it is disable to write any value to the bit.

Double-speed mode

When a ceramic oscillation is selected, a double-speed mode can be used. Do not use it when an RC oscillation is selected.

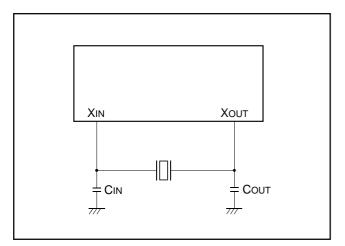


Fig. 40 External circuit of ceramic resonator

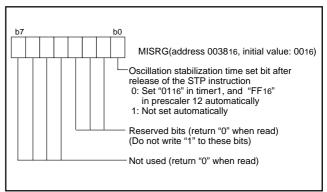


Fig. 43 Structure of MISRG

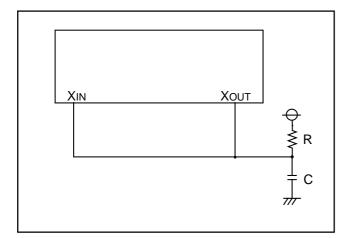


Fig. 41 External circuit of RC oscillation

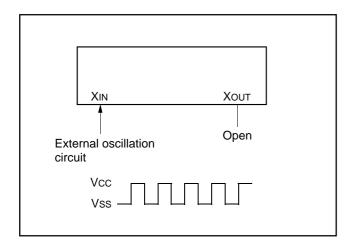


Fig. 42 External clock input circuit

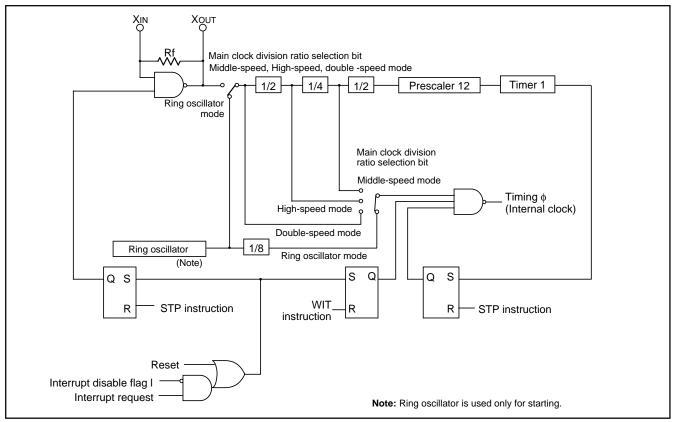


Fig. 44 Block diagram of internal clock generating circuit (for ceramic resonator)

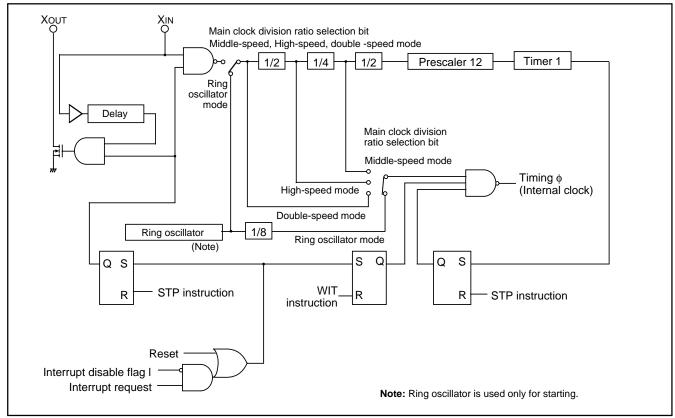


Fig. 45 Block diagram of internal clock generating circuit (for RC oscillation)

NOTES ON PROGRAMMING

Processor Status Register

The contents of the processor status register (PS) after reset are undefined except for the interrupt disable flag I which is "1". After reset, initialize flags which affect program execution. In particular, it is essential to initialize the T flag and the D flag because of their effect on calculations.

Interrupts

The contents of the interrupt request bit do not change even if the BBC or BBS instruction is executed immediately after they are changed by program because this instruction is executed for the previous contents. For executing the instruction for the changed contents, execute one instruction before executing the BBC or BBS instruction.

Decimal Calculations

- For calculations in decimal notation, set the decimal mode flag D to "1", then execute the ADC instruction or SBC instruction. In this case, execute SEC instruction, CLC instruction or CLD instruction after executing one instruction before the ADC instruction or SBC instruction
- In the decimal mode, the values of the N (negative), V (overflow) and Z (zero) flags are invalid.

Timers

- When n (0 to 255) is written to a timer latch, the frequency division ratio is 1/(n+1).
- When a count source of timer X is switched, stop a count of timer X.

Ports

• The values of the port direction registers cannot be read.

That is, it is impossible to use the LDA instruction, memory operation instruction when the T flag is "1", addressing mode using direction register values as qualifiers, and bit test instructions such as BBC and BBS.

It is also impossible to use bit operation instructions such as CLB and SEB and read/modify/write instructions of direction registers for calculations such as ROR.

For setting direction registers, use the LDM instruction, STA instruction, etc.

 Set "1" to each bit 6 of the port P3 direction register and the port P3 register.

A-D Converter

The comparator uses internal capacitors whose charge will be lost if the clock frequency is too low.

Make sure that f(XIN) is 500kHz or more during A-D conversion. Do not execute the STP instruction during A-D conversion.

Instruction Execution Timing

The instruction execution time can be obtained by multiplying the frequency of the internal clock ϕ by the number of cycles mentioned in the machine-language instruction table.

The frequency of the internal clock ϕ is the same as that of the XIN in double-speed mode, twice the XIN cycle in high-speed mode and 8 times the XIN cycle in middle-speed mode.

CPU Mode Register

The oscillation mode selection bit can be rewritten only once after releasing reset. However, after rewriting it is disable to write any value to the bit.

When a ceramic oscillation is selected, a double-speed mode of the clock division ratio selection bits can be used. Do not use it when an RC oscillation is selected.

NOTES ON USE

Handling of Power Source Pin

In order to avoid a latch-up occurrence, connect a capacitor suitable for high frequencies as bypass capacitor between power source pin (Vcc pin) and GND pin (Vss pin). Besides, connect the capacitor to as close as possible. For bypass capacitor which should not be located too far from the pins to be connected, a ceramic capacitor of 0.01 μF to 0.1 μF is recommended.

One Time PROM Version

The CNVss pin is connected to the internal memory circuit block by a low-ohmic resistance, since it has the multiplexed function to be a programmable power source pin (VPP pin) as well.

To improve the noise reduction, connect a track between CNVss pin and Vss pin with 1 to 10 $k\Omega$ resistance.

The mask ROM version track of CNVss pin has no operational interference even if it is connected via a resistor.

DATA REQUIRED FOR MASK ORDERS

The following are necessary when ordering a mask ROM production:

- (1) Mask ROM Order Confirmation Form
- (2) Mark Specification Form
- (3) Data to be written to ROM, in EPROM form (three identical copies)

DATA REQUIRED FOR ROM PROGRAMMING ORDERS

The following are necessary when ordering a ROM writing:

- (1) ROM Programming Confirmation Form
- (2) Mark Specification Form (for Special Mark)
- (3) Data to be written to ROM, in EPROM form (three identical copies)

ROM PROGRAMMING METHOD

The built-in PROM of the blank One Time PROM version can be read or programmed with a general-purpose PROM programmer using a special programming adapter. Set the address of PROM programmer in the user ROM area.

Table 7 Special programming adapter

Package	Name of Programming Adapter
32P4B	PCA7435SP
32P6B-A	PCA7435GP
36P2R-A	PCA7435FP

The PROM of the blank One Time PROM version is not tested or screened in the assembly process and following processes. To ensure proper operation after programming, the procedure shown in Figure 46 is recommended to verify programming.

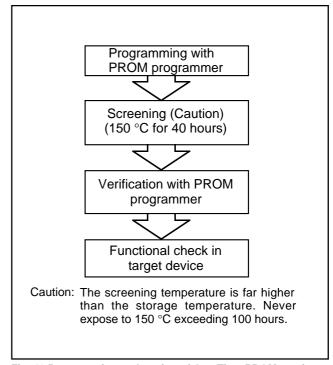


Fig. 46 Programming and testing of One Time PROM version

FUNCTIONAL DESCRIPTION SUPPLEMENT

Interrupt

7531 group permits interrupts on the basis of 12 (11 sources for 32-pin version) sources. It is vector interrupts with a fixed priority system. Accordingly,

when two or more interrupt requests occur during the same sampling, the higher-priority interrupt is accepted first. This priority is determined by hardware, but variety of priority processing can be performed by software, using an interrupt enable bit and an interrupt disable flag.

For interrupt sources, vector addresses and interrupt priority, refer to "Table 8."

Table 8 Interrupt sources, vector addresses and interrupt priority

Driority	lataumunt aasumaa	Vector addresses		Demonto	
Priority	Interrupt sources	High-order	Low-order	Remarks	
1	Reset (Note 1)	FFFD16	FFFC16	Non-maskable	
2	Serial I/O1 receive interrupt	FFFB16	FFFA16	Valid when serial I/O1 is selected	
3	Serial I/O1 transmit interrupt	FFF916	FFF816	Valid when serial I/O1 is selected	
	INT1 interrupt (Note 2)		 -	External interrupt	
			I I	(active edge selectable)	
4	INTo interrupt	FFF716	FFF616	External interrupt	
			 	(active edge selectable)	
5	Timer X interrupt	FFF516	FFF416		
	Key on wake up interrupt			External interrupt (only at falling edge)	
6	Timer 1 interrupt	FFF316	FFF216	STP instruction release timer underflow	
7	Timer 2 interrupt	FFF116	FFF016		
	Serial I/O2 interrupt		 		
8	CNTRo interrupt	FFEF16	FFEE16	External interrupt	
			 	(active edge selectable)	
	A-D conversion interrupt	-[
9	BRK instruction interrupt	FFED16	FFEC16	Non-maskable software interrupt	

Notes 1: Reset functions in the same way as an interrupt with the highest priority.

^{2:} It is available for 36-pin version.

FUNCTIONAL DESCRIPTION SUPPLEMENT

Timing After Interrupt

The interrupt processing routine begins with the machine cycle following the completion of the

instruction that is currently in execution. Figure 47 shows a timing chart after an interrupt occurs, and Figure 48 shows the time up to execution of the interrupt processing routine.

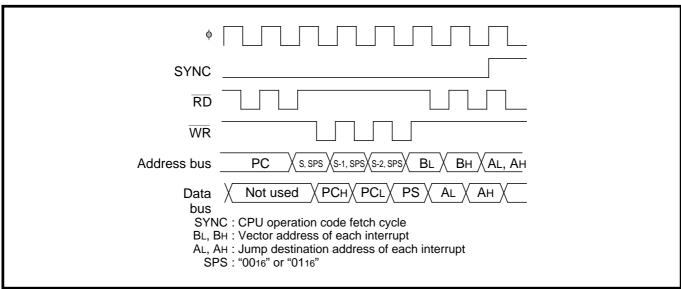


Fig. 47 Timing chart after an interrupt occurs

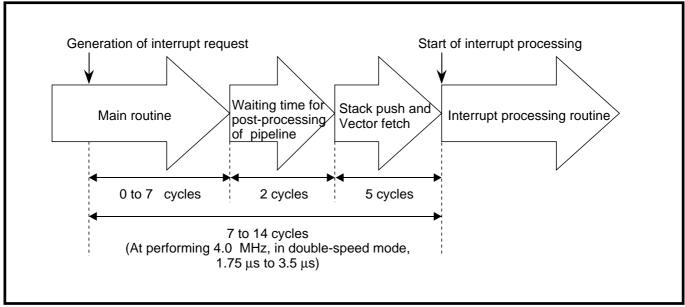


Fig. 48 Time up to execution of the interrupt processing routine

FUNCTIONAL DESCRIPTION SUPPLEMENT

A-D Converter

A-D conversion is started by setting AD conversion completion bit to "0." During A-D conversion, internal operations are performed as follows.

- 1. After the start of A-D conversion, A-D conversion register goes to "0016."
- 2. The highest-order bit of A-D conversion register is set to "1," and the comparison voltage Vref is input to the comparator. Then, Vref is compared with analog input voltage VIN.
- As a result of comparison, when Vref < VIN, the highest-order bit of A-D conversion register becomes "1." When Vref > VIN, the highest-order bit becomes "0."

By repeating the above operations up to the lowestorder bit of the A-D conversion register, an analog value converts into a digital value.

A-D conversion completes at 122 clock cycles (15.25 μs at f(XIN) = 8.0 MHz) after it is started, and the result of the conversion is stored into the A-D conversion register.

Concurrently with the completion of A-D conversion, A-D conversion interrupt request occurs, so that the AD conversion interrupt request bit is set to "1."

Relative formula for a reference voltage VREF of A-D converter and Vref

When
$$n = 0$$
 $Vref = 0$

When n = 1 to 1023 Vref =
$$\frac{\text{VREF}}{1024}$$
 X n

n: the value of A-D converter (decimal numeral)

Table 9 Change of A-D conversion register during A-D conversion

talore e erranige er re	conversion register during // 2 conversion				
	Change of A-D conversion register	Value of comparison voltage (Vref)			
At start of conversion	0 0 0 0 0 0 0 0 0 0	0			
First comparison	1 0 0 0 0 0 0 0 0 0	VREF 2			
Second comparison	* 1 1 0 0 0 0 0 0 0 0	$\frac{VREF}{2} \pm \frac{VREF}{4}$			
Third comparison	*1*2 1 0 0 0 0 0 0 0	$\frac{VREF}{2} \pm \frac{VREF}{4} \pm \frac{VREF}{8}$			
:	:	:			
After completion of tenth comparison	A result of A-D conversion * 1 * 2 * 3 * 4 * 5 * 6 * 7 * 8 * 9 * 10	$\frac{VREF}{2} \pm \frac{VREF}{4} \pm \bullet \bullet \bullet \pm \frac{VREF}{1024}$			

*1-*10: A result of the first to tenth comparison

HARDWARE

FUNCTIONAL DESCRIPTION SUPPLEMENT

Figure 49 shows A-D conversion equivalent circuit, and Figure 50 shows A-D conversion timing chart.

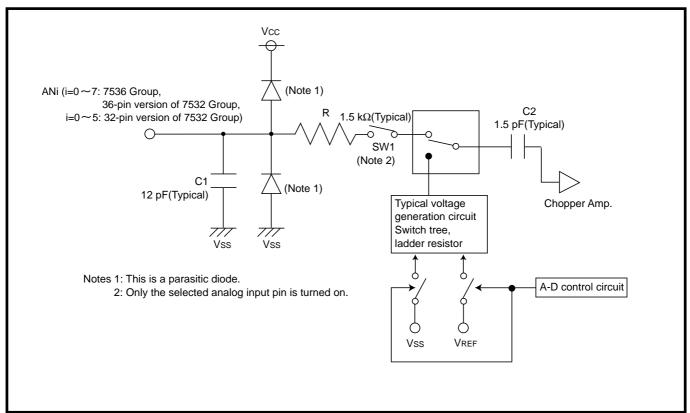


Fig. 49 A-D conversion equivalent circuit

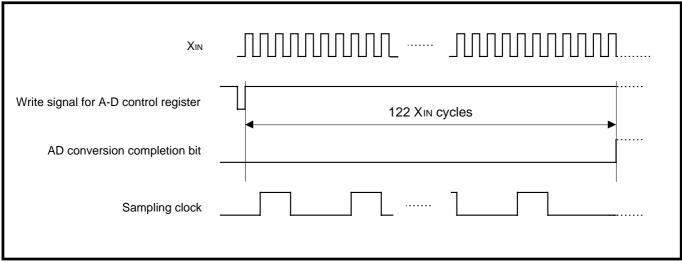


Fig. 50 A-D conversion timing chart

CHAPTER 2 APPLICATION

- 2.1 I/O port
- 2.2 Timer
- 2.3 Serial I/O
- 2.4 A-D converter
- 2.5 Reset

2.1 I/O port

2.1 I/O port

This paragraph explains the registers setting method and the notes relevant to the I/O ports.

2.1.1 Memory map

000016	Port P0 (P0)
000116	Port P0 direction register (P0D)
000216	Port P1 (P1)
000316	Port P1 direction register (P1D)
000416	Port P2 (P2)
000516	Port P2 direction register (P2D)
000616	Port P3 (P3)
000716	Port P3 direction register (P3D)
	¥

Fig. 2.1.1 Memory map of registers relevant to I/O port

2.1.2 Relevant registers

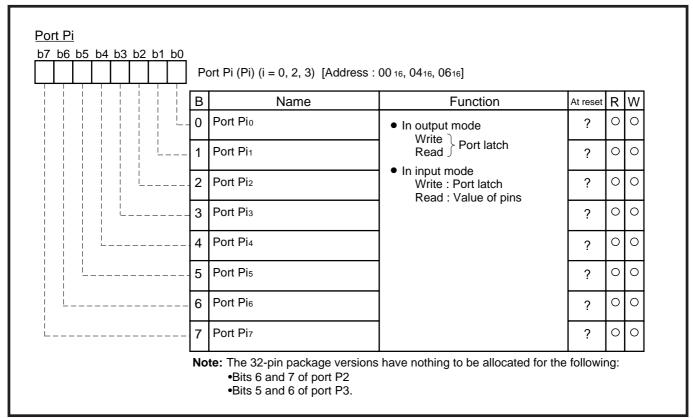


Fig. 2.1.2 Structure of Port Pi (i = 0, 2, 3)

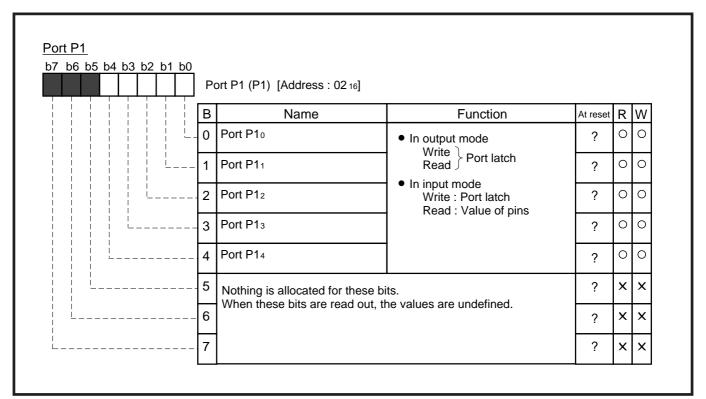


Fig. 2.1.3 Structure of Port P1

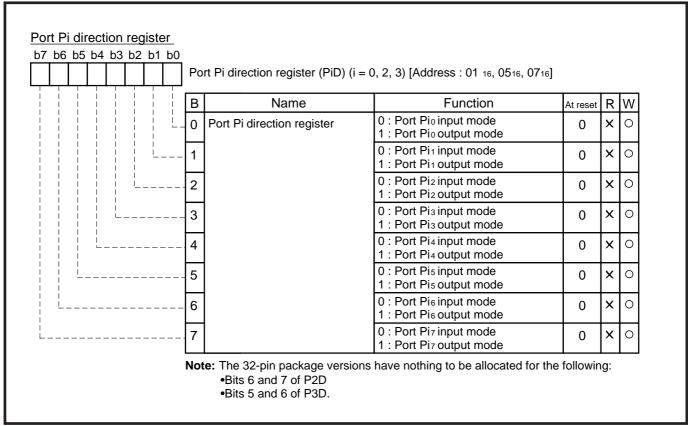


Fig. 2.1.4 Structure of Port Pi direction register (i = 0, 2, 3)

2.1 I/O port

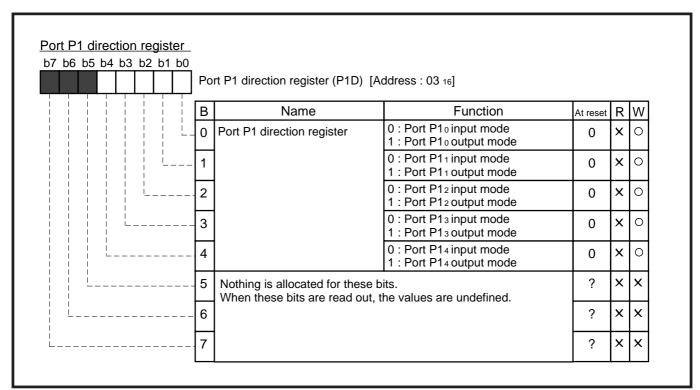


Fig. 2.1.5 Structure of Port P1 direction register

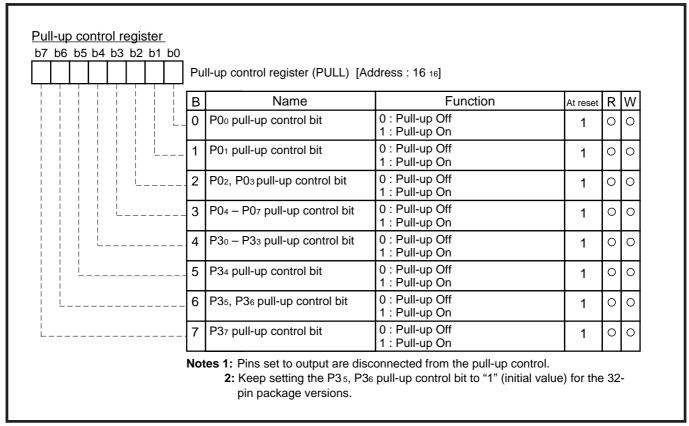


Fig. 2.1.6 Structure of Pull-up control register

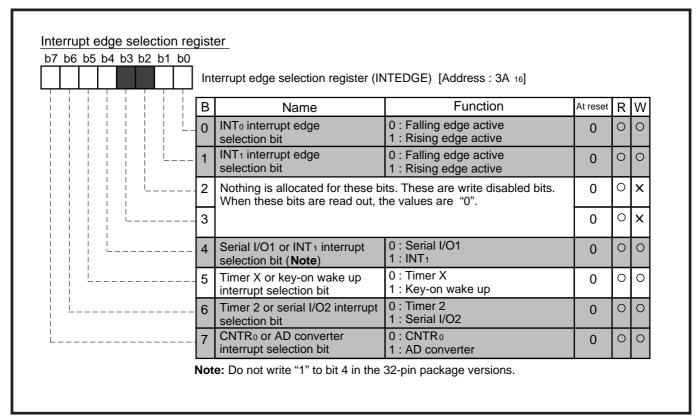


Fig. 2.1.7 Structure of Interrupt edge selection register

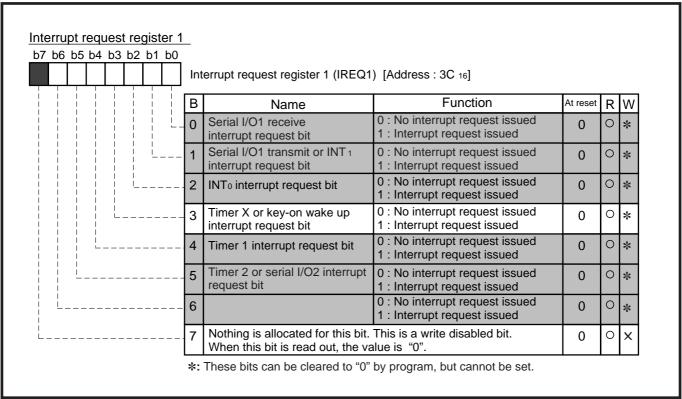


Fig. 2.1.8 Structure of Interrupt request register 1

2.1 I/O port

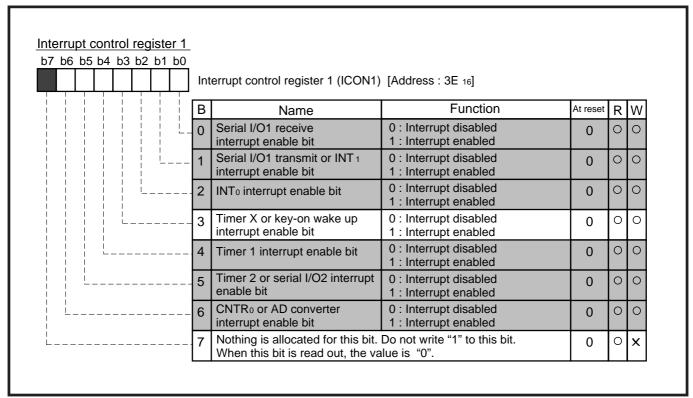


Fig. 2.1.9 Structure of Interrupt control register 1

2.1.3 Application example of key-on wake up

Outline: The built-in pull-up resistor is used.

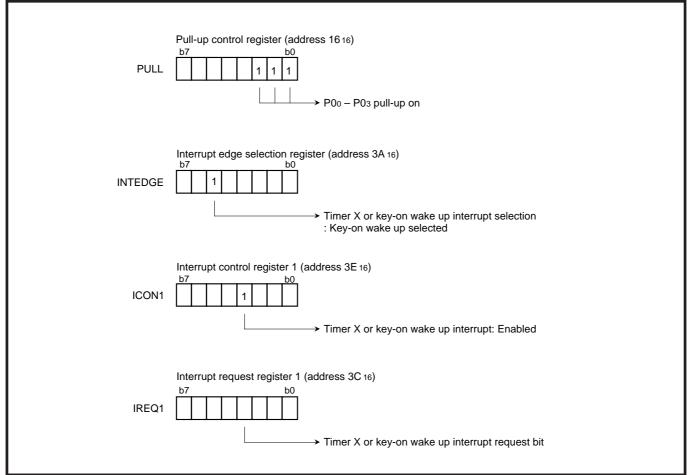


Fig. 2.1.10 Relevant registers setting

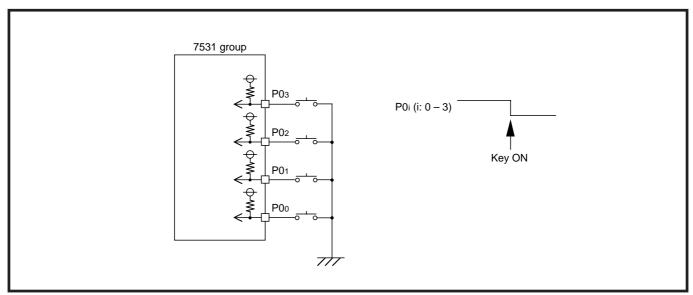


Fig. 2.1.11 Application circuit example

2.1 I/O port

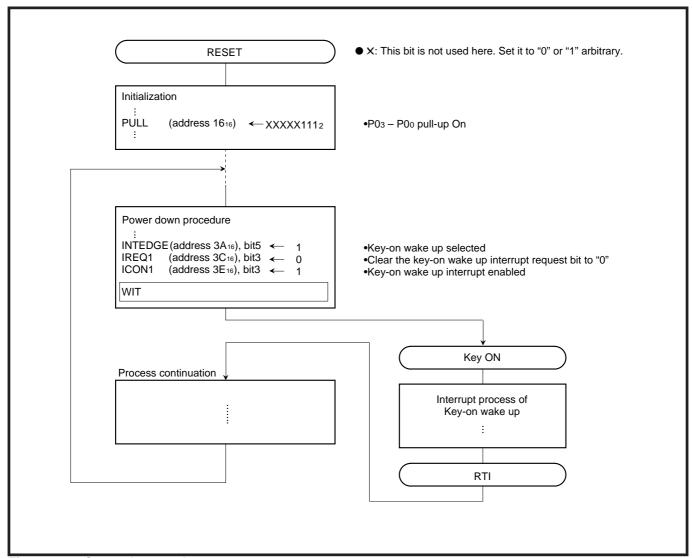


Fig. 2.1.12 Control procedure

2.1.4 Handling of unused pins

Table 2.1.1 Handling of unused pins

Pins/Ports name	Handling
P0, P1, P2, P3	•Set to the input mode and connect each to Vcc or Vss through a resistor of 1 k Ω to
	10 kΩ.
	•Set to the output mode and open at "L" or "H" level.
V _{REF}	•Connect to Vss (GND).
Хоит	•Open, only when using an external clock

2.1.5 Notes on input and output pins

(1) Notes in stand-by state

In stand-by state*1 for low-power dissipation, do not make input levels of an input port and an I/O port "undefined".

Pull-up (connect the port to VCC) or pull-down (connect the port to VSS) these ports through a resistor.

When determining a resistance value, note the following points:

- External circuit
- Variation of output levels during the ordinary operation

When using a built-in pull-up or pull-down resistor, note on varied current values:

- When setting as an input port : Fix its input level
- When setting as an output port : Prevent current from flowing out to external.

Reason

The output transistor becomes the OFF state, which causes the ports to be the high-impedance state. Note that the level becomes "undefined" depending on external circuits.

Accordingly, the potential which is input to the input buffer in a microcomputer is unstable in the state that input levels of a input port and an I/O port are "undefined". This may cause power source current.

*1 stand-by state : the stop mode by executing the **STP** instruction the wait mode by executing the **WIT** instruction

(2) Modifying output data with bit managing instruction

When the port latch of an I/O port is modified with the bit managing instruction*2, the value of the unspecified bit may be changed.

Reason

The bit managing instructions are read-modify-write form instructions for reading and writing data by a byte unit. Accordingly, when these instructions are executed on a bit of the port latch of an I/O port, the following is executed to all bits of the port latch.

- As for a bit which is set for an input port :
 - The pin state is read in the CPU, and is written to this bit after bit managing.
- As for a bit which is set for an output port :

The bit value of the port latch is read in the CPU, and is written to this bit after bit managing.

Note the following:

- Even when a port which is set as an output port is changed for an input port, its port latch holds the output data.
- As for a bit of the port latch which is set for an input port, its value may be changed even when
 not specified with a bit managing instruction in case where the pin state differs from its port latch
 contents.

^{*2} bit managing instructions : SEB, and CLB instructions

2.1 I/O port

2.1.6 Termination of unused pins

(1) Terminate unused pins

① Output ports : Open

2 Input ports:

Connect each pin to VCC or Vss through each resistor of 1 k Ω to 10 k Ω .

Ports that permit the selecting of a built-in pull-up or pull-down resistor can also use this resistor. As for pins whose potential affects to operation modes such as pins CNVss, INT or others, select the Vcc pin or the Vss pin according to their operation mode.

3 I/O ports:

• Set the I/O ports for the input mode and connect them to Vcc or Vss through each resistor of 1 k Ω to 10 k Ω .

Ports that permit the selecting of a built-in pull-up or pull-down resistor can also use this resistor. Set the I/O ports for the output mode and open them at "L" or "H".

- When opening them in the output mode, the input mode of the initial status remains until the
 mode of the ports is switched over to the output mode by the program after reset. Thus, the
 potential at these pins is undefined and the power source current may increase in the input
 mode. With regard to an effects on the system, thoroughly perform system evaluation on the user
 side.
- Since the direction register setup may be changed because of a program runaway or noise, set direction registers by program periodically to increase the reliability of program.

(2) Termination remarks

① Input ports and I/O ports:

Do not open in the input mode.

Reason

- The power source current may increase depending on the first-stage circuit.
- An effect due to noise may be easily produced as compared with proper termination ② and
 ③ shown on the above.

2 I/O ports:

When setting for the input mode, do not connect to VCC or VSS directly.

Reason

If the direction register setup changes for the output mode because of a program runaway or noise, a short circuit may occur between a port and Vcc (or Vss).

3 I/O ports:

When setting for the input mode, do not connect multiple ports in a lump to VCC or Vss through a resistor.

Reason

If the direction register setup changes for the output mode because of a program runaway or noise, a short circuit may occur between ports.

• At the termination of unused pins, perform wiring at the shortest possible distance (20 mm or less) from microcomputer pins.

2.2 Timer

This paragraph explains the registers setting method and the notes relevant to the timers.

2.2.1 Memory map

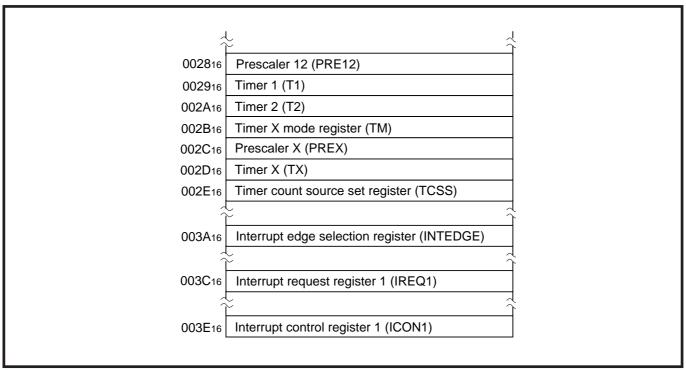


Fig. 2.2.1 Memory map of registers relevant to timers

2.2.2 Relevant registers

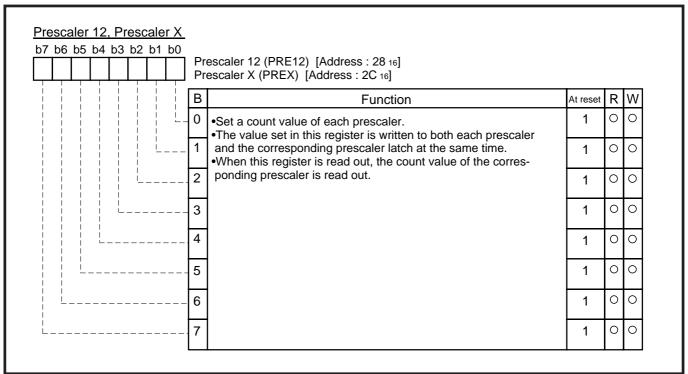


Fig. 2.2.2 Structure of Prescaler 12, Prescaler X

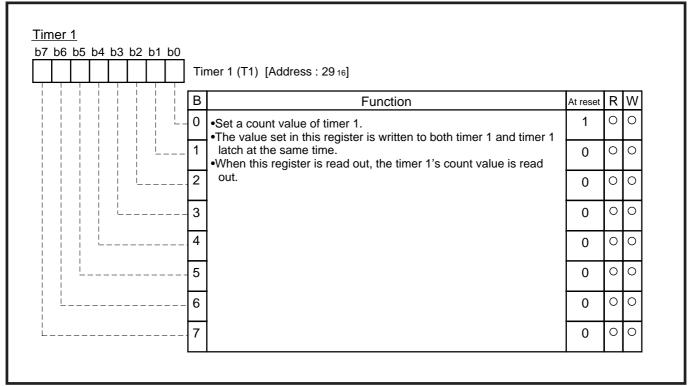


Fig. 2.2.3 Structure of Timer 1

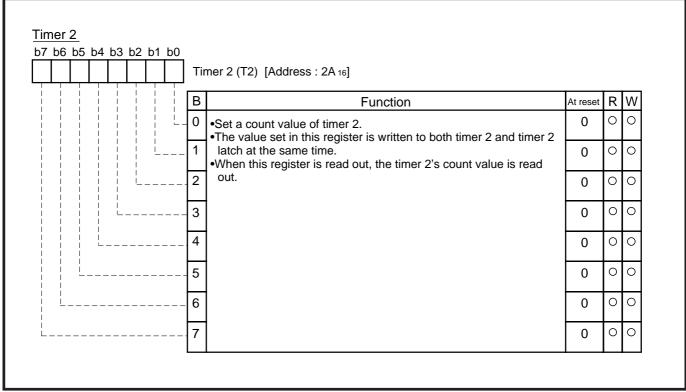


Fig. 2.2.4 Structure of Timer 2

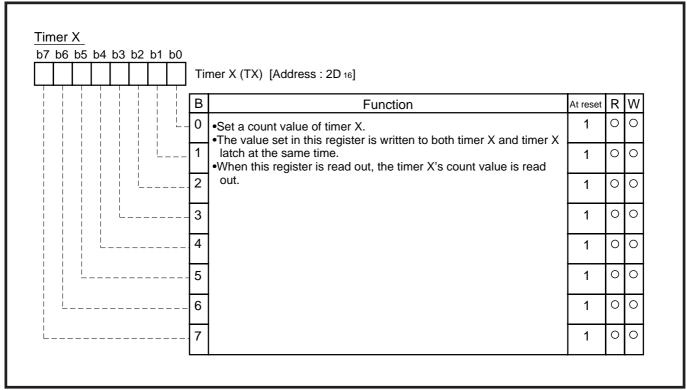


Fig. 2.2.5 Structure of Timer X

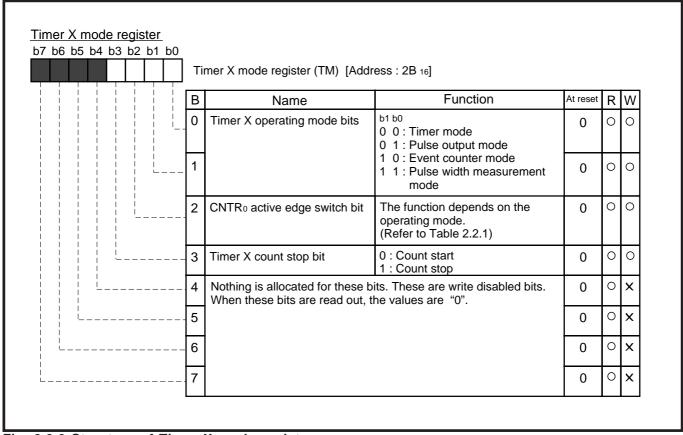


Fig. 2.2.6 Structure of Timer X mode register

Table 2.2.1 CNTRo active edge switch bit function

ontents
ner count
ner count

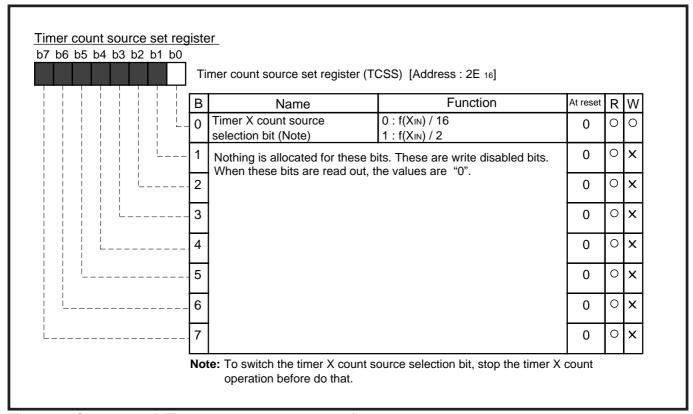


Fig. 2.2.7 Structure of Timer count source set register

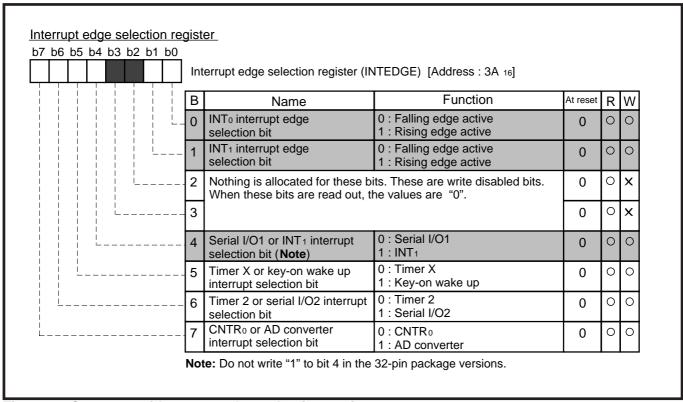


Fig. 2.2.8 Structure of Interrupt edge selection register

b7 b6 b5 b4 b3 b2 b1 b0	Int	errupt request register 1 (IREQ1) [Address : 3C 16]			
	В	Name	Function	At reset	R	W
	0	Serial I/O1 receive interrupt request bit	0 : No interrupt request issued 1 : Interrupt request issued	0	0	*
	1	Serial I/O1 transmit or INT 1 interrupt request bit	0 : No interrupt request issued 1 : Interrupt request issued	0	0	*
	2	INT₀ interrupt request bit	0 : No interrupt request issued 1 : Interrupt request issued	0	0	*
	3	Timer X or key-on wake up interrupt request bit	0 : No interrupt request issued 1 : Interrupt request issued	0	0	*
	4	Timer 1 interrupt request bit	0 : No interrupt request issued 1 : Interrupt request issued	0	0	*
	5	Timer 2 or serial I/O2 interrupt request bit	0 : No interrupt request issued 1 : Interrupt request issued	0	0	*
	6	CNTR₀ or AD converter interrupt request bit	0 : No interrupt request issued 1 : Interrupt request issued	0	0	*
L	7	Nothing is allocated for this bit. When this bit is read out, the va		0	0	×

Fig. 2.2.9 Structure of Interrupt request register 1

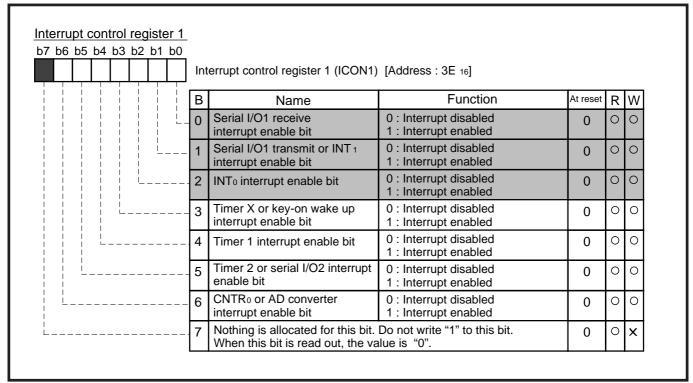


Fig. 2.2.10 Structure of Interrupt control register 1

2.2.3 Timer application examples

(1) Basic functions and uses

[Function 1] Control of Event interval (Timer X, Timer 1, Timer 2)

When a certain time, by setting a count value to each timer, has passed, the timer interrupt request occurs.

<Use>

- •Generation of an output signal timing
- •Generation of a wait time

[Function 2] Control of Cyclic operation (Timer X, Timer 1, Timer 2)

The value of the timer latch is automatically written to the corresponding timer each time the timer underflows, and each timer interrupt request occurs in cycles.

<Use>

- Generation of cyclic interrupts
- •Clock function (measurement of 250 ms); see Application example 1
- •Control of a main routine cycle

[Function 3] Output of Rectangular waveform (Timer X)

The output level of the CNTR₀ pin is inverted each time the timer underflows (in the pulse output mode).

<Use>

- •Piezoelectric buzzer output; see Application example 2
- •Generation of the remote-control carrier waveforms

[Function 4] Count of External pulses (Timer X)

External pulses input to the CNTR₀ pin are counted as the timer count source (in the event counter mode).

<Use>

- •Frequency measurement; see Application example 3
- Division of external pulses
- •Generation of interrupts due to a cycle using external pulses as the count source; count of a reel pulse

[Function 5] Measurement of External pulse width (Timer X)

The "H" or "L" level width of external pulses input to CNTR₀ pin is measured (in the pulse width measurement mode).

<Use>

- Measurement of external pulse frequency (measurement of pulse width of FG pulse* for a motor); see Application example 4
- •Measurement of external pulse duty (when the frequency is fixed)

FG pulse*: Pulse used for detecting the motor speed to control the motor speed.

2.2 Timer

(2) Timer application example 1: Clock function (measurement of 250 ms)

Outline: The input clock is divided by the timer so that the clock can count up at 250 ms intervals. **Specifications**: •The clock $f(X_{IN}) = 4.19$ MHz (2^{22} Hz) is divided by the timer.

•The clock is counted up in the process routine of the timer X interrupt which occurs at 250 ms intervals.

Figure 2.2.11 shows the timers connection and setting of division ratios; Figure 2.2.12 shows the relevant registers setting; Figure 2.2.13 shows the control procedure.

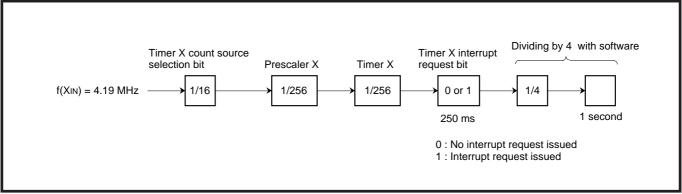


Fig. 2.2.11 Timers connection and setting of division ratios

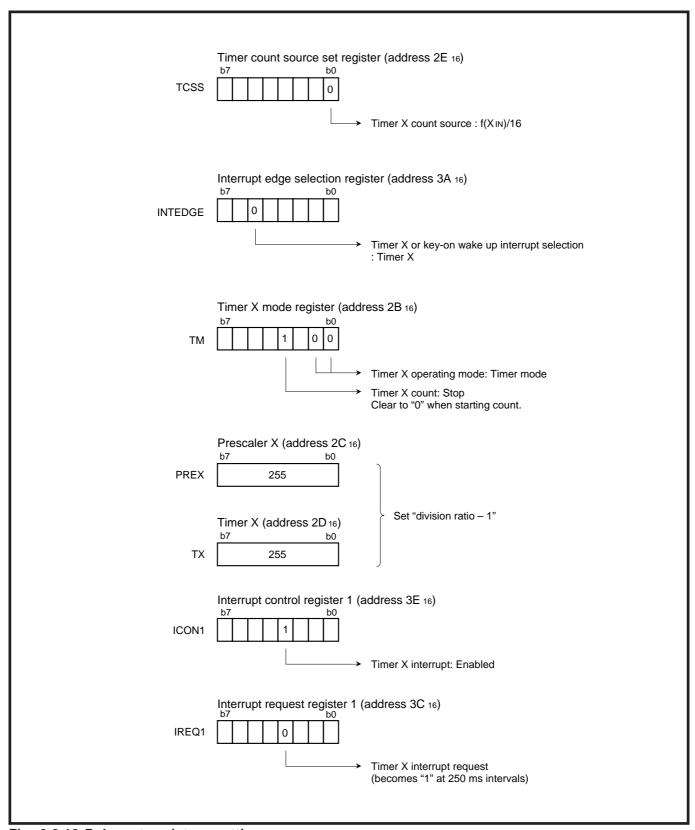


Fig. 2.2.12 Relevant registers setting

2.2 Timer

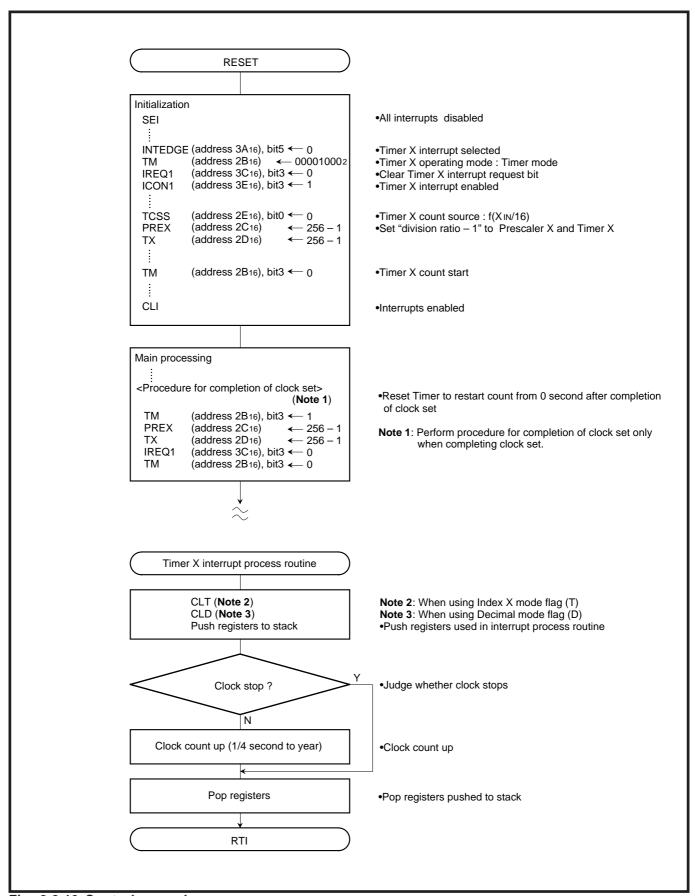


Fig. 2.2.13 Control procedure

(3) Timer application example 2: Piezoelectric buzzer output

Outline: The rectangular waveform output function of the timer is applied for a piezoelectric buzzer output.

- **Specifications**: •The rectangular waveform, dividing the clock $f(X_{IN}) = 4.19$ MHz (2^{22} Hz) into about 2 kHz (2048 Hz), is output from the P1₄/CNTR₀ pin.
 - •The level of the P1₄/CNTR₀ pin is fixed to "H" while a piezoelectric buzzer output stops.

Figure 2.2.14 shows a peripheral circuit example, and Figure 2.2.15 shows the timers connection and setting of division ratios. Figures 2.2.16 shows the relevant registers setting, and Figure 2.2.17 shows the control procedure.

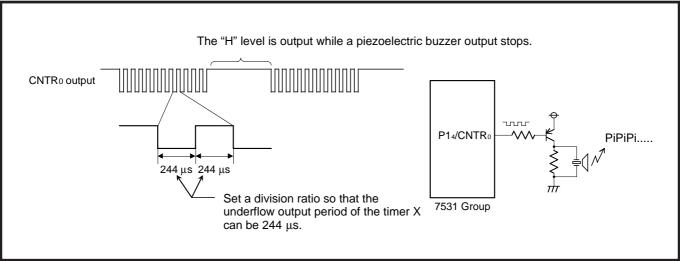


Fig. 2.2.14 Peripheral circuit example

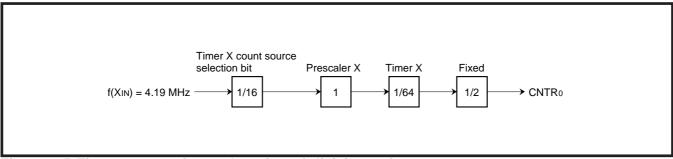


Fig. 2.2.15 Timers connection and setting of division ratios

2.2 Timer

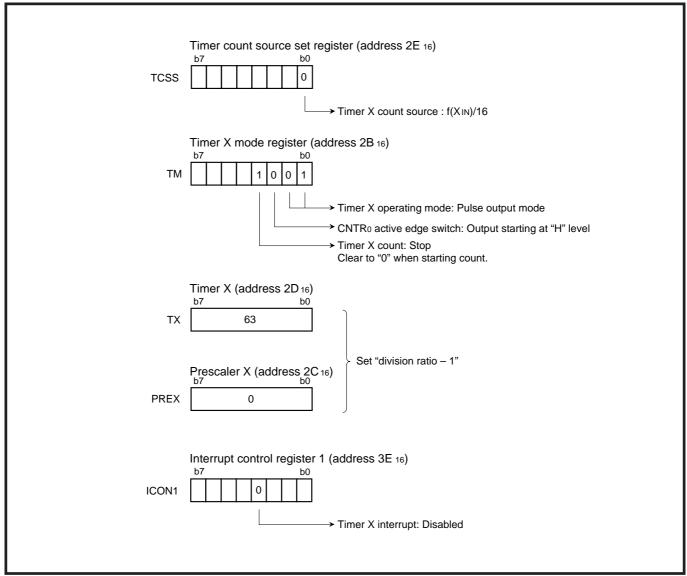


Fig. 2.2.16 Relevant registers setting

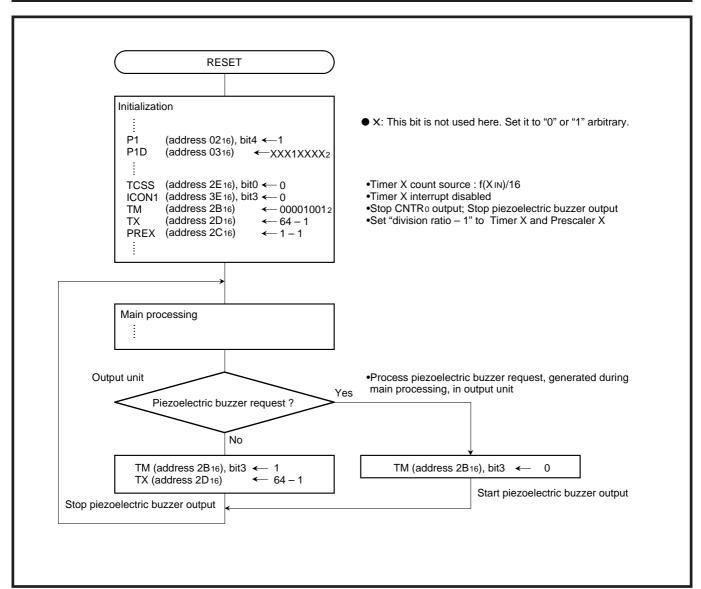


Fig. 2.2.17 Control procedure

2.2 Timer

(4) Timer application example 3: Frequency measurement

Outline: The following two values are compared to judge whether the frequency is within a valid range.

- •A value by counting pulses input to P14/CNTR0 pin with the timer.
- •A reference value

Specifications: •The pulse is input to the P14/CNTR0 pin and counted by the timer X.

- •A count value is read out at about 2 ms intervals, the timer 1 interrupt interval. When the count value is 28 to 40, it is judged that the input pulse is valid.
- •Because the timer is a down-counter, the count value is compared with 227 to 215 (Note).

Note: 227 to $215 = \{255 \text{ (initial value of counter)} - 28\}$ to $\{255 - 40\}$; 28 to 40 means the number of valid value.

Figure 2.2.18 shows the judgment method of valid/invalid of input pulses; Figure 2.2.19 shows the relevant registers setting; Figure 2.2.20 shows the control procedure.

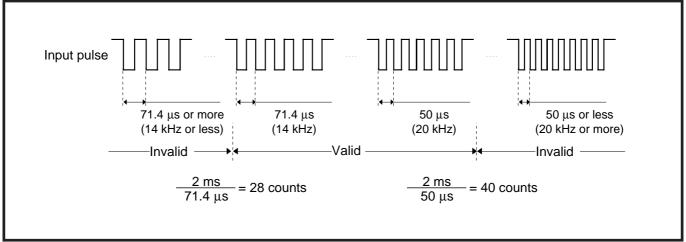


Fig 2.2.18 Judgment method of valid/invalid of input pulses

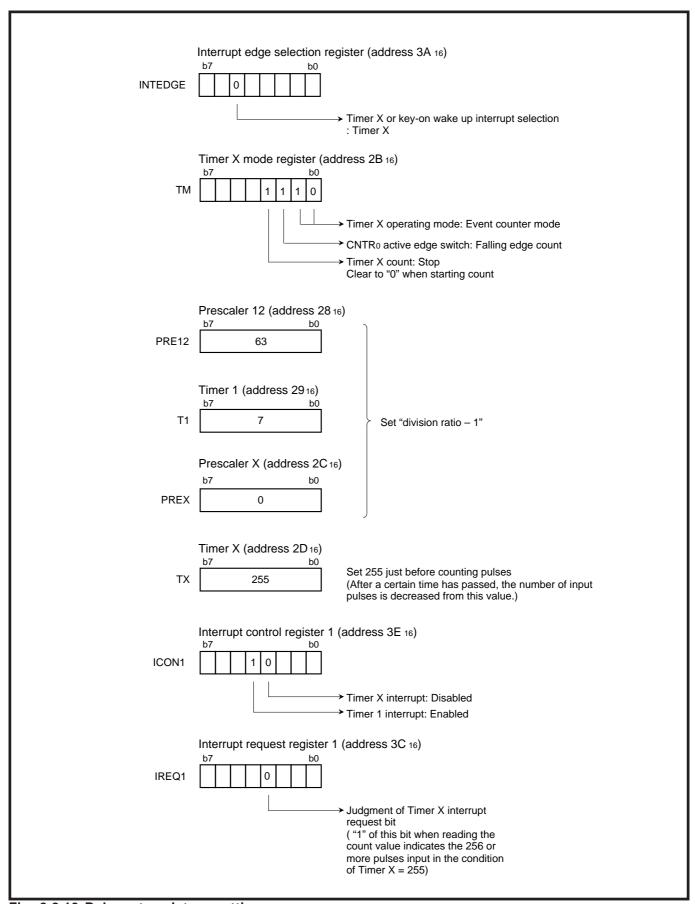


Fig. 2.2.19 Relevant registers setting

2.2 Timer

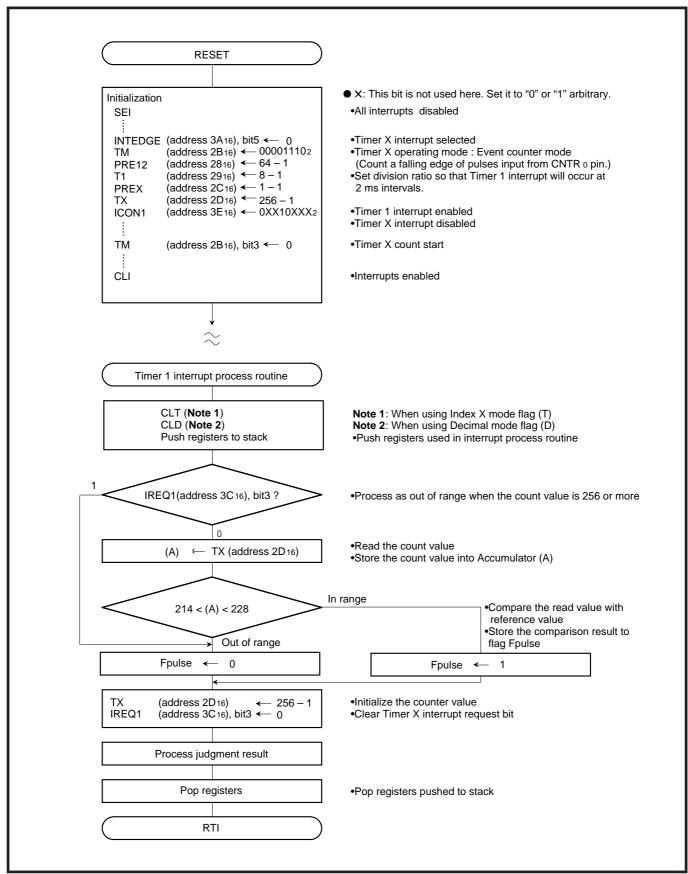


Fig. 2.2.20 Control procedure

(5) Timer application example 4: Measurement of FG pulse width for motor

Outline: The timer X counts the "H" level width of the pulses input to the P14/CNTR0 pin. An underflow is detected by the timer X interrupt and an end of the input pulse "H" level is detected by the CNTR0 interrupt.

Specifications: •The timer X counts the "H" level width of the FG pulse input to the P14/CNTR0 pin.

<Example>

When the clock frequency is 4.19 MHz, the count source is 3.8 μ s, which is obtained by dividing the clock frequency by 16. Measurement can be made up to 250 ms in the range of FFFF₁₆ to 0000_{16} .

Figure 2.2.21 shows the timers connection and setting of division ratio; Figure 2.2.22 shows the relevant registers setting; Figure 2.2.23 shows the control procedure.

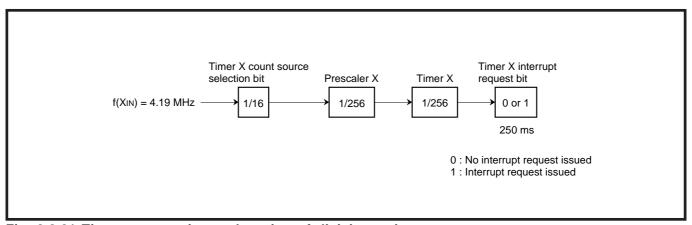


Fig. 2.2.21 Timers connection and setting of division ratios

2.2 Timer

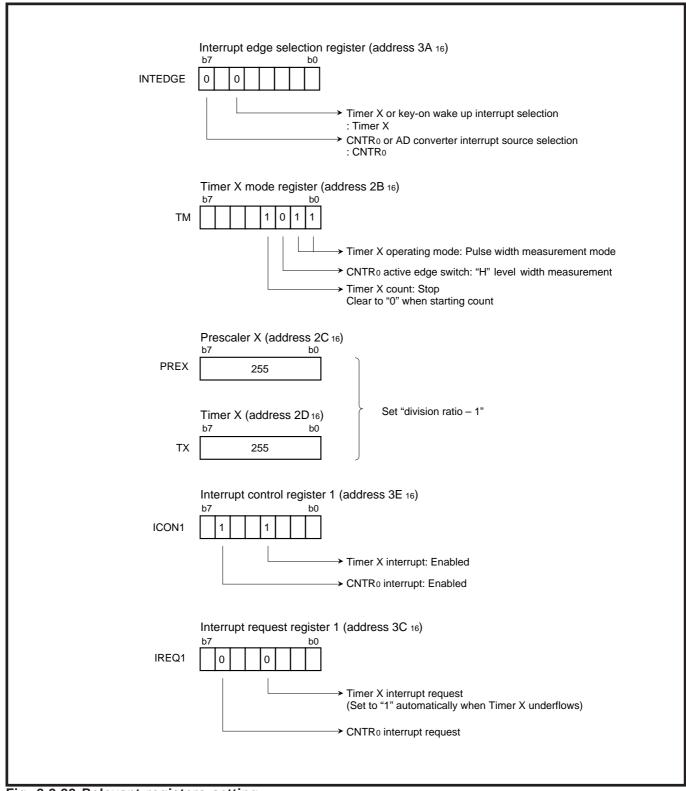


Fig. 2.2.22 Relevant registers setting

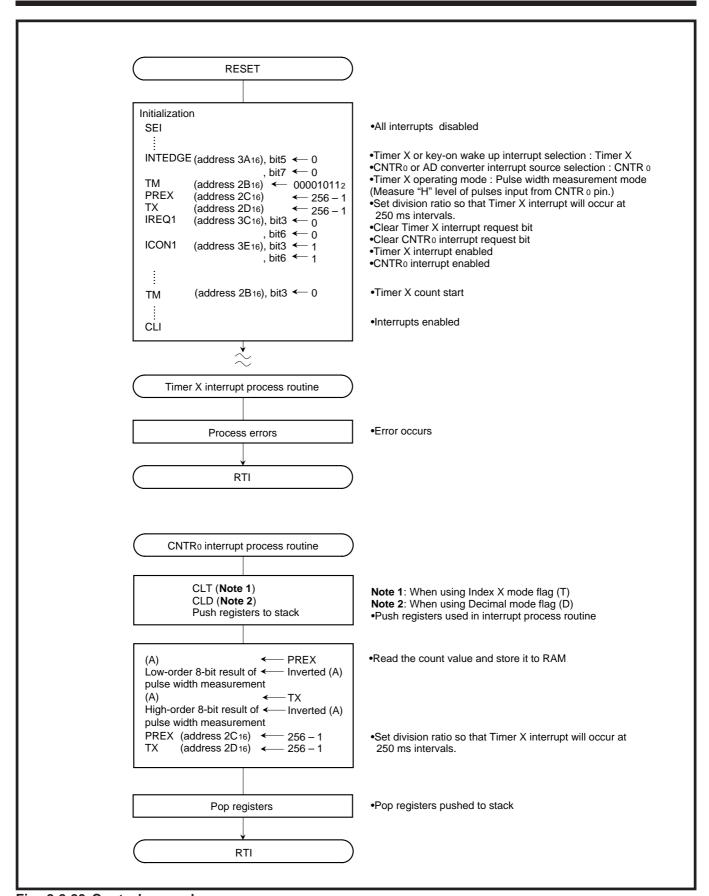


Fig. 2.2.23 Control procedure

2.3 Serial I/O

2.3 Serial I/O

This paragraph explains the registers setting method and the notes relevant to the serial I/O.

2.3.1 Memory map

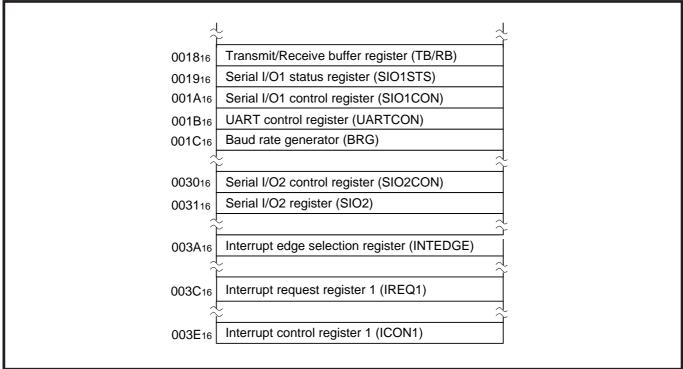


Fig. 2.3.1 Memory map of registers relevant to serial I/O

2.3.2 Relevant registers

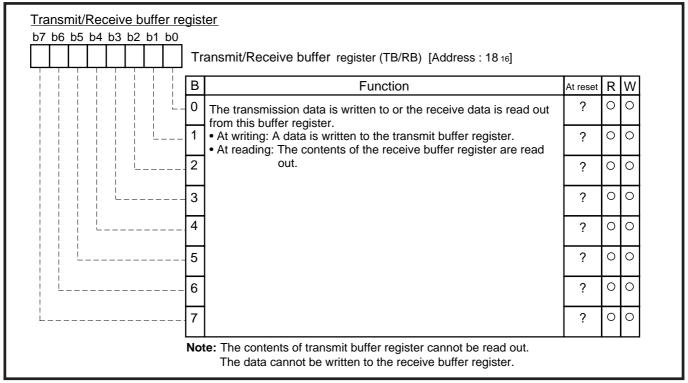


Fig. 2.3.2 Structure of Transmit/Receive buffer register

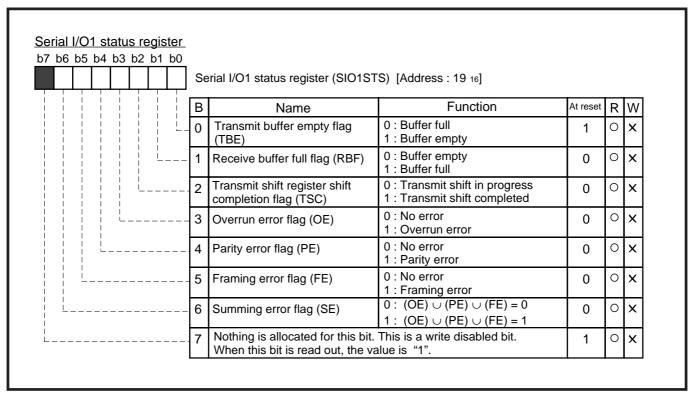


Fig. 2.3.3 Structure of Serial I/O1 status register

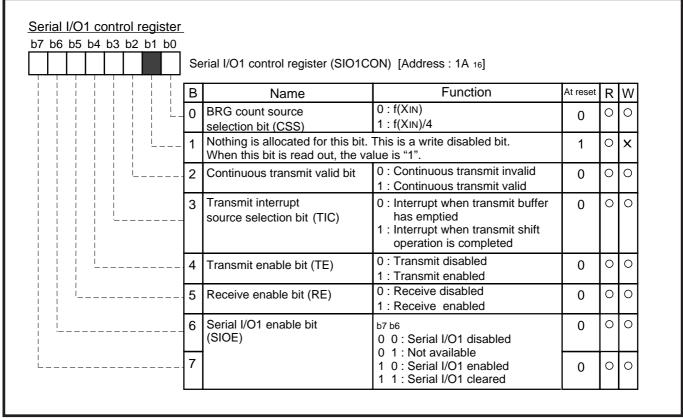


Fig. 2.3.4 Structure of Serial I/O1 control register

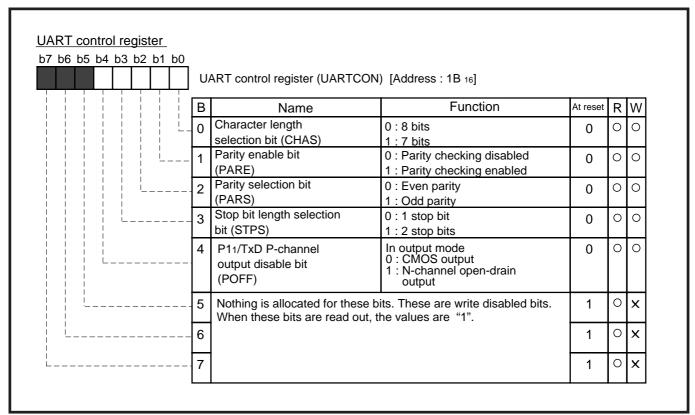


Fig. 2.3.5 Structure of UART control register

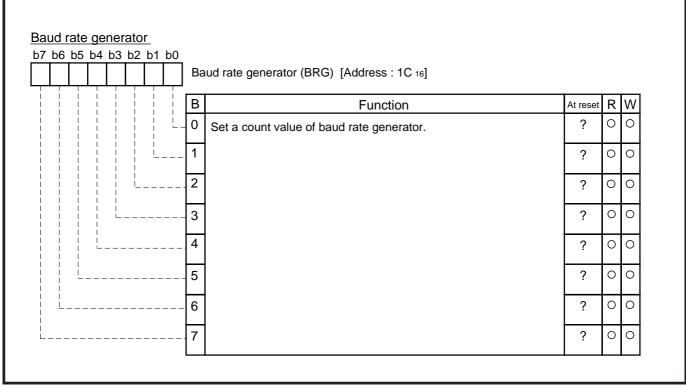


Fig. 2.3.6 Structure of Baud rate generator

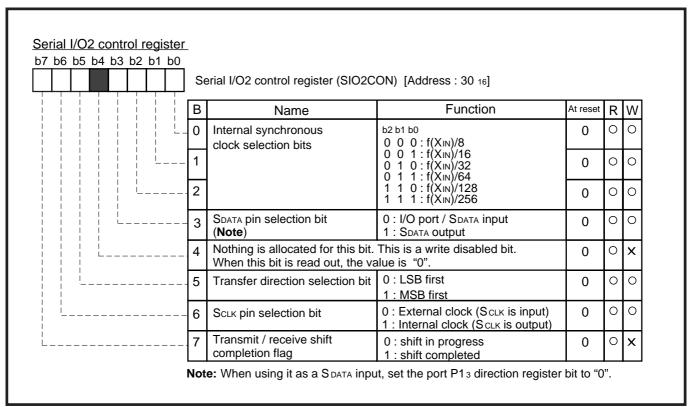


Fig. 2.3.7 Structure of Serial I/O2 control register

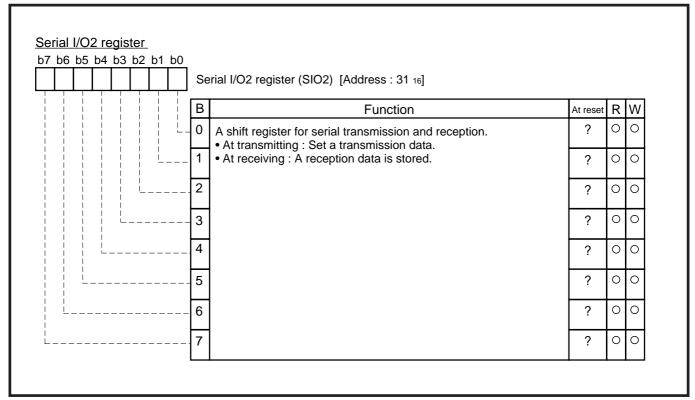


Fig. 2.3.8 Structure of Serial I/O2 register

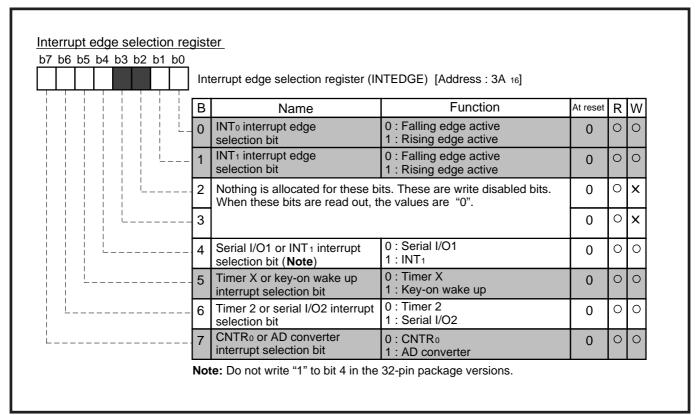


Fig. 2.3.9 Structure of Interrupt edge selection register

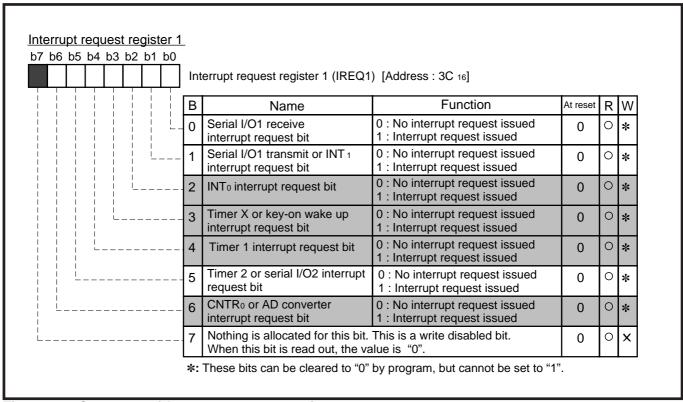


Fig. 2.3.10 Structure of Interrupt request register 1

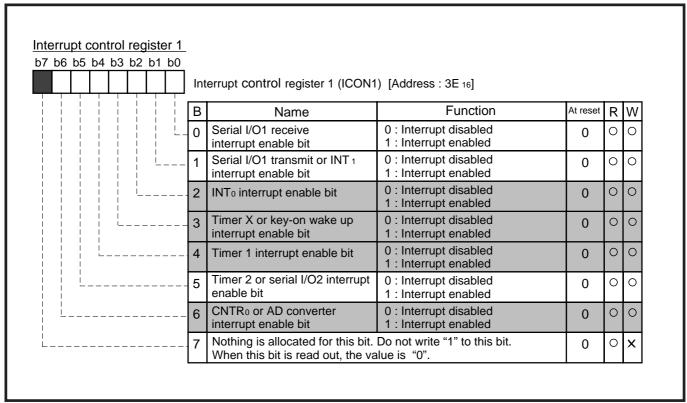


Fig. 2.3.11 Structure of Interrupt control register 1

2.3 Serial I/O

2.3.3 Serial I/O connection examples

(1) Control of peripheral IC equipped with CS pin

Figure 2.3.12 shows connection examples with a peripheral IC equipped with the CS pin. Each case uses the clock synchronous serial I/O mode.

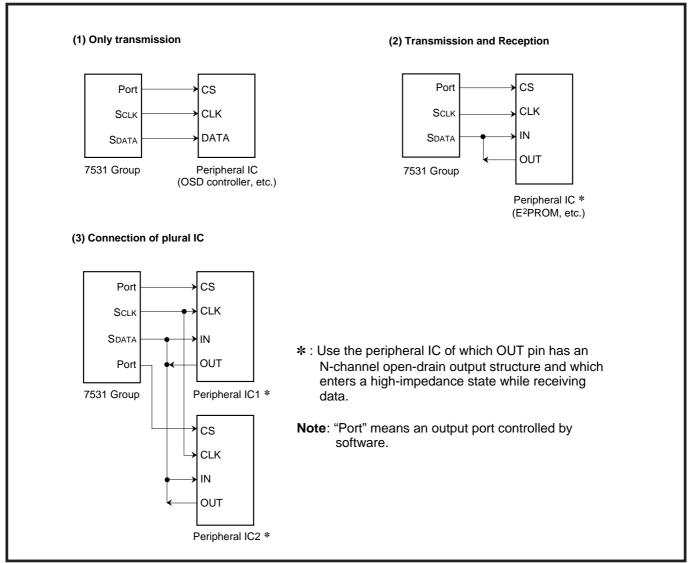


Fig. 2.3.12 Serial I/O connection examples (1)

(2) Connection with microcomputer

Figure 2.3.13 shows connection examples with another microcomputer.

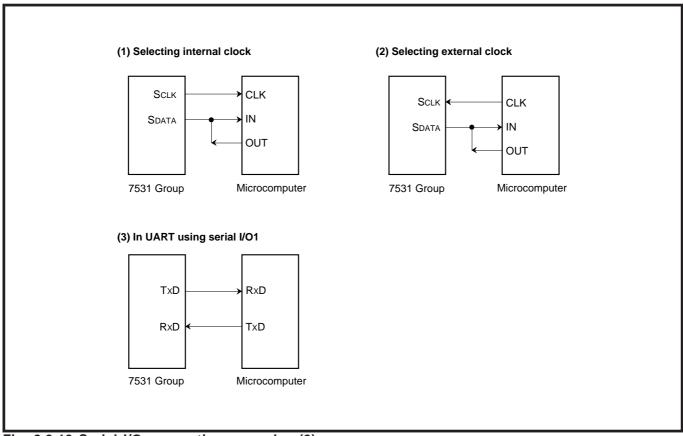


Fig. 2.3.13 Serial I/O connection examples (2)

2.3 Serial I/O

2.3.4 Serial I/O transfer data format

The clock synchronous or the clock asynchronous (UART) can be selected as the serial I/O. Figure 2.3.14 shows the serial I/O transfer data format.

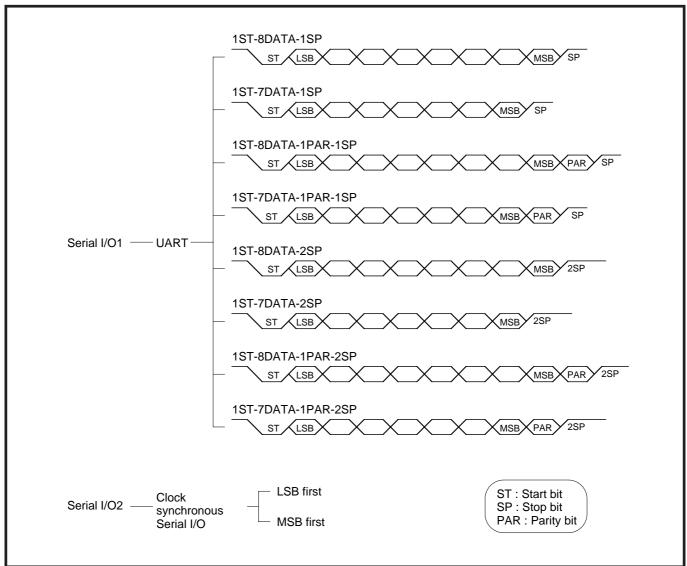


Fig. 2.3.14 Serial I/O transfer data format

2.3.5 Serial I/O application examples

(1) Communication using clock synchronous serial I/O (transmit/receive)

Outline: 2-byte data is transmitted and received, using the clock synchronous serial I/O. Port P0₀ is used for communication control and outputs the quasi-SRDY signal.

The following explain an example using the serial I/O2. Figure 2.3.15 shows a connection diagram, and Figure 2.3.16 shows a timing chart.

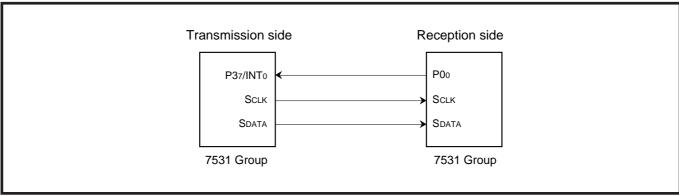


Fig. 2.3.15 Connection diagram

Specifications: •The Serial I/O2, clock synchronous serial I/O, is used.

- •Synchronous clock frequency : 125 kHz; f(X_{IN}) = 8 MHz divided by 64
- •Transfer direction : LSB first
- •The reception side outputs the quasi-\$\overline{S_{RDY}}\$ signal at 2 ms intervals which the timer generates, and 2-byte data is transferred from the transmission side to the reception side.

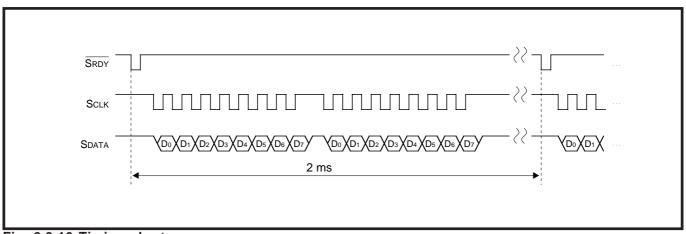


Fig. 2.3.16 Timing chart

2.3 Serial I/O

Figures 2.3.17 and 2.3.19 show the registers setting relevant to the serial I/O2 and Figure 2.3.18 shows the transmission data setting of the serial I/O2.

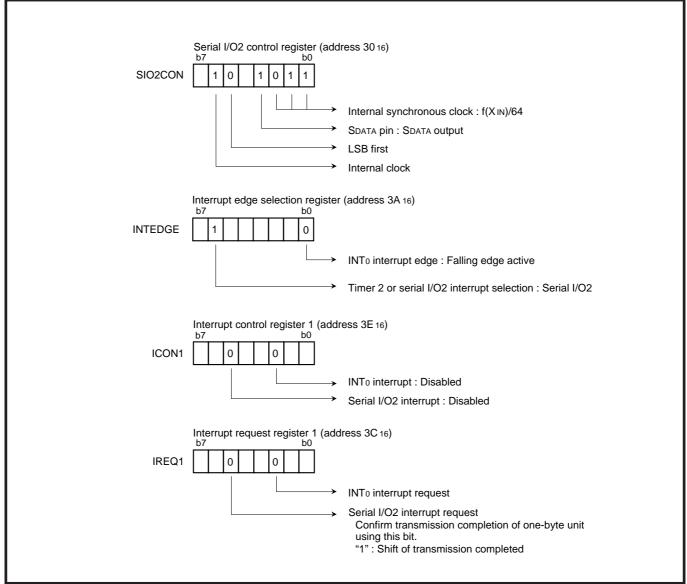


Fig. 2.3.17 Registers setting relevant to transmission side

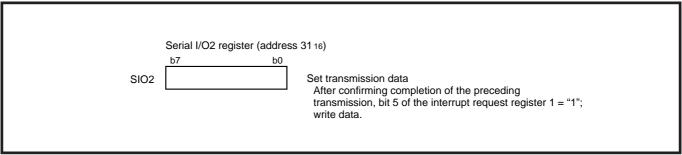


Fig. 2.3.18 Transmission data setting of serial I/O2

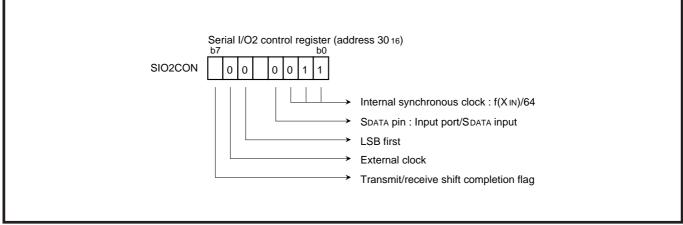


Fig. 2.3.19 Registers setting relevant to reception side

2.3 Serial I/O

Figure 2.3.20 shows a control procedure of transmission side, and Figure 2.3.21 shows a control procedure of reception side.

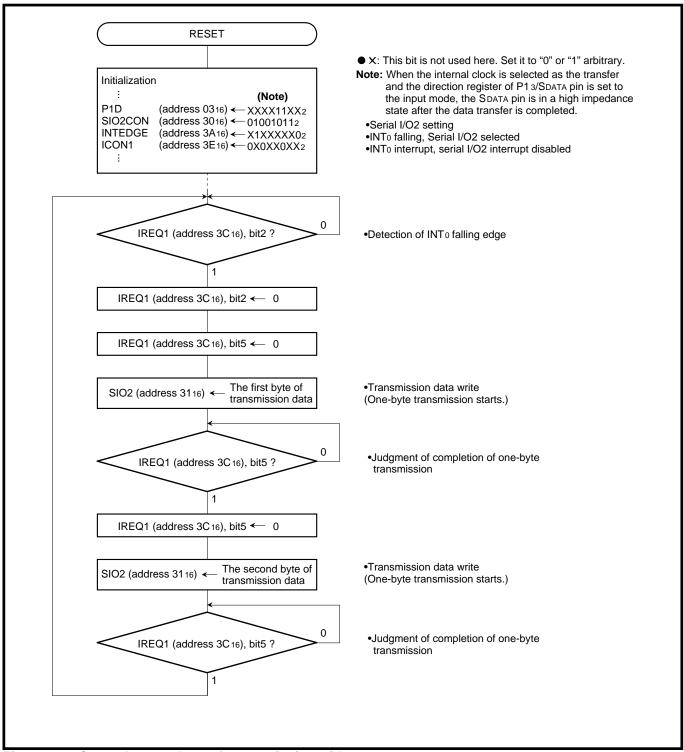


Fig. 2.3.20 Control procedure of transmission side

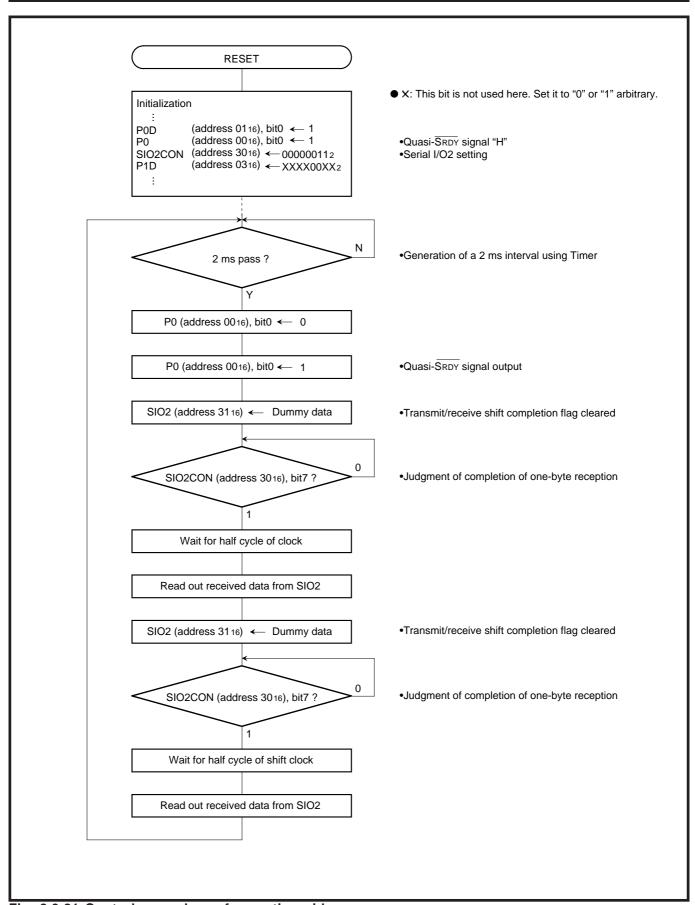


Fig. 2.3.21 Control procedure of reception side

2.3 Serial I/O

(2) Communication using asynchronous serial I/O, UART (transmit/receive)

Outline: 2-byte data is transmitted and received, using the clock asynchronous serial I/O. Port P0₀ is used for communication control.

Figure 2.3.22 shows a connection diagram, and Figure 2.3.23 shows a timing chart.

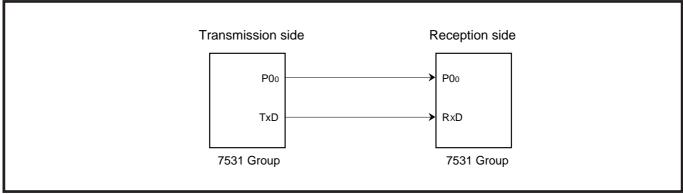


Fig. 2.3.22 Connection diagram

Specifications: •The Serial I/O1, asynchronous serial I/O, is used.

•Transfer bit rate : 9600 bps; $f(X_{IN}) = 4.9152$ MHz divided by 512

•Communication control using port P0₀; Port P0₀ output level is controlled by software.

•2-byte data is transferred from the transmission side to the reception side at 10 ms intervals which the timer generates

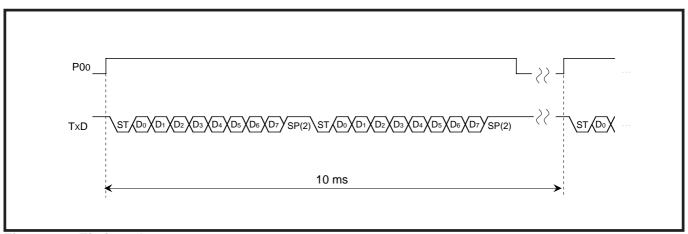


Fig. 2.3.23 Timing chart

2.3 Serial I/O

Table 2.3.1 shows a setting example of the baud rate generator (BRG) and transfer bit rate values; Figure 2.3.23 shows the registers setting relevant to transmission side; Figure 2.3.24 shows the registers setting relevant to reception side

Table 2.3.1 Setting example of baud rate generator (BRG) and transfer bit rate values

BRG count source	BRG set value	Transfer bit rate (bps) (Note 2)	
(Note 1)		At $f(X_{IN}) = 4.9152 \text{ MHz}$	At $f(X_{IN}) = 8 \text{ MHz}$
f(X _{IN}) / 4	255 (FF ₁₆)	300	488.28125
f(X _{IN}) / 4	127 (7F ₁₆)	600	976.5625
f(X _{IN}) / 4	63 (3F ₁₆)	1200	1953.125
f(X _{IN}) / 4	31 (1F ₁₆)	2400	3906.25
f(X _{IN}) / 4	15 (0F ₁₆)	4800	7812.5
f(X _{IN}) / 4	7 (0716)	9600	15625
f(X _{IN}) / 4	3 (0316)	19200	31250
f(X _{IN}) / 4	1 (0116)	38400	62500
f(X _{IN})	3 (0316)	76800	125000
f(X _{IN})	1 (0116)	153600	250000
f(X _{IN})	0 (0016)	307200	500000

Notes 1: Select the BRG count source with bit 0 of the serial I/O1 control register (address 1A₁₆).

2: Equation of transfer bit rate:

Transfer bit rate (bps) =
$$\frac{f(X_{IN})}{(BRG \text{ set value } + 1) \times 16 \times m^*}$$

m*: m = 1 in the case of bit 0 of the serial I/O1 control register (address $001A_{16}$) = "0" m = 4 in the case of bit 0 of the serial I/O1 control register (address $001A_{16}$) = "1"

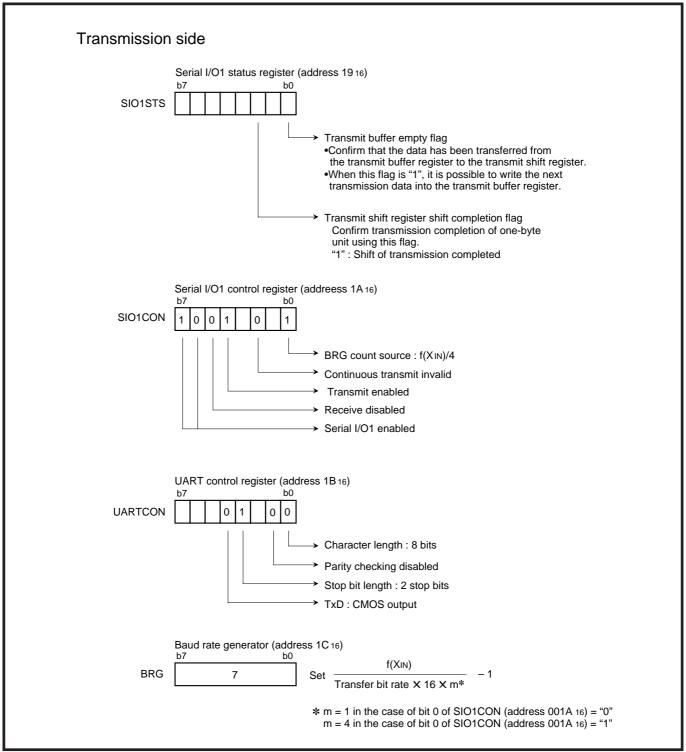


Fig. 2.3.24 Registers setting relevant to transmission side

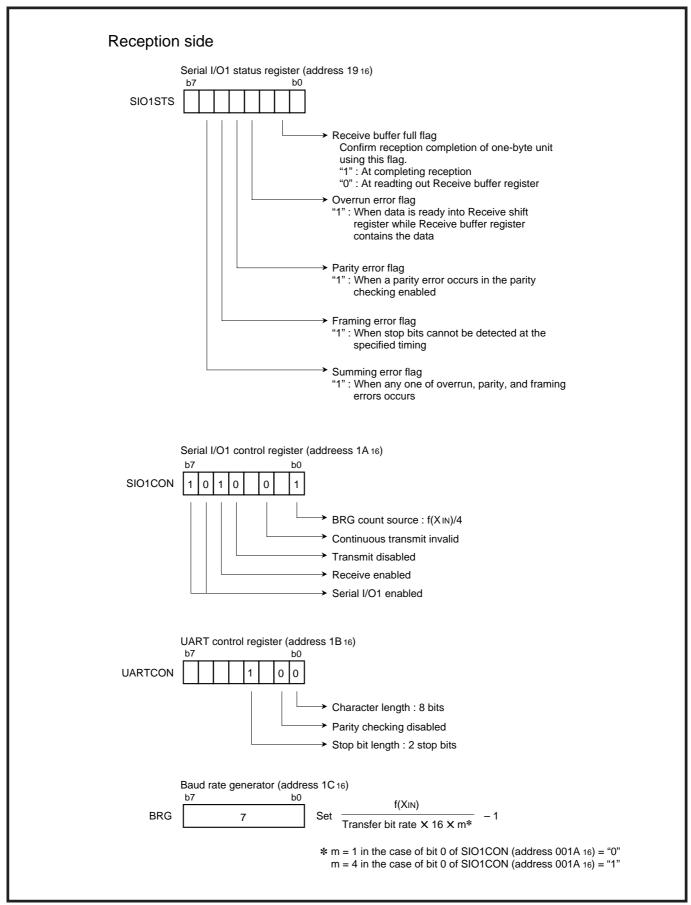


Fig. 2.3.25 Registers setting relevant to reception side

2.3 Serial I/O

Figure 2.3.26 shows a control procedure of transmission side, and Figure 2.3.27 shows a control procedure of reception side.

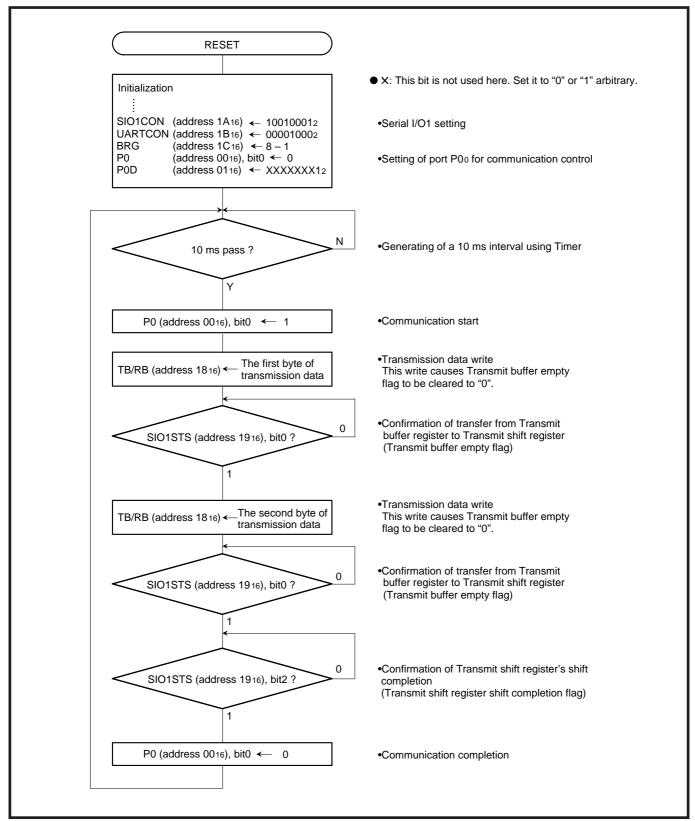


Fig. 2.3.26 Control procedure of transmission side

2-48

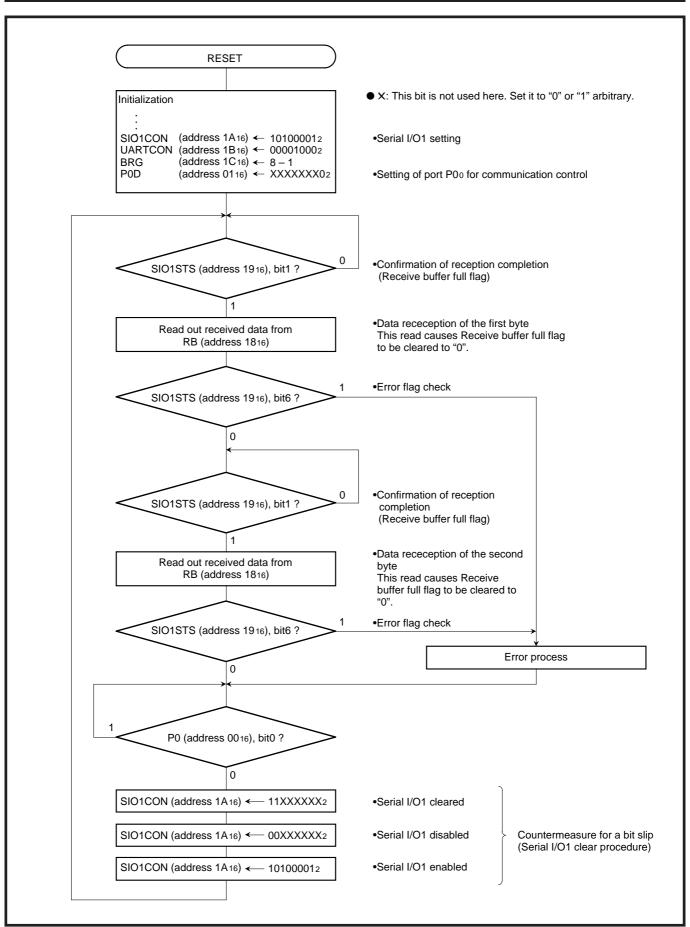


Fig. 2.3.27 Control procedure of reception side

2.3 Serial I/O

2.3.6 Notes on serial I/O

(1) Handling of clear the serial I/O1

When serial I/O1 is set again or the transmit/receive operation is stopped/restarted while serial I/O1 is operating, clear the serial I/O1 as shown in Figure 2.3.28.

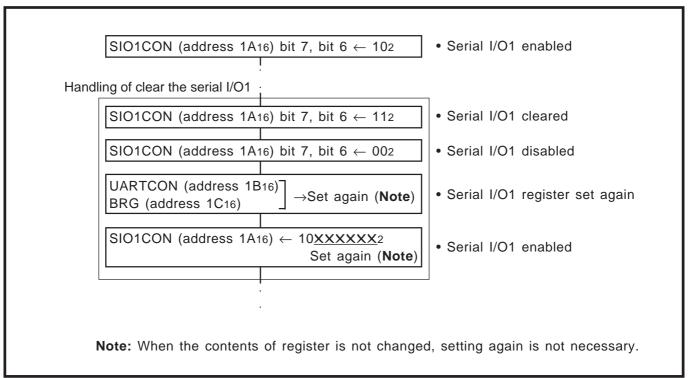


Fig. 2.3.28 Sequence of clearing serial I/O

(2) Data transmission control with referring to transmit shift register completion flag

The transmit shift register completion flag changes from "1" to "0" with a delay of 0.5 to 1.5 shift clocks. When data transmission is controlled with referring to the flag after writing the data to the transmit buffer register, note the delay.

(3) Writing transmit data

When an external clock is used as the synchronous clock for the clock synchronous serial I/O, write the transmit data to the transmit buffer register (serial I/O shift register) at "H" of the transfer clock input level.

(4) Serial I/O2 transmit/receive shift completion flag

- •The transmit/receive shift completion flag of the serial I/O2 control register is set to "1" after completing transmit/receive shift. In order to set this flag to "0", write data (dummy data at reception) to the serial I/O2 register by program.
- •Bit 7 of the serial I/O2 control register is set to "1" a half cycle (of the shift clock) earlier than completion of shift operation. Accordingly, when using this bit to confirm shift completion, a half cycle or more of the shift clock must pass after confirming that this bit is set to "1", before performing read/write to the serial I/O2 register.

2.4 A-D converter

This paragraph explains the registers setting method and the notes relevant to the A-D converter.

2.4.1 Memory map

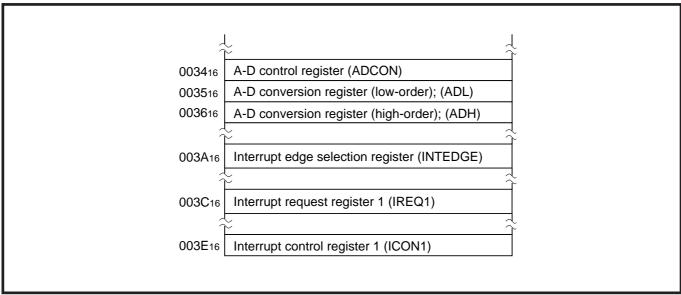


Fig. 2.4.1 Memory map of registers relevant to A-D converter

2.4.2 Relevant registers

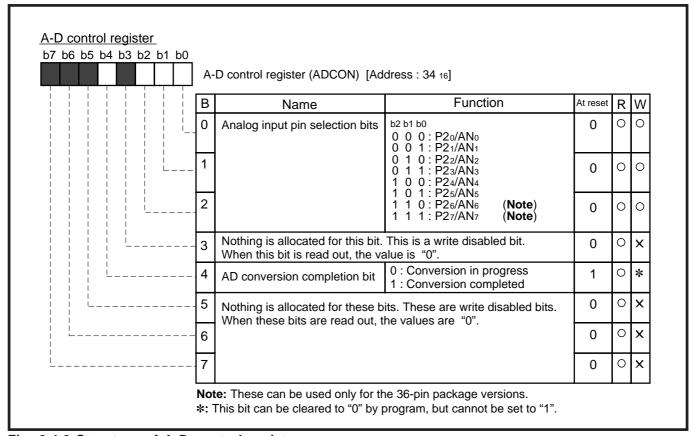


Fig. 2.4.2 Structure of A-D control register

2.4 A-D converter

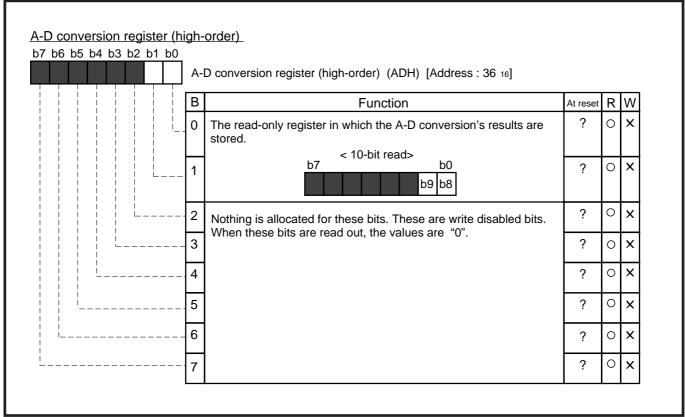


Fig. 2.4.3 Structure of A-D conversion register (high-order)

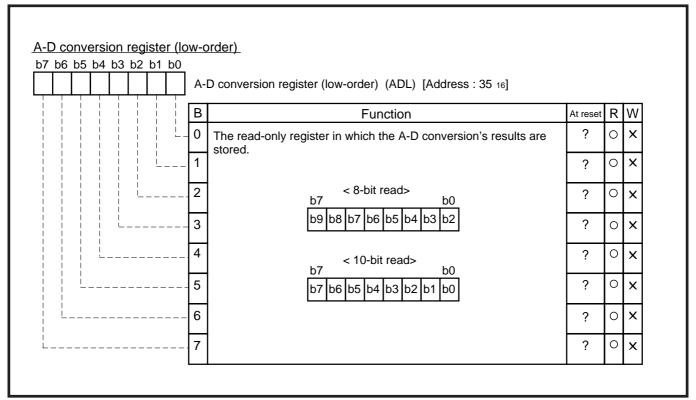


Fig. 2.4.4 Structure of A-D conversion register (low-order)

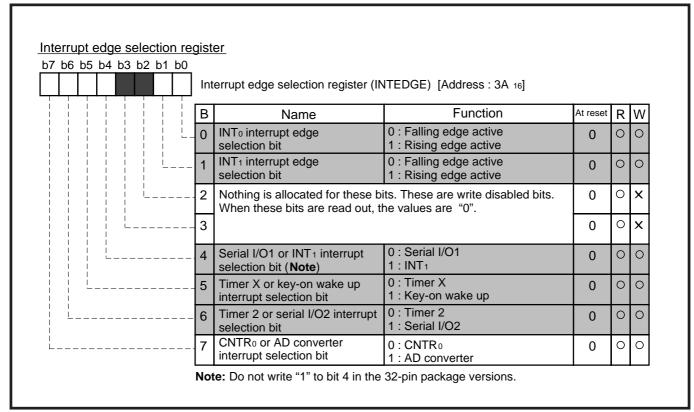


Fig. 2.4.5 Structure of Interrupt edge selection register

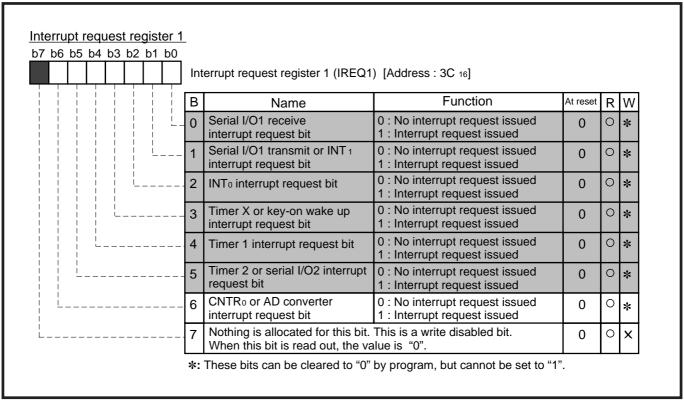


Fig. 2.4.6 Structure of Interrupt request register 1

APPLICATION

2.4 A-D converter

o7 b6 b5 b4 b3 b2 b1 b0	In	terrupt control register 1 (ICON1) [Address : 3E 16]			
	В	Name	Function	At reset	R	W
	0	Serial I/O1 receive interrupt enable bit	0 : Interrupt disabled 1 : Interrupt enabled	0	0	0
	1	Serial I/O1 transmit or INT 1 interrupt enable bit	0 : Interrupt disabled 1 : Interrupt enabled	0	0	0
	- 2	INT₀ interrupt enable bit	0 : Interrupt disabled 1 : Interrupt enabled	0	0	0
	3	Timer X or key-on wake up interrupt enable bit	0 : Interrupt disabled 1 : Interrupt enabled	0	0	0
	4	Timer 1 interrupt enable bit	0 : Interrupt disabled 1 : Interrupt enabled	0	0	0
	5	Timer 2 or serial I/O2 interrupt enable bit	0 : Interrupt disabled 1 : Interrupt enabled	0	0	0
	6	CNTR ₀ or AD converter interrupt enable bit	0 : Interrupt disabled 1 : Interrupt enabled	0	0	0
L	7	Nothing is allocated for this bit. When this bit is read out, the va		0	0	X

Fig. 2.4.7 Structure of Interrupt control register 1

2.4.3 A-D converter application examples

(1) Conversion of analog input voltage

Outline: The analog input voltage input from a sensor is converted to digital values.

Figure 2.4.8 shows a connection diagram, and Figure 2.4.9 shows the relevant registers setting.

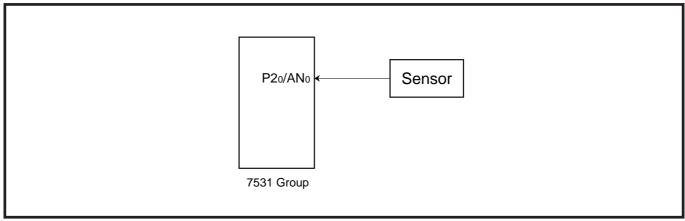


Fig. 2.4.8 Connection diagram

Specifications: •The analog input voltage input from a sensor is converted to digital values.

•P2₀/AN₀ pin is used as an analog input pin.

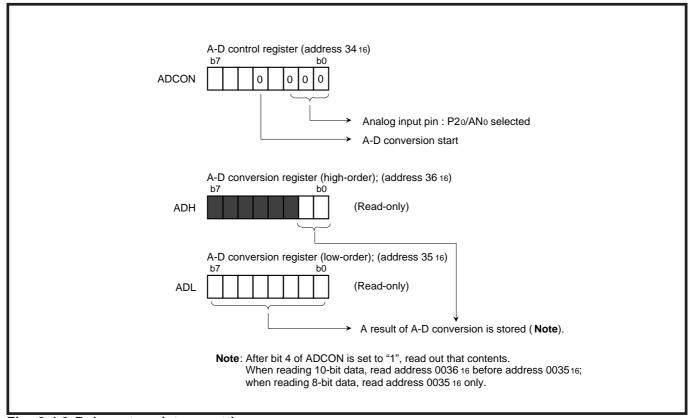


Fig. 2.4.9 Relevant registers setting

APPLICATION

2.4 A-D converter

An analog input signal from a sensor is converted to the digital value according to the relevant registers setting shown by Figure 2.4.9. Figure 2.4.10 shows the control procedure for 8-bit read, and Figure 2.4.11 shows the control procedure for 10-bit read.

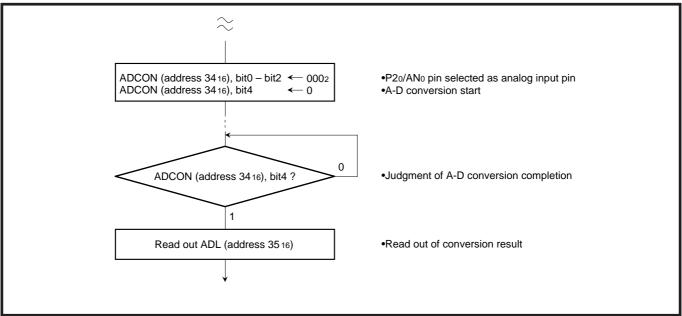


Fig. 2.4.10 Control procedure for 8-bit read

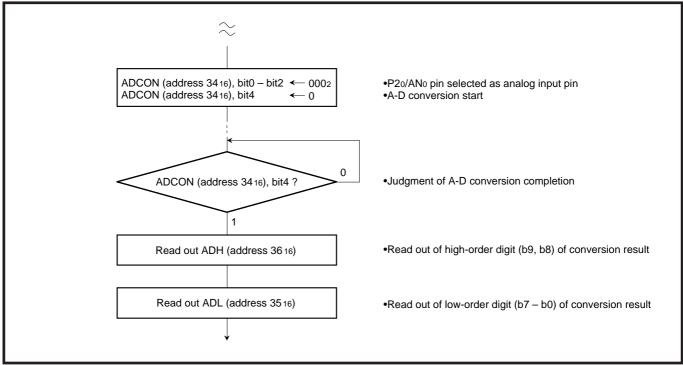


Fig. 2.4.11 Control procedure for 10-bit read

APPLICATION

2.4 A-D converter

2.4.4 Notes on A-D converter

(1) Analog input pin

Make the signal source impedance for analog input low, or equip an analog input pin with an external capacitor of $0.01\mu F$ to $1\mu F$. Further, be sure to verify the operation of application products on the user side.

Reason

An analog input pin includes the capacitor for analog voltage comparison. Accordingly, when signals from signal source with high impedance are input to an analog input pin, charge and discharge noise generates. This may cause the A-D conversion/comparison precision to be worse.

(2) Clock frequency during A-D conversion

The comparator consists of a capacity coupling, and a charge of the capacity will be lost if the clock frequency is too low. Thus, make sure the following during an A-D conversion.

- f(X_{IN}) is 500 kHz or more
- Do not execute the STP instruction

2.5 Reset

2.5 Reset

2.5.1 Connection example of reset IC

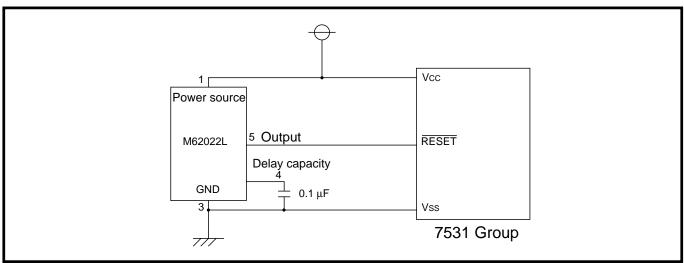


Fig. 2.5.1 Example of poweron reset circuit

Figure 2.5.2 shows the system example which switches to the RAM backup mode by detecting a drop of the system power source voltage with the INT interrupt.

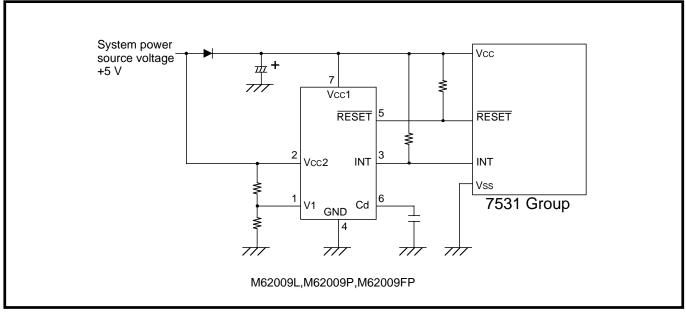


Fig. 2.5.2 RAM backup system

APPLICATION

2.5.2 Notes on RESET pin

Connecting capacitor

In case where the RESET signal rise time is long, connect a ceramic capacitor or others across the RESET pin and the Vss pin. Use a 1000 pF or more capacitor for high frequency use. When connecting the capacitor, note the following :

- Make the length of the wiring which is connected to a capacitor as short as possible.
- Be sure to verify the operation of application products on the user side.

Reason

If the several nanosecond or several ten nanosecond impulse noise enters the $\overline{\text{RESET}}$ pin, it may cause a microcomputer failure.

APPLICATION

2.5 Reset

MEMO

CHAPTER 3

APPENDIX

- 3.1 Electrical characteristics
- 3.2 Typical characteristics
- 3.3 Notes on use
- 3.4 Countermeasures against noise
- 3.5 List of registers
- 3.6 Mask ROM confirmation form
- 3.7 ROM programming confirmation form
- 3.8 Mark specification form
- 3.9 Package outline
- 3.10 Machine instructions
- 3.11 List of instruction code
- 3.12 SFR memory map
- 3.13 Pin configurations

3.1 Electrical characteristics

3.1 Electrical characteristics

3.1.1 7531 Group (General purpose)

Applied to: M37531M4-XXXFP/SP/GP, M37531M8-XXXFP/SP/GP, M37531E4FP/SP/GP, M37531E8FP/SP

(1) Absolute maximum ratings (General purpose)

Table 3.1.1 Absolute maximum ratings

Symbol		Parameter	Conditions	Ratings	Unit
Vcc	Power source volta	age		-0.3 to 7.0	V
Vı	Input voltage	P00–P07, P10–P14, P20–P27, P30–P37, VREF	All voltages are	-0.3 to Vcc + 0.3	٧
Vı	Input voltage	RESET, XIN	based on Vss. Output transistors	-0.3 to Vcc + 0.3	V
Vı	Input voltage	CNVss (Note 1)	are cut off.	-0.3 to 13	V
Vo	Output voltage	P00-P07, P10-P14, P20-P27, P30-P37, XOUT		-0.3 to Vcc + 0.3	V
Pd	Power dissipation		Ta = 25°C	300 (Note 2)	mW
Topr	Operating tempera	Operating temperature		-20 to 85	°C
Tstg	Storage temperatu	ire		-40 to 125	°C

Note 1: It is a rating only for the One Time PROM version. Connect to VSS for the mask ROM version. 2: 200 mW for the 32P6B package product.

(2) Recommended operating conditions (General purpose)

Table 3.1.2 Recommended operating conditions (1)

(Vcc = 2.2 to 5.5 V, Ta = -20 to 85 °C, unless otherwise noted)

Comment of	Davies	-4		Limits		Unit
Symbol	Param	eter	Min.	Тур.	Max.	Unit
Vcc	Power source voltage (ceramic) f(XIN	N) = 8 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
	f(XIN	N) = 4 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
	f(XIN	N) = 2 MHz (High-, Middle-speed mode)	2.2	5.0	5.5	V
	f(XII	n) = 4 MHz (Double-speed mode)	4.0	5.0	5.5	V
	f(XII	N) = 2 MHz (Double-speed mode)	2.4	5.0	5.5	V
	f(XII	x) = 1 MHz (Double-speed mode)	2.2	5.0	5.5	V
	Power source voltage (CR) f(XIII	N) = 4 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
	f(XII	N) = 2 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
	f(XII	N) = 1 MHz (High-, Middle-speed mode)	2.2	5.0	5.5	V
Vss	Power source voltage			0		V
VREF	Analog reference voltage		2.0		Vcc	V
VIH	"H" input voltage P00–P07, P10–P14, P20–P27, P30–P37		0.8Vcc		Vcc	V
VIH	"H" input voltage (TTL input level selected	d) P10, P12, P13, P36, P37 (Note 1)	2.0		Vcc	V
VIH	"H" input voltage	RESET, XIN	0.8Vcc		Vcc	V
VIL	"L" input voltage	P00-P07, P10-P14, P20-P27, P30-P37	0		0.3Vcc	V
VIL	"L" input voltage (TTL input level selected	P10, P12, P13, P36, P37 (Note 1)	0		0.8	V
VIL	"L" input voltage	RESET, CNVss	0		0.2Vcc	V
VIL	"L" input voltage	XIN	0		0.16Vcc	V
∑IOH(peak)	"H" total peak output current (Note 2)	P00-P07, P10-P14, P20-P27, P30-P37			-80	mA
∑lOL(peak)	"L" total peak output current (Note 2)	P00-P07, P10-P14, P20-P27, P37			80	mA
∑IOL(peak)	"L" total peak output current (Note 2)	P30-P36			60	mA
∑IOH(avg)	"H" total average output current (Note 2)	P00-P07, P10-P14, P20-P27, P30-P37			-40	mA
∑lOL(avg)	"L" total average output current (Note 2)	P00-P07, P10-P14, P20-P27, P37			40	mA
Σ IOL(avg)	"L" total average output current (Note 2)	P30-P36			30	mA

Note 1: Vcc = 4.0 to 5.5V

^{2:} The total output current is the sum of all the currents flowing through all the applicable ports. The total average current is an average value measured over 100 ms. The total peak current is the peak value of all the currents.

3.1 Electrical characteristics

Table 3.1.3 Recommended operating conditions (2)

(Vcc = 2.2 to 5.5 V, Ta = -20 to 85 °C, unless otherwise noted)

Cumbal	Parameter			Limits		Unit
Symbol	Parameter		Min.	Тур.	Max.	
IOH(peak)	"H" peak output current (Note 1)	P00–P07, P10–P14, P20–P27, P30–P37			-10	mA
IOL(peak)	"L" peak output current (Note 1)	P00-P07, P10-P14, P20-P27, P37			10	mA
IOL(peak)	"L" peak output current (Note 1)	P30-P36			30	mA
IOH(avg)	"H" average output current (Note 2)	P00-P07, P10-P14, P20-P27, P30-P37			-5	mA
IOL(avg)	"L" average output current (Note 2)	P00–P07, P10–P14, P20–P27, P37			5	mA
IOL(avg)	"L" average output current (Note 2)	P30-P36			15	mA
f(XIN)	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	VCC = 4.0 to 5.5 V Double-speed mode			4	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	VCC = 2.4 to 5.5 V Double-speed mode			2	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	VCC = 2.2 to 5.5 V Double-speed mode			1	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	VCC = 4.0 to 5.5 V High-, Middle-speed mode			8	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	VCC = 2.4 to 5.5 V High-, Middle-speed mode			4	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 2.2 to 5.5 V High-, Middle-speed mode			2	MHz
	Oscillation frequency (Note 3) at RC oscillation	Vcc = 4.0 to 5.5 V High-, Middle-speed mode			4	MHz
	Oscillation frequency (Note 3) at RC oscillation	VCC = 2.4 to 5.5 V High-, Middle-speed mode			2	MHz
	Oscillation frequency (Note 3) at RC oscillation	Vcc = 2.2 to 5.5 V High-, Middle-speed mode			1	MHz

Notes 1: The peak output current is the peak current flowing in each port.

2: The average output current IoL (avg), IoH (avg) in an average value measured over 100 ms.

3: When the oscillation frequency has a duty cycle of 50 %.

(3) Electrical characteristics (General purpose)

Table 3.1.4 Electrical characteristics

(Vcc = 2.2 to 5.5 V, Vss = 0 V, Ta = -20 to 85 °C, unless otherwise noted)

O made at		<u> </u>		T			Limits		11
Symbol		Para	meter	l est c	onditions	Min.	Тур.	Max.	Unit
Voн	"H" output voltage		07, P10–P14, P20–P27, 37 (Note 1)	IOH = -5 m VCC = 4.0		Vcc-1.5			V
				IOH = -1.0 VCC = 2.2		Vcc-1.0			V
VoL	"L" output voltage	P00-F P37	07, P10–P14, P20–P27,	IOL = 5 mA VCC = 4.0				1.5	V
				IOL = 1.5 n VCC = 4.0				0.3	V
				IOL = 1.0 m VCC = 2.2				1.0	V
VoL	"L" output voltage P30-P36		36	IOL = 15 m VCC = 4.0				2.0	V
				IOL = 1.5 m VCC = 4.0				0.3	V
				IOL = 10 m VCC = 2.2				1.0	V
VT+-VT-	Hysteresis		INT ₀ , INT ₁ (Note 2) 7 (Note 3)			0.4		V	
VT+-VT-	Hysteresis	RxD,	SCLK, SDATA (Note 2)				0.5		V
VT+-VT-	Hysteresis	RESE	T				0.5		V
lін	"H" input current	P00-F P30-F	07, P10–P14, P20–P27, 37	VI = VCC (Pin floating transistors				5.0	μΑ
lін	"H" input current	RESE	T	VI = VCC				5.0	μA
IIН	"H" input current	XIN		VI = VCC			4.0		μA
lıL	"L" input current	P00-F P30-F	07, P10–P14, P20–P27, 37	VI = VSS (Pin floating transistors				-5.0	μА
lıL	"L" input current	RESE	T, CNVss	VI = VSS				-5.0	μA
lıL	"L" input current	XIN	,	VI = VSS			-4.0		μA
lıL	"L" input current	P00-F	07, P30–P37	VI = VSS (Pull up trai	nsistors "on")		-0.2	-0.5	mA
VRAM	RAM hold voltage			When cloc	ck stopped	2.0		5.5	V
Icc	Power source curr	ent	High-speed mode, f(XIN) = Output transistors "off"	8 MHz			5.0	8.0	mA
			High-speed mode, f(XIN) = Output transistors "off"	2 MHz, Vcc	= 2.2 V		0.5	1.5	mA
			Double-speed mode, f(XIN) Output transistors "off"	= 4 MHz			5.0	8.0	mA
			Middle-speed mode, f(XIN) Output transistors "off"	= 8 MHz			2.0	5.0	mA
			f(XIN) = 8 MHz (in WIT state Functions except timers 1 a Output transistors "off"				1.6	3.2	mA
			f(XIN) = 2 MHz, Vcc = 2.2 \ Output transistors "off"	/ (in WIT sta	te)		0.2		mA
			Increment when A-D convertion f(XIN) = 8 MHz, VCC = 5 V	ersion is exec	cuted		0.5		mA
			All oscillation stopped (in S	TP state)	Ta = 25 °C		0.1	1.0	μA
			Output transistors "off"		Ta = 85 °C			10	μA

Notes 1: P11 is measured when the P11/TxD P-channel output disable bit of the UART control register (bit 4 of address 001B16) is "0".

^{2:} RXD, SCLK, SDATA, INTo, and INTo have hysteresises only when bits 0 to 2 of the port P1P3 control register are set to "0" (CMOS level).

3: It is available only when operating key-on wake up.

3.1 Electrical characteristics

(4) A-D converter characteristics (General purpose)

Table 3.1.5 A-D Converter characteristics

(Vcc = 2.7 to 5.5 V, Vss = 0 V, Ta = -20 to 85 °C, unless otherwise noted)

Cumbal	Deremeter	Toot conditions		Limits		Unit
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
_	Resolution				10	Bits
_	Linearity error	Vcc = 2.7 to 5.5 V Ta = 25 °C			±3	LSB
_	Differential nonlinear error	VCC = 2.7 to 5.5 V Ta = 25 °C			±0.9	LSB
Vот	Zero transition voltage	VCC = VREF = 5.12 V	0	5	20	mV
		VCC = VREF = 3.072 V	0	3	15	mV
VFST	Full scale transition voltage	VCC = VREF = 5.12 V	5105	5115	5125	mV
		VCC = VREF = 3.072 V	3060	3069	3075	mV
tCONV	Conversion time				122	tc(XIN)
RLADDER	Ladder resistor			55		kΩ
IVREF	Reference power source input current	VREF = 5.0 V	50	150	200	μΑ
		VREF = 3.0 V	30	70	120	μΛ
II(AD)	A-D port input current				5.0	μA

(5) Timing requirements (General purpose)

Table 3.1.6 Timing requirements (1)

(Vcc = 4.0 to 5.5 V, Vss = 0 V, Ta = -20 to 85 °C, unless otherwise noted)

Courselle ad	Devenuetos		Limits		l lait
Symbol	Parameter	Min.	Тур.	Max.	Unit
tw(RESET)	Reset input "L" pulse width	15			μs
tc(XIN)	External clock input cycle time	125			ns
twh(XIN)	External clock input "H" pulse width	50			ns
twL(XIN)	External clock input "L" pulse width	50			ns
tc(CNTR)	CNTR ₀ input cycle time	200			ns
twh(CNTR)	CNTR ₀ , INT ₀ , INT ₁ , input "H" pulse width	80			ns
twL(CNTR)	CNTR ₀ , INT ₀ , INT ₁ , input "L" pulse width	80			ns
tc(Sclk)	Serial I/O2 clock input cycle time	1000			ns
twh(Sclk)	Serial I/O2 clock input "H" pulse width	400			ns
twL(Sclk)	Serial I/O2 clock input "L" pulse width	400			ns
tsu(SCLK-SDATA)	Serial I/O2 input set up time	200			ns
th(SCLK-SDATA)	Serial I/O2 input hold time	200			ns

Table 3.1.7 Timing requirements (2)

(Vcc = 2.2 to 5.5 V or 2.4 to 5.5 V, Vss = 0 V, Ta = -20 to 85 °C, unless otherwise noted)

Countrie al	Descriptor	Doromotor			Limits			
Symbol	Parameter		Min.	Тур.	Max.	Unit		
tw(RESET)	Reset input "L" pulse width	Vcc = 2.2 to 5.5 V	45			μs		
		Vcc = 2.4 to 5.5 V	35			μs		
tc(XIN)	External clock input cycle time	Vcc = 2.2 to 5.5 V	500			ns		
		Vcc = 2.4 to 5.5 V	250			ns		
twh(XIN)	External clock input "H" pulse width	Vcc = 2.2 to 5.5 V	200			ns		
		Vcc = 2.4 to 5.5 V	100			ns		
twL(XIN)	External clock input "L" pulse width	Vcc = 2.2 to 5.5 V	200			ns		
		Vcc = 2.4 to 5.5 V	100			ns		
tc(CNTR)	CNTR ₀ input cycle time	Vcc = 2.2 to 5.5 V	1000			ns		
		Vcc = 2.4 to 5.5 V	500			ns		
twh(CNTR)	CNTRo, INTo, INT1, input "H" pulse width	Vcc = 2.2 to 5.5 V	460			ns		
		Vcc = 2.4 to 5.5 V	230			ns		
twL(CNTR)	CNTRo, INTo, INT1, input "L" pulse width	Vcc = 2.2 to 5.5 V	460			ns		
		Vcc = 2.4 to 5.5 V	230			ns		
tc(Sclk)	Serial I/O2 clock input cycle time	Vcc = 2.2 to 5.5 V	4000			ns		
		Vcc = 2.4 to 5.5 V	2000			ns		
twh(Sclk)	Serial I/O2 clock input "H" pulse width	Vcc = 2.2 to 5.5 V	1900			ns		
		Vcc = 2.4 to 5.5 V	950			ns		
twL(SCLK)	Serial I/O2 clock input "L" pulse width	Vcc = 2.2 to 5.5 V	1900			ns		
		VCC = 2.4 to 5.5 V	950			ns		
tsu(SCLK-SDATA)	Serial I/O2 input set up time		400			ns		
th(SCLK-SDATA)	Serial I/O2 input hold time		400			ns		

3.1 Electrical characteristics

(6) Switching characteristics (General purpose)

Table 3.1.8 Switching characteristics (1)

(Vcc = 4.0 to 5.5 V, Vss = 0 V, Ta = -20 to 85 °C, unless otherwise noted)

Cumbal	Parameter	L	Unit		
Symbol	Parameter	Min.	Тур.	Max.	Onit
twh(Sclk)	Serial I/O2 clock output "H" pulse width	tc(Sclk)/2-30			ns
twL(Sclk)	Serial I/O2 clock output "L" pulse width	tc(Sclk)/2-30			ns
td(SCLK-SDATA)	Serial I/O2 output delay time			140	ns
tv(SCLK-SDATA)	Serial I/O2 output valid time	0			ns
tr(SCLK)	Serial I/O2 clock output rising time			30	ns
tf(SCLK)	Serial I/O2 clock output falling time			30	ns
tr(CMOS)	CMOS output rising time (Note 1)		10	30	ns
tf(CMOS)	CMOS output falling time (Note 1)		10	30	ns

Note 1: Pin XouT is excluded.

Table 3.1.9 Switching characteristics (2)

(Vcc = 2.2 to 5.5 V, Vss = 0 V, Ta = -20 to 85 °C, unless otherwise noted)

Cymphol	Doromotor	Li		Unit	
Symbol	Parameter	Min.	Тур.	Max.	Unit
twh(Sclk)	Serial I/O2 clock output "H" pulse width	tc(Sclk)/2-50			ns
twL(Sclk)	Serial I/O2 clock output "L" pulse width	tc(Sclk)/2-50			ns
td(SCLK-SDATA)	Serial I/O2 output delay time			350	ns
tv(SCLK-SDATA)	Serial I/O2 output valid time	0			ns
tr(SCLK)	Serial I/O2 clock output rising time			50	ns
tf(SCLK)	Serial I/O2 clock output falling time			50	ns
tr(CMOS)	CMOS output rising time (Note 1)		20	50	ns
tf(CMOS)	CMOS output falling time (Note 1)		20	50	ns

Note 1: Pin XouT is excluded.

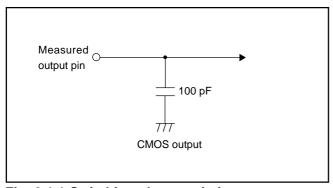


Fig. 3.1.1 Switching characteristics measurement circuit diagram (General purpose)

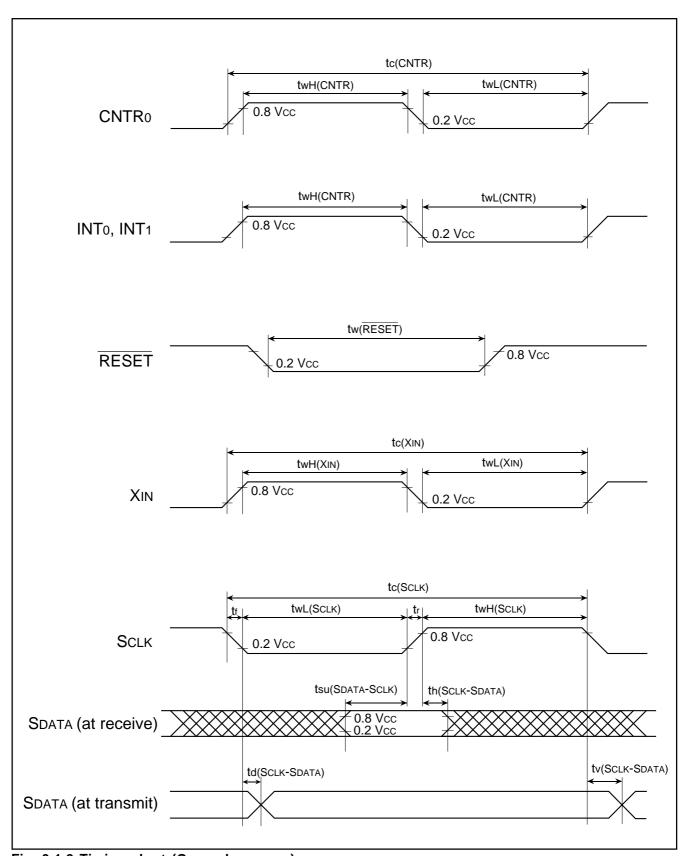


Fig. 3.1.2 Timing chart (General purpose)

3.1 Electrical characteristics

3.1.2 7531 Group (Extended operating temperature version)

Applied to: M37531M4T-XXXFP/SP/GP, M37531E4T-XXXGP

(1) Absolute maximum ratings (Extended operating temperature version)

Table 3.1.10 Absolute maximum ratings

Symbol		Parameter	Conditions	Ratings	Unit
Vcc	Power source volta	age		-0.3 to 7.0	V
VI	Input voltage	P00-P07, P10-P14, P20-P27, P30-P37, VREF	All voltages are	-0.3 to Vcc + 0.3	V
VI	Input voltage	RESET, XIN	based on Vss. Output transistors	-0.3 to Vcc + 0.3	V
Vı	Input voltage	CNVss (Note 1)	are cut off.	-0.3 to 13	V
Vo	Output voltage	P00-P07, P10-P14, P20-P27, P30-P37, XOUT		-0.3 to Vcc + 0.3	V
Pd	Power dissipation		Ta = 25°C	300 (Note 2)	mW
Topr	Operating tempera	Operating temperature		-40 to 85	°C
Tstg	Storage temperatu	ıre		-65 to 150	°C

Notes 1: It is a rating only for the One Time PROM version. Connect to Vss for the mask ROM version.

^{2: 200} mW for the 32P6B package version.

(2) Recommended operating conditions (Extended operating temperature version)

Table 3.1.11 Recommended operating conditions (1)

(Vcc = 2.4 to 5.5 V, Ta = -40 to 85 °C, unless otherwise noted)

			Limits			
Symbol		Parameter	Min.	Тур.	Max.	Unit
Vcc	Power source voltage (ceramic)	f(XIN) = 8 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
		f(XIN) = 4 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
		f(XIN) = 4 MHz (Double-speed mode)	4.0	5.0	5.5	V
		f(XIN) = 2 MHz (Double-speed mode)	2.4	5.0	5.5	V
	Power source voltage (CR)	f(XIN) = 4 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
		f(XIN) = 2 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
Vss	Power source voltage			0		V
VREF	Analog reference voltage		2.0		Vcc	V
VIH	"H" input voltage	P00–P07, P10–P14, P20–P27, P30–P37	0.8Vcc		Vcc	V
VIH	"H" input voltage (TTL input level selected)	P10, P12, P13, P36, P37 (Note 1)	2.0		Vcc	V
VIH	"H" input voltage	RESET, XIN			Vcc	V
VIL	"L" input voltage	P00–P07, P10–P14, P20–P27, P30–P37	0		0.3Vcc	V
VIL	"L" input voltage (TTL input level selected)	P10, P12, P13, P36, P37 (Note 1)	0		0.8	V
VIL	"L" input voltage	RESET, CNVss	0		0.2Vcc	V
VIL	"L" input voltage	Xin	0		0.16Vcc	V
∑IOH(peak)	"H" total peak output current (Note 2)	P00–P07, P10–P14, P20–P27, P30–P37			-80	mA
∑IOL(peak)	"L" total peak output current (Note 2)	P00–P07, P10–P14, P20–P27, P37			80	mA
∑IOL(peak)	"L" total peak output current (Note 2)	P30–P36			60	mA
\sum IOH(avg)	"H" total average output current (Note 2)	P00-P07, P10-P14, P20-P27, P30-P37			-40	mA
∑lOL(avg)	"L" total average output current (Note 2)	P00–P07, P10–P14, P20–P27, P37			40	mA
\sum IOL(avg)	"L" total average output current (Note 2)	P30–P36			30	mA

Note 1: Vcc = 4.0 to 5.5V

^{2:} The total output current is the sum of all the currents flowing through all the applicable ports. The total average current is an average value measured over 100 ms. The total peak current is the peak value of all the currents.

3.1 Electrical characteristics

Table 3.1.12 Recommended operating conditions (2)

(Vcc = 2.4 to 5.5 V, Ta = -40 to 85 °C, unless otherwise noted)

Symbol	Dorometo	Parameter		Limits			
Symbol	Parameter		Min.	Тур.	Max.	Unit	
IOH(peak)	"H" peak output current (Note 1) P00-P0	7, P10–P14, P20–P27, P30–P37			-10	mA	
IOL(peak)	"L" peak output current (Note 1) P00-P0			10	mA		
IOL(peak)	"L" peak output current (Note 1) P30-P3			30	mA		
IOH(avg)	"H" average output current (Note 2) P00-P0			-5	mA		
IOL(avg)	"L" average output current (Note 2) P00-P0			5	mA		
IOL(avg)	"L" average output current (Note 2) P30-P3			15	mA		
f(XIN)	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 4.0 to 5.5 V Double-speed mode			4	MHz	
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	VCC = 2.4 to 5.5 V Double-speed mode			2	MHz	
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 4.0 to 5.5 V High-, Middle-speed mode			8	MHz	
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 2.4 to 5.5 V High-, Middle-speed mode			4	MHz	
	Oscillation frequency (Note 3) at RC oscillation	VCC = 4.0 to 5.5 V High-, Middle-speed mode			4	MHz	
	Oscillation frequency (Note 3) at RC oscillation	Vcc = 2.4 to 5.5 V High-, Middle-speed mode			2	MHz	

Notes 1: The peak output current is the peak current flowing in each port.

^{2:} The average output current IoL (avg), IoH (avg) in an average value measured over 100 ms.

3: When the oscillation frequency has a duty cycle of 50 %.

(3) Electrical characteristics (Extended operating temperature version)

Table 3.1.13 Electrical characteristics

(Vcc = 2.4 to 5.5 V, Vss = 0 V, Ta = -40 to 85 °C, unless otherwise noted)

0		D		T 1 -			Limits		11
Symbol		Para	ımeter	l est co	onditions	Min.	Тур.	Max.	Unit
Vон	"H" output voltage		07, P10–P14, P20–P27, 37 (Note 1)	IOH = -5 m VCC = 4.0 t		Vcc-1.5			V
				IOH = -1.0 VCC = 2.4		Vcc-1.0			V
Vol	"L" output voltage	P00-F P37	07, P10–P14, P20–P27,	IOL = 5 mA VCC = 4.0				1.5	V
				IOL = 1.5 m VCC = 4.0 t				0.3	V
				IOL = 1.0 m VCC = 2.4 t				1.0	V
VoL	"L" output voltage P30–P36		IOL = 15 m. VCC = 4.0 f				2.0	V	
				IOL = 1.5 m VCC = 4.0 t				0.3	V
				IOL = 10 m. VCC = 2.4 t				1.0	V
VT+-VT-	Hysteresis		0, INT0, INT1 (Note 2) 07 (Note 3)	ote 3)			0.4		V
VT+-VT-	Hysteresis	RxD,	SCLK, SDATA (Note 2)	SDATA (Note 2)			0.5		V
VT+-VT-	Hysteresis	RESE	T				0.5		V
lін	"H" input current	P00-F P30-F	07, P10–P14, P20–P27, 37	VI = VCC (Pin floatin transistors				5.0	μА
lін	"H" input current	RESE	T	VI = VCC				5.0	μA
lін	"H" input current	XIN		VI = VCC			4.0		μA
lıL	"L" input current	P00-F P30-F	07, P10–P14, P20–P27, 37	VI = VSS (Pin floatin transistors	g. Pull up "off")			-5.0	μA
lıL	"L" input current	RESE	T, CNVss	VI = VSS				-5.0	μA
lıL	"L" input current	XIN	,	VI = VSS			-4.0		μA
lıL	"L" input current	P00-F	07, P30–P37	VI = VSS (Pull up trar	nsistors "on")		-0.2	-0.5	mA
VRAM	RAM hold voltage			When cloc	k stopped	2.0		5.5	V
Icc	Power source curr	ent	High-speed mode, f(XIN) = Output transistors "off"	8 MHz			5.0	8.0	mA
			High-speed mode, f(XIN) = Output transistors "off"	2 MHz, Vcc	= 2.4 V		0.5	1.5	mA
			Double-speed mode, f(XIN) Output transistors "off"	= 4 MHz			5.0	8.0	mA
			Middle-speed mode, f(XIN) Output transistors "off"	= 8 MHz,			2.0	5.0	mA
		f(XIN) = 8 MHz (in WIT state Functions except Timer 1 a Output transistors "off"			top		1.6	3.2	mA
		f(XIN) = 2 MHz, VCC = 2.4 Output transistors "off"		/ (in WIT stat	re)		0.2		mA
			Increment when A-D conve f(XIN) = 8 MHz, VCC = 5 V	rsion is exec	uted		0.5		mA
			All oscillation stopped (in STP s		Ta = 25 °C		0.1	1.0	μA
			Output transistors "off"		Ta = 85 °C		-	10	μA

Notes 1: P11 is measured when the P11/TxD P-channel output disable bit of the UART control register (bit 4 of address 001B16) is "0".

^{2:} RXD, SCLK, SDATA, INTo and INT1 have hysteresises only when bits 0 to 2 of the port P1P3 control register are set to "0" (CMOS level).

^{3:} It is available only when operating key-on wake up.

3.1 Electrical characteristics

(4) A-D converter characteristics (Extended operating temperature version)

Table 3.1.14 A-D Converter characteristics

(Vcc = 2.7 to 5.5 V, Vss = 0 V, Ta = -40 to 85 °C, unless otherwise noted)

Cumbal	Doromotor	Toot conditions		Limits		Unit
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Uniii
_	Resolution				10	Bits
_	Linearity error	VCC = 2.7 to 5.5 V Ta = 25 °C			±3	LSB
_	Differential nonlinear error	VCC = 2.7 to 5.5 V Ta = 25 °C			±0.9	LSB
Vот	Zero transition voltage	VCC = VREF = 5.12 V	0	5	20	mV
		VCC = VREF = 3.072 V	0	3	15	mV
VFST	Full scale transition voltage	VCC = VREF = 5.12 V	5105	5115	5125	mV
		VCC = VREF = 3.072 V	3060	3069	3075	mV
tCONV	Conversion time				122	tc(XIN)
RLADDER	Ladder resistor			55		kΩ
IVREF	Reference power source input current	VREF = 5.0 V	50	150	200	μΑ
		VREF = 3.0 V	30	70	120	μΛ
lı(AD)	A-D port input current				5.0	μA

(5) Timing requirements (Extended operating temperature version)

Table 3.1.15 Timing requirements (1)

(Vcc = 4.0 to 5.5 V, Vss = 0 V, Ta = -40 to 85 °C, unless otherwise noted)

Symbol	Parameter			Unit	
Symbol	Farameter	Min.	Тур.	Max.	Offic
tw(RESET)	Reset input "L" pulse width	15			μs
tc(XIN)	External clock input cycle time	125			ns
twh(XIN)	External clock input "H" pulse width	50			ns
twL(XIN)	External clock input "L" pulse width	50			ns
tc(CNTR)	CNTRo input cycle time	200			ns
twh(CNTR)	CNTR ₀ , INT ₀ , INT ₁ input "H" pulse width	80			ns
twL(CNTR)	CNTRo, INTo, INT1 input "L" pulse width	80			ns
tc(Sclk)	Serial I/O2 clock input cycle time	1000			ns
twh(Sclk)	Serial I/O2 clock input "H" pulse width	400			ns
twL(SCLK)	Serial I/O2 clock input "L" pulse width	400			ns
tsu(SCLK-SDATA)	Serial I/O2 input set up time	200			ns
th(SCLK-SDATA)	Serial I/O2 input hold time	200			ns

Table 3.1.16 Timing requirements (2)

(Vcc = 2.4 to 5.5 V, Vss = 0 V, Ta = -40 to 85 °C, unless otherwise noted)

O made at	December		Limits		Unit
Symbol	Parameter	Min.	Тур.	Max.	Unit
tw(RESET)	Reset input "L" pulse width	35			μs
tc(XIN)	External clock input cycle time	250			ns
twh(XIN)	External clock input "H" pulse width	100			ns
twl(XIN)	External clock input "L" pulse width	100			ns
tc(CNTR)	CNTR ₀ input cycle time	500			ns
twn(CNTR)	CNTRo, INTo, INT1 input "H" pulse width	230			ns
twL(CNTR)	CNTR ₀ , INT ₀ , INT ₁ input "L" pulse width	230			ns
tc(Sclk)	Serial I/O2 clock input cycle time	2000			ns
twh(Sclk)	Serial I/O2 clock input "H" pulse width	950			ns
twl(Sclk)	Serial I/O2 clock input "L" pulse width	950			ns
tsu(SCLK-SDATA)	Serial I/O2 input set up time	400			ns
th(SCLK-SDATA)	Serial I/O2 input hold time	400			ns

3.1 Electrical characteristics

(6) Switching characteristics (Extended operating temperature version)

Table 3.1.17 Switching characteristics (1)

(Vcc = 4.0 to 5.5 V, Vss = 0 V, Ta = -40 to 85 °C, unless otherwise noted)

Cumbal	Parameter	Li		Unit	
Symbol	Parameter	Min.	Тур.	Max.	Uniii
twh(Sclk)	Serial I/O2 clock output "H" pulse width	tc(Sclk)/2-30			ns
twL(ScLK)	Serial I/O2 clock output "L" pulse width	tc(Sclk)/2-30			ns
td(SCLK-SDATA)	Serial I/O2 output delay time			140	ns
tv(SCLK-SDATA)	Serial I/O2 output valid time	0			ns
tr(SCLK)	Serial I/O2 clock output rising time			30	ns
tf(SCLK)	Serial I/O2 clock output falling time			30	ns
tr(CMOS)	CMOS output rising time (Note 1)		10	30	ns
tf(CMOS)	CMOS output falling time (Note 1)		10	30	ns

Note 1: Pin XouT is excluded.

Table 3.1.18 Switching characteristics (2)

(Vcc = 2.4 to 5.5 V, Vss = 0 V, Ta = -40 to 85 °C, unless otherwise noted)

Comphal	Parameter -	Lii		l lait	
Symbol	Parameter	Min.	Тур.	Max.	Unit
twh(Sclk)	Serial I/O2 clock output "H" pulse width	tc(Sclk)/2-50			ns
twL(Sclk)	Serial I/O2 clock output "L" pulse width	tc(ScLK)/2-50			ns
td(SCLK-SDATA)	Serial I/O2 output delay time			350	ns
tv(SCLK-SDATA)	Serial I/O2 output valid time	0			ns
tr(SCLK)	Serial I/O2 clock output rising time			50	ns
tf(SCLK)	Serial I/O2 clock output falling time			50	ns
tr(CMOS)	CMOS output rising time (Note 1)		20	50	ns
tf(CMOS)	CMOS output falling time (Note 1)		20	50	ns

Note 1: Pin XouT is excluded.

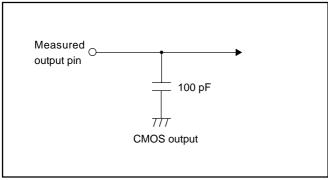


Fig. 3.1.3 Switching characteristics measurement circuit diagram (Extended operating temperature version)

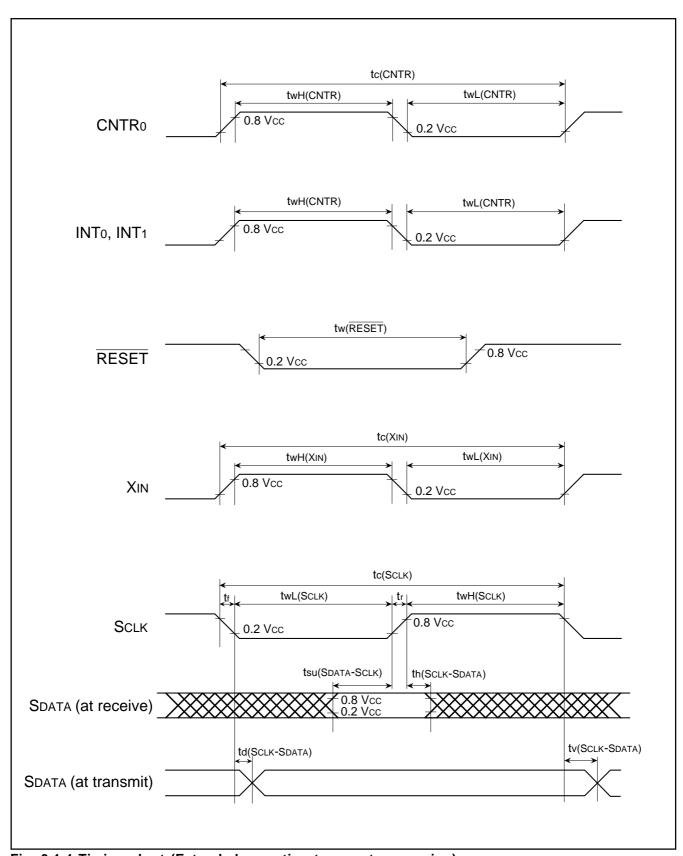


Fig. 3.1.4 Timing chart (Extended operating temperature version)

3.1 Electrical characteristics

3.1.3 7531 Group (Extended operating temperature 125 °C version)

Applied to: M37531M4V-XXXGP, M37531E4V-XXXGP

(1) Absolute maximum ratings (Extended operating temperature 125 °C version)

Table 3.1.19 Absolute maximum ratings

Symbol		Parameter	Conditions	Ratings	Unit
Vcc	Power source volta	age		-0.3 to 7.0	V
Vı	Input voltage	P00-P07, P10-P14, P20-P25, P30-P34, P37, VREF	All voltages are	-0.3 to Vcc + 0.3	V
VI	Input voltage	RESET, XIN	based on Vss.	-0.3 to VCC + 0.3	V
Vı	Input voltage	CNVss (Note 1)	Output transistors are cut off.	-0.3 to 13	V
Vo	Output voltage	P00–P07, P10–P14, P20–P25, P30–P34, P37, XOUT		-0.3 to Vcc + 0.3	V
Pd	Power dissipation		Ta = 25°C	200	mW
Topr	Operating temperature (Note 2)			-40 to 125	°C
Tstg	Storage temperature			-65 to 150	°C

Notes 1: It is a rating only for the One Time PROM version. Connect to Vss for the mask ROM version.

2: The total time is limited as follows: 6000 hours at 55 to 85 °C, 1000 hours at 85 to 125 °C

(2) Recommended operating conditions (Extended operating temperature 125 °C version)

Table 3.1.20 Recommended operating conditions (1)

(Vcc = 2.4 to 5.5 V, Ta = -40 to 125 °C, unless otherwise noted)

0		Parameter		Limits		Unit
Symbol		Parameter	Min.	Тур.	Max.	Unit
Vcc	Power source voltage (ceramic)	f(XIN) = 8 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
		f(XIN) = 4 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
		f(XIN) = 4 MHz (Double-speed mode)	4.0	5.0	5.5	V
		f(XIN) = 2 MHz (Double-speed mode)	2.4	5.0	5.5	V
	Power source voltage (CR)	f(XIN) = 4 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
		f(XIN) = 2 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
Vss	Power source voltage			0		V
VREF	Analog reference voltage	2.0		Vcc	V	
VIH	"H" input voltage	P00-P07, P10-P14, P20-P25, P30-P34, P37	0.8Vcc		Vcc	V
VIH	"H" input voltage (TTL input level selected)	P10, P12, P13, P37 (Note 1)			Vcc	V
VIH	"H" input voltage	RESET, XIN			Vcc	V
VIL	"L" input voltage	P00-P07, P10-P14, P20-P25, P30-P34, P37			0.3Vcc	V
VIL	"L" input voltage (TTL input level selected)	P10, P12, P13, P37 (Note 1)			0.8	V
VIL	"L" input voltage	RESET, CNVss	0		0.2Vcc	V
VIL	"L" input voltage	XIN	0		0.16Vcc	V
\sum IOH(peak)	"H" total peak output current (Note 2)	P00–P07, P10–P14, P20–P25, P30–P34, P37			-80	mA
∑IOL(peak)	"L" total peak output current (Note 2)	P00–P07, P10–P14, P20–P25, P37			80	mA
∑IOL(peak)	"L" total peak output current (Note 2)	P30–P34			60	mA
\sum IOH(avg)	"H" total average output current (Note 2)	current P00-P07, P10-P14, P20-P25, P30-P34, P37			-40	mA
\sum IOL(avg)	"L" total average output current (Note 2)	P00–P07, P10–P14, P20–P25, P37			40	mA
∑lOL(avg)	"L" total average output current (Note 2)	P30-P34			30	mA

Note 1: Vcc = 4.0 to 5.5V

^{2:} The total output current is the sum of all the currents flowing through all the applicable ports. The total average current is an average value measured over 100 ms. The total peak current is the peak value of all the currents.

3.1 Electrical characteristics

Table 3.1.21 Recommended operating conditions (2) (Vcc = 2.4 to 5.5 V, Ta = -40 to 125 °C, unless otherwise noted)

Cumbal	Parameter			Limits		Unit
Symbol	Parameter		Min.	Тур.	Max.	Onit
IOH(peak)	"H" peak output current (Note 1) P00-P0	7, P10–P14, P20–P25, P30–P34, P37			-10	mA
IOL(peak)	"L" peak output current (Note 1) P00-P0	L" peak output current (Note 1) P00–P07, P10–P14, P20–P25, P37			10	mA
IOL(peak)	"L" peak output current (Note 1) P30-P3			30	mA	
IOH(avg)	"H" average output current (Note 2) P00-P0			-5	mA	
IOL(avg)	"L" average output current (Note 2) P00-P0			5	mA	
IOL(avg)	"L" average output current (Note 2) P30-P3			15	mA	
f(XIN)	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 4.0 to 5.5 V Double-speed mode			4	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 2.4 to 5.5 V Double-speed mode			2	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 4.0 to 5.5 V High-, Middle-speed mode			8	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 2.4 to 5.5 V High-, Middle-speed mode			4	MHz
	Oscillation frequency (Note 3) at RC oscillation	Vcc = 4.0 to 5.5 V High-, Middle-speed mode			4	MHz
	Oscillation frequency (Note 3) at RC oscillation	Vcc = 2.4 to 5.5 V High-, Middle-speed mode			2	MHz

Notes 1: The peak output current is the peak current flowing in each port.

^{2:} The average output current IoL (avg), IoH (avg) in an average value measured over 100 ms.

3: When the oscillation frequency has a duty cycle of 50 %.

(3) Electrical characteristics (Extended operating temperature 125 °C version)

Table 3.1.22 Electrical characteristics

(Vcc = 2.4 to 5.5 V, Vss = 0 V, Ta = -40 to 125 °C, unless otherwise noted)

0		_		- .	11.0		Limits		Unit
Symbol		Para	ameter	l est c	onditions	Min.	Тур.	Max.	Unit
Voн	"H" output voltage		207, P10–P14, P20–P25, 234, P37 (Note 1)	IOH = -5 m VCC = 4.0		Vcc-1.5			V
				IOH = -1.0 VCC = 2.4		Vcc-1.0			V
VoL	"L" output voltage	P00-F P37	207, P10–P14, P20–P25,	IOL = 5 mA VCC = 4.0				1.5	V
				IOL = 1.5 n VCC = 4.0				0.3	V
				IOL = 1.0 m VCC = 2.4				1.0	V
Vol	"L" output voltage	"L" output voltage P30-P34		IOL = 15 m VCC = 4.0				2.0	V
				IOL = 1.5 n VCC = 4.0				0.3	V
				IOL = 10 m VCC = 2.4				1.0	V
VT+-VT-	Hysteresis		o, INTo, (Note 2) 207 (Note 3)				0.4		V
VT+-VT-	Hysteresis	RxD,	SCLK, SDATA (Note 2)				0.5		V
VT+-VT-	Hysteresis	RESE	Т				0.5		V
Іін	"H" input current		907, P10–P14, P20–P25, 934, P37	VI = VCC (Pin floating. Pull up transistors "off")				5.0	μA
lін	"H" input current	RESE	T	VI = VCC				5.0	μA
lін	"H" input current	XIN		VI = VCC			4.0		μA
lıL	"L" input current		707, P10–P14, P20–P25, P34, P37	VI = VSS (Pin floating transistors				-5.0	μA
lıL	"L" input current	RESE	T, CNVss	VI = VSS	·			-5.0	μA
lıL	"L" input current	XIN		VI = VSS			-4.0		μA
lıL	"L" input current	P00-F	07, P30–P34, P37	Vı = Vss (Pull up trai	nsistors "on")		-0.2	-0.5	mA
VRAM	RAM hold voltage			When cloc	ck stopped	2.0		5.5	V
Icc	Power source curr	ent	High-speed mode, f(XIN) = Output transistors "off"	8 MHz			5.0	8.0	mA
			High-speed mode, f(XIN) = Output transistors "off"	2 MHz, Vcc	= 2.4 V		0.5	1.5	mA
			Double-speed mode, f(XIN) Output transistors "off"	= 4 MHz			5.0	8.0	mA
			Middle-speed mode, f(XIN) Output transistors "off"	= 8 MHz,			2.0	5.0	mA
		f(XIN) = 8 MHz (in WIT state Functions except Timer 1 a Output transistors "off"			stop		1.6	3.2	mA
			f(XIN) = 2 MHz, Vcc = 2.4 \ Output transistors "off"	/ (in WIT sta	te)		0.2		mA
	Increment when A-D convertion of the first state of		ersion is exec	cuted		0.5		mA	
		All oscillation stopped (ir Output transistors "off"		All oscillation stopped (in STP state) Output transistors "off" $Ta = 25 \text{ °C}$ $Ta = 125 \text{ °C}$			0.1	1.0	μA
								50	μA

Notes 1: P11 is measured when the P11/TxD P-channel output disable bit of the UART control register (bit 4 of address 001B16) is "0".

^{2:} RXD, SCLK, SDATA, and INTo have hysteresises only when bits 0 to 2 of the port P1P3 control register are set to "0" (CMOS level).

^{3:} It is available only when operating key-on wake up.

3.1 Electrical characteristics

(4) A-D converter characteristics (Extended operating temperature 125 °C version)

Table 3.1.23 A-D Converter characteristics

(Vcc = 2.7 to 5.5 V, Vss = 0 V, Ta = -40 to 125 °C, unless otherwise noted)

Cumbal	Doromotor	Toot conditions		Limits			
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit	
_	Resolution				10	Bits	
_	Linearity error	Vcc = 2.7 to 5.5 V Ta = 25 °C			±3	LSB	
_	Differential nonlinear error	Vcc = 2.7 to 5.5 V Ta = 25 °C			±0.9	LSB	
Vот	Zero transition voltage	VCC = VREF = 5.12 V	0	5	20	mV	
		VCC = VREF = 3.072 V	0	3	15	mV	
VFST	Full scale transition voltage	VCC = VREF = 5.12 V	5105	5115	5125	mV	
		VCC = VREF = 3.072 V	3060	3069	3075	mV	
tCONV	Conversion time				122	tc(XIN)	
RLADDER	Ladder resistor			55		kΩ	
IVREF	Reference power source input current	VREF = 5.0 V	50	150	200	μA	
		VREF = 3.0 V	30	70	120	μΛ	
II(AD)	A-D port input current				5.0	μA	

(5) Timing requirements (Extended operating temperature 125 °C version)

Table 3.1.24 Timing requirements (1)

(Vcc = 4.0 to 5.5 V, Vss = 0 V, Ta = -40 to 125 °C, unless otherwise noted)

Symbol	Parameter		1.1-21		
		Min.	Тур.	Max.	Unit
tw(RESET)	Reset input "L" pulse width	15			μs
tc(XIN)	External clock input cycle time	125			ns
twh(XIN)	External clock input "H" pulse width	50			ns
twl(XIN)	External clock input "L" pulse width	50			ns
tc(CNTR)	CNTR ₀ input cycle time	200			ns
twn(CNTR)	CNTRo, INTo input "H" pulse width	80			ns
twL(CNTR)	CNTRo, INTo input "L" pulse width	80			ns
tc(Sclk)	Serial I/O2 clock input cycle time	1000			ns
twh(Sclk)	Serial I/O2 clock input "H" pulse width	400			ns
twL(ScLK)	Serial I/O2 clock input "L" pulse width	400			ns
tsu(SCLK-SDATA)	Serial I/O2 input set up time	200			ns
th(SCLK-SDATA)	Serial I/O2 input hold time	200			ns

Table 3.1.25 Timing requirements (2)

(Vcc = 2.4 to 5.5 V, Vss = 0 V, Ta = -40 to 125 °C, unless otherwise noted)

Symbol	Parameter				
		Min.	Тур.	Max.	Unit
tw(RESET)	Reset input "L" pulse width	35			μs
tc(XIN)	External clock input cycle time	250			ns
twh(XIN)	External clock input "H" pulse width	100			ns
twl(XIN)	External clock input "L" pulse width	100			ns
tc(CNTR)	CNTR ₀ input cycle time	500			ns
twh(CNTR)	CNTR ₀ , INT ₀ , input "H" pulse width	230			ns
twL(CNTR)	CNTR ₀ , INT ₀ , input "L" pulse width	230			ns
tc(Sclk)	Serial I/O2 clock input cycle time	2000			ns
twh(Sclk)	Serial I/O2 clock input "H" pulse width	950			ns
twl(Sclk)	Serial I/O2 clock input "L" pulse width	950			ns
tsu(SCLK-SDATA)	Serial I/O2 input set up time	400			ns
th(SCLK-SDATA)	Serial I/O2 input hold time	400			ns

3.1 Electrical characteristics

(6) Switching characteristics (Extended operating temperature 125 °C version)

Table 3.1.26 Switching characteristics (1)

(Vcc = 4.0 to 5.5 V, Vss = 0 V, Ta = -40 to 125 °C, unless otherwise noted)

Symbol	Parameter	Li	Linit		
		Min.	Тур.	Max.	Unit
twh(Sclk)	Serial I/O2 clock output "H" pulse width	tc(ScLK)/2-50			ns
twL(Sclk)	Serial I/O2 clock output "L" pulse width	tc(Sclk)/2-50			ns
td(SCLK-SDATA)	Serial I/O2 output delay time			200	ns
tv(SCLK-SDATA)	Serial I/O2 output valid time	0			ns
tr(SCLK)	Serial I/O2 clock output rising time			50	ns
tf(SCLK)	Serial I/O2 clock output falling time			50	ns
tr(CMOS)	CMOS output rising time (Note 1)		10	50	ns
tf(CMOS)	CMOS output falling time (Note 1)		10	50	ns

Note 1: Pin XOUT is excluded.

Table 3.1.27 Switching characteristics (2)

(Vcc = 2.4 to 5.5 V, Vss = 0 V, Ta = -40 to 125 °C, unless otherwise noted)

Symbol	Parameter	Li	Lloit		
		Min.	Тур.	Max.	Unit
twh(Sclk)	Serial I/O2 clock output "H" pulse width	tc(Sclk)/2-80			ns
twL(ScLK)	Serial I/O2 clock output "L" pulse width	tc(Sclk)/2-80			ns
td(SCLK-SDATA)	Serial I/O2 output delay time			400	ns
tv(SCLK-SDATA)	Serial I/O2 output valid time	0			ns
tr(SCLK)	Serial I/O2 clock output rising time			80	ns
tf(SCLK)	Serial I/O2 clock output falling time			80	ns
tr(CMOS)	CMOS output rising time (Note 1)		20	80	ns
tf(CMOS)	CMOS output falling time (Note 1)		20	80	ns

Note 1: Pin Xout is excluded.

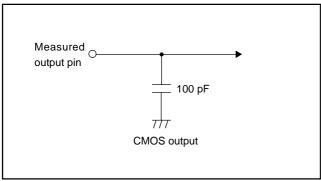


Fig. 3.1.5 Switching characteristics measurement circuit diagram (Extended operating temperature 125 °C version)

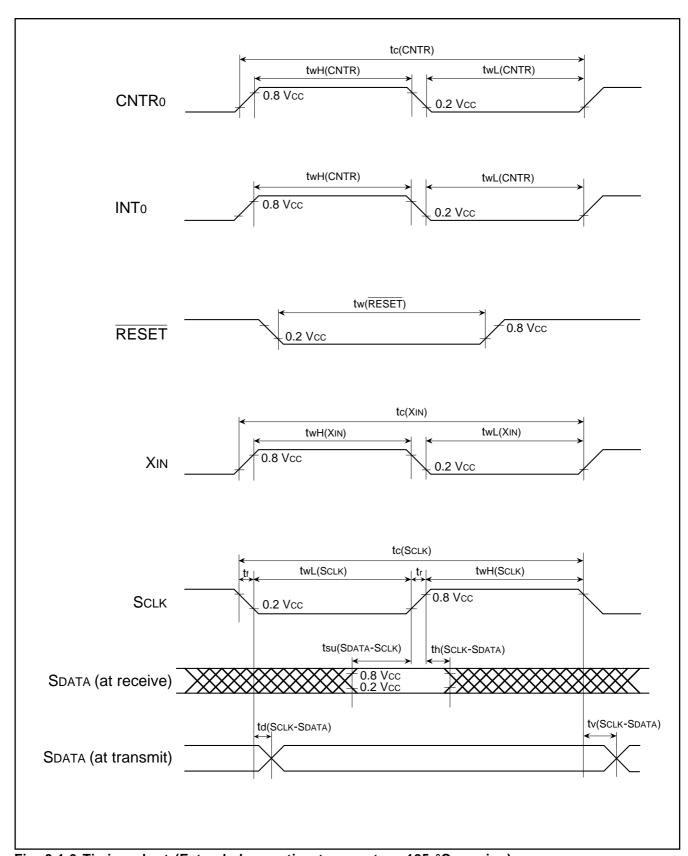


Fig. 3.1.6 Timing chart (Extended operating temperature 125 °C version)

3.2 Typical characteristics

3.2 Typical characteristics

3.2.1 Power source current characteristic example (Icc-Vcc characteristic)

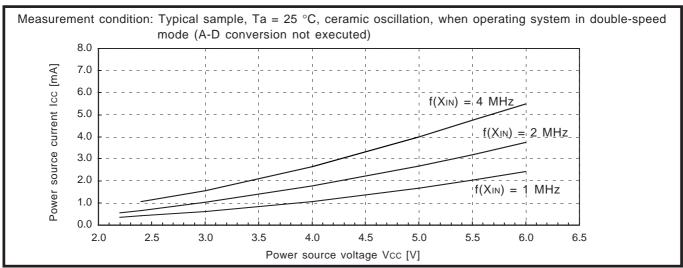


Fig. 3.2.1 Icc-Vcc characteristic example (in double-speed mode)

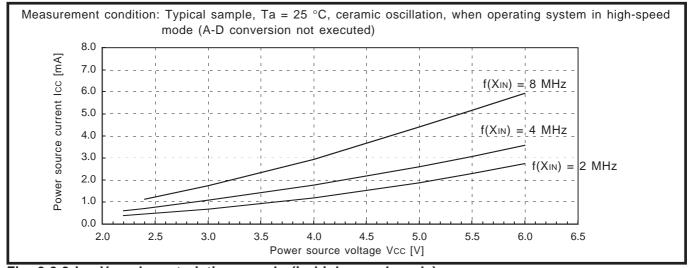


Fig. 3.2.2 Icc-Vcc characteristic example (in high-speed mode)

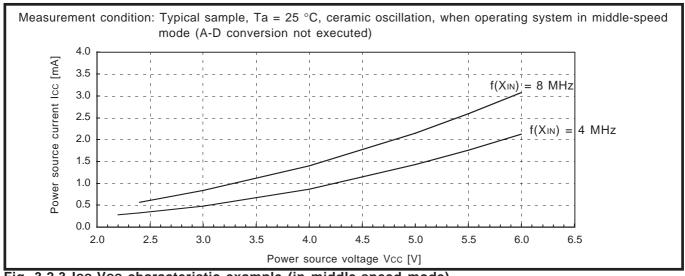


Fig. 3.2.3 Icc-Vcc characteristic example (in middle-speed mode)

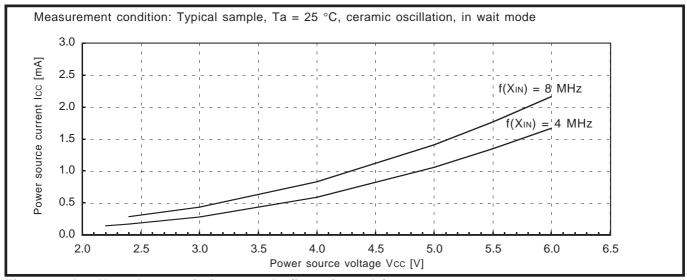


Fig. 3.2.4 Icc-Vcc characteristic example (in wait mode)

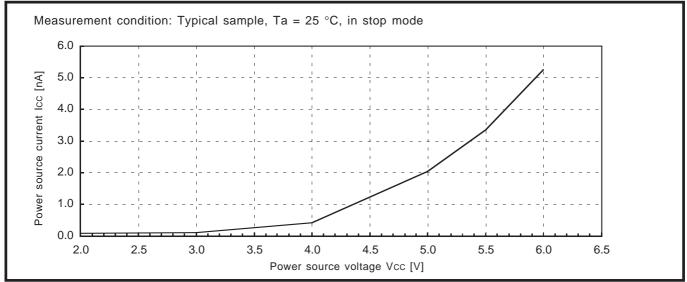


Fig. 3.2.5 Icc-Vcc characteristic example (in stop mode)

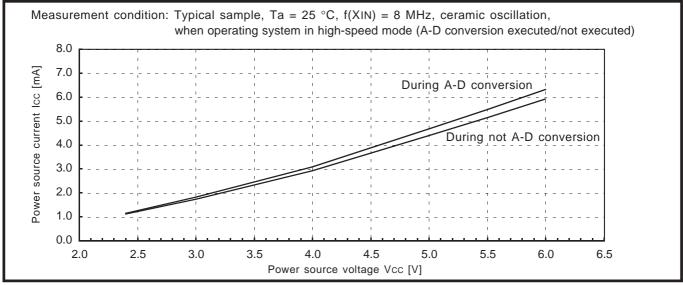


Fig. 3.2.6 Icc-Vcc characteristic example (addition when operating A-D conversion, A-D conversion executed/not executed, f(XIN) = 8MHz, in high-speed mode)

3.2 Typical characteristics

3.2.2 Power source current frequency characteristic example (ICC-f(XIN) characteristic)

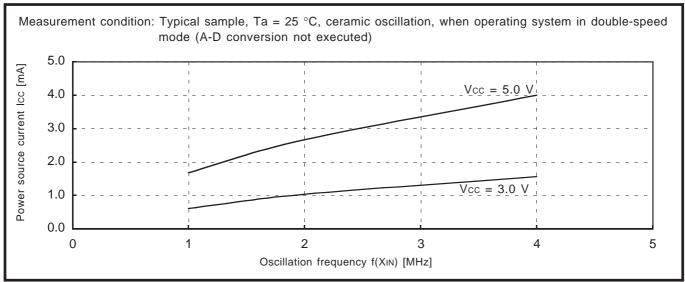


Fig. 3.2.7 Icc-f(XIN) characteristic example (in double-speed mode)

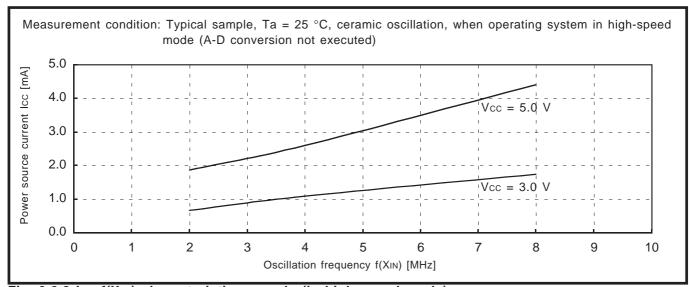
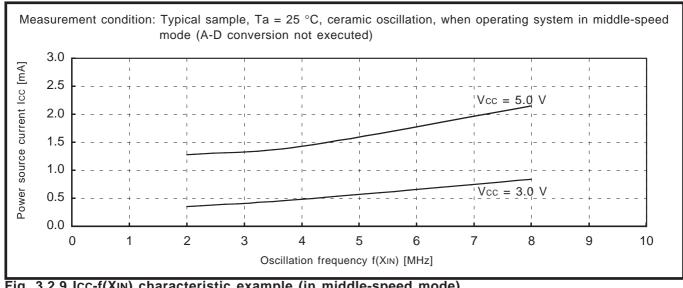


Fig. 3.2.8 Icc-f(XIN) characteristic example (in high-speed mode)



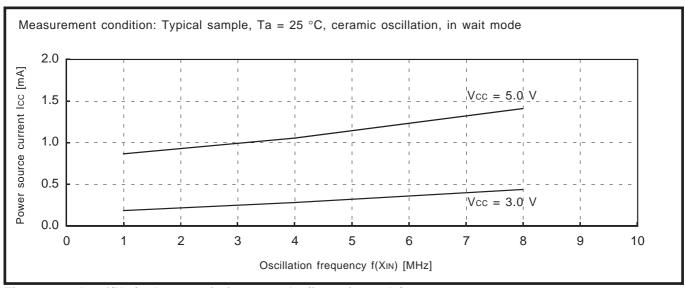


Fig. 3.2.10 Icc-f(XIN) characteristic example (in wait mode)

3.2 Typical characteristics

3.2.3 Port typical characteristic example

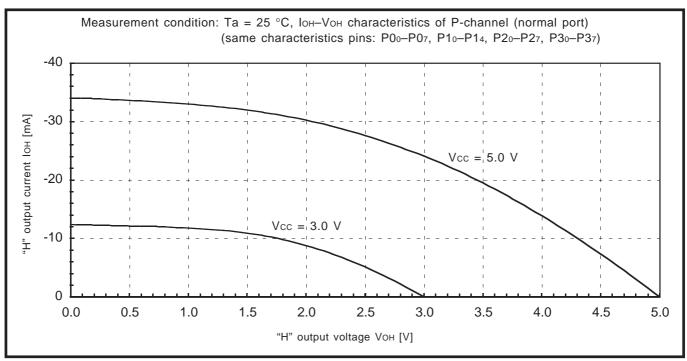


Fig. 3.2.11 Voн-loн characteristic example of P-channel (Ta = 25 °C): normal port

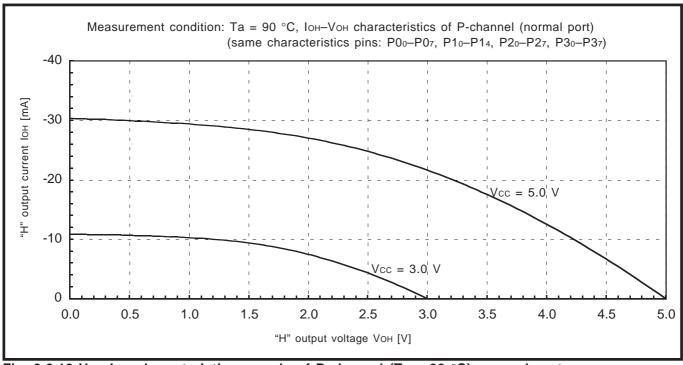


Fig. 3.2.12 Voн-loн characteristic example of P-channel (Ta = 90 °C): normal port

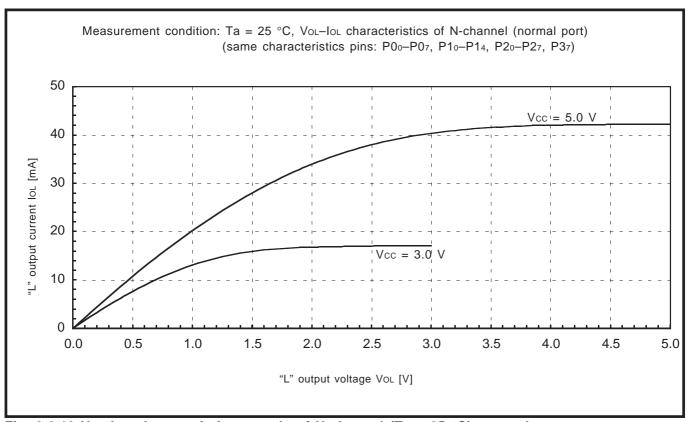


Fig. 3.2.13 Vol-lol characteristic example of N-channel (Ta = 25 °C): normal port

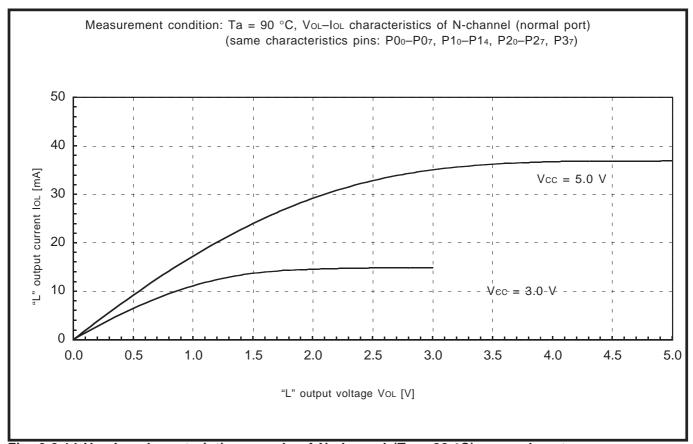


Fig. 3.2.14 Vol-lol characteristic example of N-channel (Ta = 90 °C): normal port

3.2 Typical characteristics

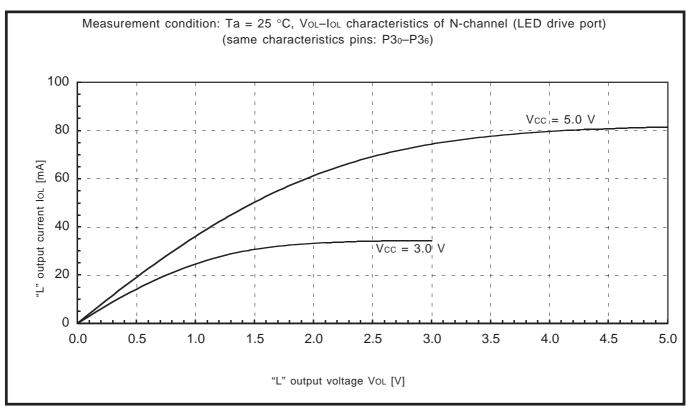


Fig. 3.2.15 Vol-lol characteristic example of N-channel (Ta = 25 $^{\circ}$ C): LED drive port

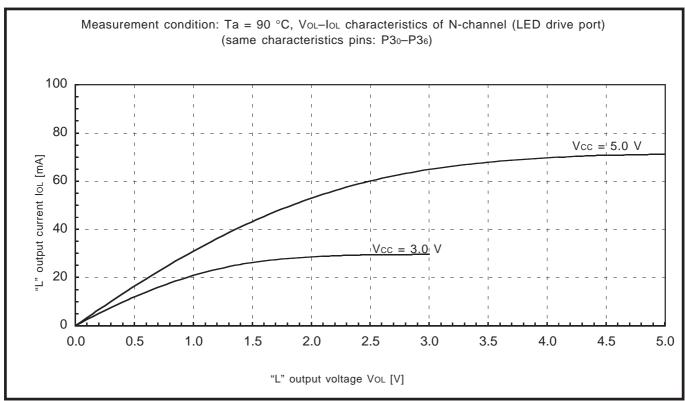


Fig. 3.2.16 Vol-lol characteristic example of N-channel (Ta = 90 °C): LED drive port

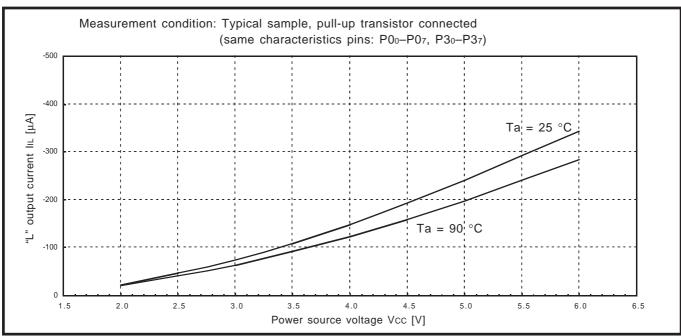
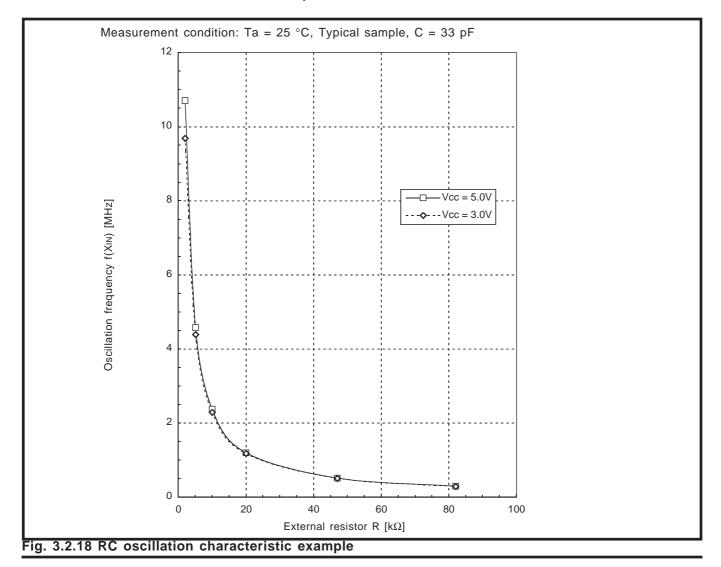


Fig. 3.2.17 "L" input current when connecting pull-up transistor

3.2.4 RC oscillation characteristic example



3.2 Typical characteristics

3.2.5 A-D conversion typical characteristic example

(1) Definition of A-D conversion accuracy

The A-D conversion accuracy is defined below (refer to Fig. 3.2.14).

Relative accuracy

- ① Zero transition voltage (Vo_T)
 - This means an analog input voltage when the actual A-D conversion output data changes from "0" to "1."
- ② Full-scale transition voltage (V_{FST})
 - This means an analog input voltage when the actual A-D conversion output data changes from "1023" to "1022."
- 3 Linearity error
 - This means a deviation from the line between V_{OT} and V_{FST} of a converted value between V_{OT} and V_{FST} .
- 4 Differential non-linearity error
 - This means a deviation from the input potential difference required to change a converted value between Vot and Vfst by 1 LSB of the 1 LSB at the relative accuracy.

Absolute accuracy

This means a deviation from the ideal characteristics between 0 to VREF of actual A-D conversion characteristics.

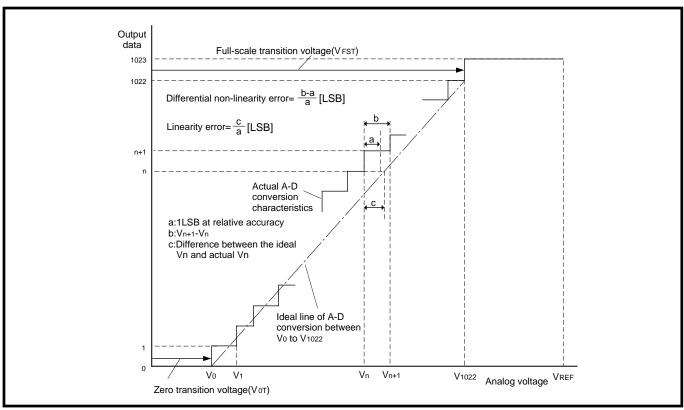


Fig. 3.2.19 Definition of A-D conversion accuracy

Vn: Analog input voltage when the output data changes from "n" to "n + 1" (n = 0 to 1022)

- 1 LSB at relative accuracy $\rightarrow \frac{V_{FST} V_{OT}}{1022}$ (V)
- 1 LSB at absolute accuracy $\rightarrow \frac{V_{REF}}{1024}$ (V)

(2) A-D conversion accuracy characteristic example-1

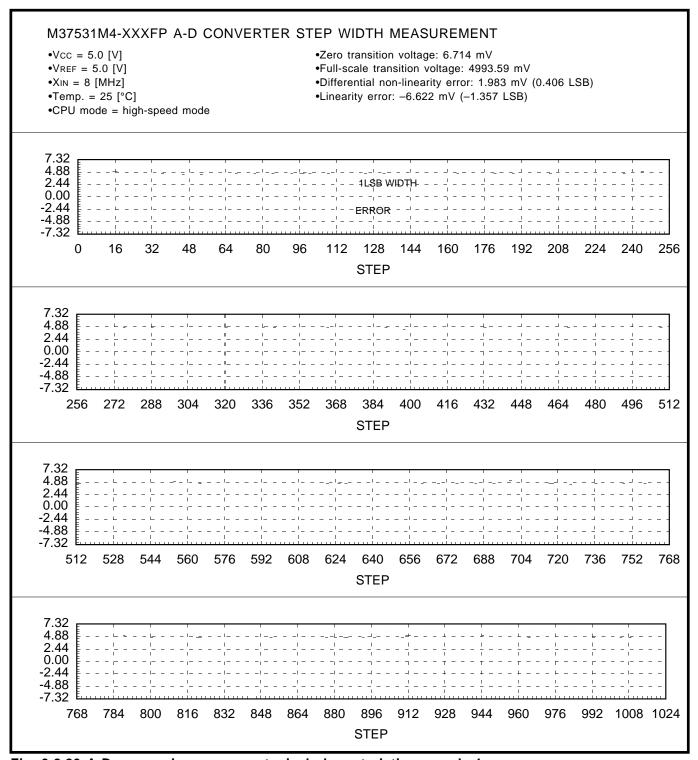


Fig. 3.2.20 A-D conversion accuracy typical characteristic example-1

3.2 Typical characteristics

(3) A-D conversion accuracy characteristic example-2

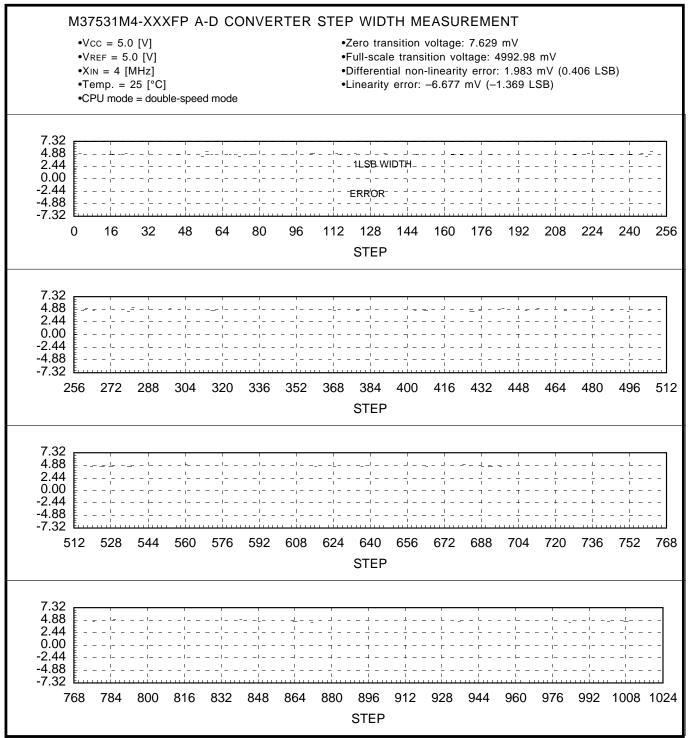


Fig. 3.2.21 A-D conversion accuracy typical characteristic example-2

3.3 Notes on use

3.3.1 Notes on interrupts

(1) Setting of interrupt request bit and interrupt enable bit

To set an interrupt request bit and an interrupt enable bit for interrupts, execute as the following sequence :

- ① Clear an interrupt request bit to "0" (no interrupt request issued).
- ② Set an interrupt enable bit to "1" (interrupts enabled).

Reason

If the above setting ①, ② are performed simultaneously with one instruction, an unnecessary interrupt processing routine is executed. Because an interrupt enable bit is set to "1" (interrupts enabled) before an interrupt request bit is cleared to "0".

(2) Switching external interrupt detection edge

For the products able to switch the external interrupt detection edge, switch it as the following sequence.

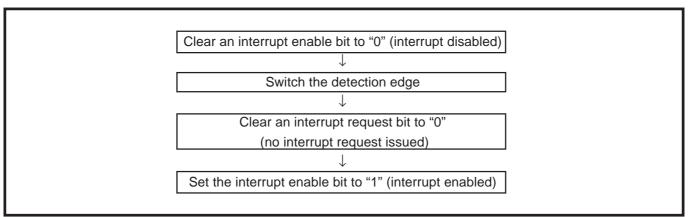


Fig. 3.3.1 Sequence of switch the detection edge

Reason

The interrupt circuit recognizes the switching of the detection edge as the change of external input signals. This may cause an unnecessary interrupt.

(3) Check of interrupt request bit

When executing the **BBC** or **BBS** instruction to an interrupt request bit of an interrupt request register immediately after this bit is set to "0" by using a data transfer instruction, execute one or more instructions before executing the **BBC** or **BBS** instruction.

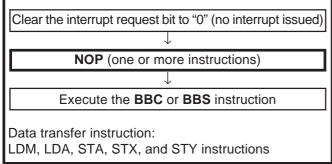


Fig. 3.3.2 Seguence of check of interrupt request bit

Reason

If the **BBC** or **BBS** instruction is executed immediately after an interrupt request bit of an interrupt request register is cleared to "0", the value of the interrupt request bit before being cleared to "0" is read.

3.3 Notes on use

(4) Structure of interrupt control register 1

Fix the bit 7 of the interrupt control register 1 to "0". Figure 3.3.3 shows the structure of the interrupt control register 1.

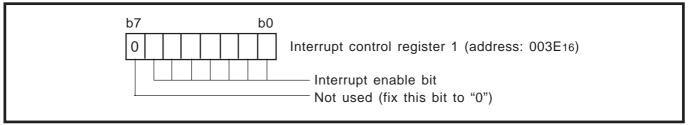


Fig. 3.3.3 Structure of interrupt control register 1

3.3.2 Notes on serial I/O

(1) Handling of serial I/O1 clear

When serial I/O1 is set again or the transmit/receive operation is stopped/restarted while serial I/O1 is operating, clear the serial I/O1 as shown in Figure 3.3.4.

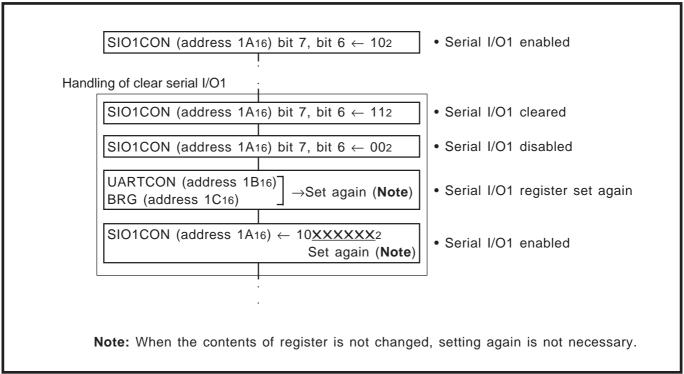


Fig. 3.3.4 Sequence of clearing serial I/O

(2) Data transmission control with referring to transmit shift register completion flag

The transmit shift register completion flag changes from "1" to "0" with a delay of 0.5 to 1.5 shift clocks. When data transmission is controlled with referring to the flag after writing the data to the transmit buffer register, note the delay.

(3) Writing transmit data

When an external clock is used as the synchronous clock for the clock synchronous serial I/O, write the transmit data to the transmit buffer register (serial I/O shift register) at "H" of the transfer clock input level.

(4) Serial I/O2 transmit/receive shift completion flag

- •The transmit/receive shift completion flag of the serial I/O2 control register is set to "1" after completing transmit/receive shift. In order to set this flag to "0", write data (dummy data at reception) to the serial I/O2 register by program.
- •Bit 7 of the serial I/O2 control register is set to "1" a half cycle (of the shift clock) earlier than completion of shift operation. Accordingly, when using this bit to confirm shift completion, a half cycle or more of the shift clock must pass after confirming that this bit is set to "1", before performing read/write to the serial I/O2 register.

3.3.3 Notes on A-D converter

(1) Analog input pin

Make the signal source impedance for analog input low, or equip an analog input pin with an external capacitor of $0.01\mu\text{F}$ to $1\mu\text{F}$. Further, be sure to verify the operation of application products on the user side.

Reason

An analog input pin includes the capacitor for analog voltage comparison. Accordingly, when signals from signal source with high impedance are input to an analog input pin, charge and discharge noise generates. This may cause the A-D conversion precision to be worse.

(2) Clock frequency during A-D conversion

The comparator consists of a capacity coupling, and a charge of the capacity will be lost if the clock frequency is too low. Thus, make sure the following during an A-D conversion.

- f(XIN) is 500 kHz or more
- Do not execute the STP instruction

3.3.4 Notes on RESET pin

(1) Connecting capacitor

In case where the $\overline{\text{RESET}}$ signal rise time is long, connect a ceramic capacitor or others across the $\overline{\text{RESET}}$ pin and the Vss pin. And use a 1000 pF or more capacitor for high frequency use. When connecting the capacitor, note the following :

- Make the length of the wiring which is connected to a capacitor as short as possible.
- Be sure to verify the operation of application products on the user side.

Reason

If the several nanosecond or several ten nanosecond impulse noise enters the $\overline{\text{RESET}}$ pin, it may cause a microcomputer failure.

3.3 Notes on use

3.3.5 Notes on input and output pins

(1) Notes in stand-by state

In stand-by state*1 for low-power dissipation, do not make input levels of an input port and an I/O port "undefined".

Pull-up (connect the port to Vcc) or pull-down (connect the port to Vss) these ports through a resistor.

When determining a resistance value, note the following points:

- External circuit
- Variation of output levels during the ordinary operation

When using built-in pull-up or pull-down resistor, note on varied current values:

- When setting as an input port : Fix its input level
- When setting as an output port : Prevent current from flowing out to external

Reason

The output transistor becomes the OFF state, which causes the ports to be the high-impedance state. Note that the level becomes "undefined" depending on external circuits.

Accordingly, the potential which is input to the input buffer in a microcomputer is unstable in the state that input levels of a input port and an I/O port are "undefined". This may cause power source current.

*1 stand-by state : the stop mode by executing the **STP** instruction the wait mode by executing the **WIT** instruction

(2) Modifying output data with bit managing instruction

When the port latch of an I/O port is modified with the bit managing instruction*2, the value of the unspecified bit may be changed.

Reason

The bit managing instructions are read-modify-write form instructions for reading and writing data by a byte unit. Accordingly, when these instructions are executed on a bit of the port latch of an I/O port, the following is executed to all bits of the port latch.

- As for a bit which is set for an input port :
 - The pin state is read in the CPU, and is written to this bit after bit managing.
- As for a bit which is set for an output port :

The bit value of the port latch is read in the CPU, and is written to this bit after bit managing.

Note the following:

- Even when a port which is set as an output port is changed for an input port, its port latch holds the output data.
- As for a bit of the port latch which is set for an input port, its value may be changed even when not specified with a bit managing instruction in case where the pin state differs from its port latch contents.

^{*2} bit managing instructions: SEB, and CLB instructions

3.3.6 Notes on programming

(1) Processor status register

① Initializing of processor status register

Flags which affect program execution must be initialized after a reset.

In particular, it is essential to initialize the T and D flags because they have an important effect on calculations.

Reason

After a reset, the contents of the processor status register (PS) are undefined except for the I flag which is "1".

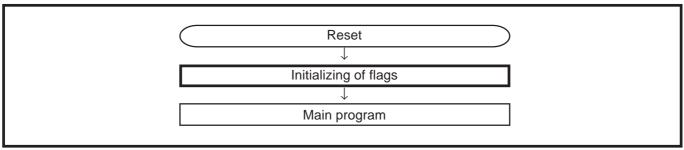


Fig. 3.3.5 Initialization of processor status register

2 How to reference the processor status register

To reference the contents of the processor status register (PS), execute the **PHP** instruction once then read the contents of (S+1). If necessary, execute the **PLP** instruction to return the PS to its original status.

A NOP instruction should be executed after every PLP instruction.

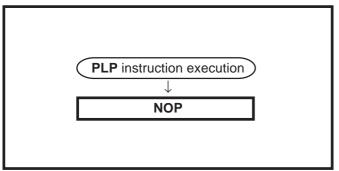


Fig. 3.3.6 Sequence of PLP instruction execution

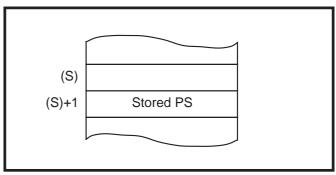


Fig. 3.3.7 Stack memory contents after PHP instruction execution

3.3 Notes on use

(2) Decimal calculations

1 Execution of decimal calculations

The **ADC** and **SBC** are the only instructions which will yield proper decimal notation, set the decimal mode flag (D) to "1" with the **SED** instruction. After executing the **ADC** or **SBC** instruction, execute another instruction before executing the **SEC**, **CLC**, or **CLD** instruction.

2 Notes on status flag in decimal mode

When decimal mode is selected, the values of three of the flags in the status register (the N, V, and Z flags) are invalid after a **ADC** or **SBC** instruction is executed.

The carry flag (C) is set to "1" if a carry is generated as a result of the calculation, or is cleared to "0" if a borrow is generated. To determine whether a calculation has generated a carry, the C flag must be initialized to "0" before each calculation. To check for a borrow, the C flag must be initialized to "1" before each calculation.

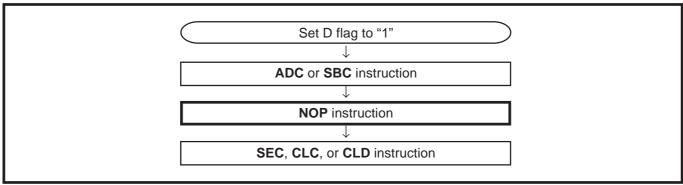


Fig. 3.3.8 Status flag at decimal calculations

(3) JMP instruction

When using the **JMP** instruction in indirect addressing mode, do not specify the last address on a page as an indirect address.

3.3.7 Programming and test of built-in PROM version

As for in the One Time PROM version (shipped in blank), its built-in PROM can be read or programmed with a general-purpose PROM programmer using a special programming adapter.

The built-in EPROM version is available only for program development and on-chip program evaluation. The programming test and screening for PROM of the One Time PROM version (shipped in blank) are not performed in the assembly process and the following processes. To ensure reliability after programming, performing programming and test according to the Figure 3.3.9 before actual use are recommended.

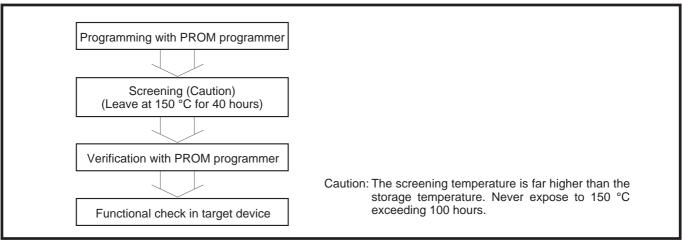


Fig. 3.3.9 Programming and testing of One Time PROM version

3.3.8 Notes on built-in PROM version

(1) Programming adapter

Use a special programming adapter shown in Table 3.3.1 and a general-purpose PROM programmer when reading from or programming to the built-in PROM in the built-in PROM version.

Table 3.3.1 Programming adapters

Microcomputer	Programming adapter	
M37531E4SP (One Time PROM version shipped in blank)	PCA7435SP	
M37531E8SP (One Time PROM version shipped in blank)	F CA74333F	
M37531E4FP (One Time PROM version shipped in blank) PCA7435F		
M37531E8FP (One Time PROM version shipped in blank)	- FOAT4331T	
M37531E4GP (One Time PROM version shipped in blank)	PCA7435GP	

3.3 Notes on use

(2) Programming/reading

In PROM mode, operation is the same as that of the M5M27C101AK, but programming conditions of PROM programmer are not set automatically because there are no internal device ID codes. Accurately set the following conditions for data programming /reading. Take care not to apply 21 V to VPP pin (is also used as the CNVss pin), or the product may be permanently damaged.

- Programming voltage: 12.5 V
- Setting of PROM programmer switch: refer to Table 3.3.2.

Table 3.3.2 PROM programmer address setting

Product name format	PROM programmer start address	PROM programmer end address	
M37531E4SP			
M37531E4FP	Address 0E08016 (Note 1)	Address 0FFFD16 (Note 1)	
M37531E4GP			
M37531E8SP	Address 0C08016 (Note 2)	Address 0FFFD16 (Note 2)	
M37531E8FP	/ tad. 333 3333 13 (11313 <u>2</u>)	7.00.000 0 2 . 0 (0.000 2)	

Notes 1: Addersses E08016 to FFFD16 in the built-in PROM corresponds to addresses 0E08016 to 0FFFD16 in the PROM programmer.

^{2:} Addersses C08016 to FFFD16 in the built-in PROM corresponds to addresses 0C08016 to 0FFFD16 in the PROM programmer.

3.3.9 Termination of unused pins

(1) Terminate unused pins

① Output ports : Open

2 Input ports:

Connect each pin to VCC or Vss through each resistor of 1 k Ω to 10 k Ω .

Ports that permit the selecting of a built-in pull-up or pull-down resistor can also use this resistor. As for pins whose potential affects to operation modes such as pins CNVss, INT or others, select the Vcc pin or the Vss pin according to their operation mode.

3 I/O ports:

• Set the I/O ports for the input mode and connect them to Vcc or Vss through each resistor of 1 k Ω to 10 k Ω .

Ports that permit the selecting of a built-in pull-up or pull-down resistor can also use this resistor. Set the I/O ports for the output mode and open them at "L" or "H".

- When opening them in the output mode, the input mode of the initial status remains until the
 mode of the ports is switched over to the output mode by the program after reset. Thus, the
 potential at these pins is undefined and the power source current may increase in the input
 mode. With regard to an effects on the system, thoroughly perform system evaluation on the user
 side.
- Since the direction register setup may be changed because of a program runaway or noise, set direction registers by program periodically to increase the reliability of program.

(2) Termination remarks

Input ports and I/O ports :Do not open in the input mode.

Reason

- The power source current may increase depending on the first-stage circuit.
- An effect due to noise may be easily produced as compared with proper termination ② and ③ shown on the above.

2 I/O ports:

When setting for the input mode, do not connect to VCC or VSS directly.

Reason

If the direction register setup changes for the output mode because of a program runaway or noise, a short circuit may occur between a port and Vcc (or Vss).

③ I/O ports :

When setting for the input mode, do not connect multiple ports in a lump to VCC or Vss through a resistor.

Reason

If the direction register setup changes for the output mode because of a program runaway or noise, a short circuit may occur between ports.

• At the termination of unused pins, perform wiring at the shortest possible distance (20 mm or less) from microcomputer pins.

3.3 Notes on use

3.3.10 Notes on CPU mode register

(1) Switching method of CPU mode register after releasing reset

Switch the CPU mode register (CPUM) at the head of program after releasing reset in the following method.

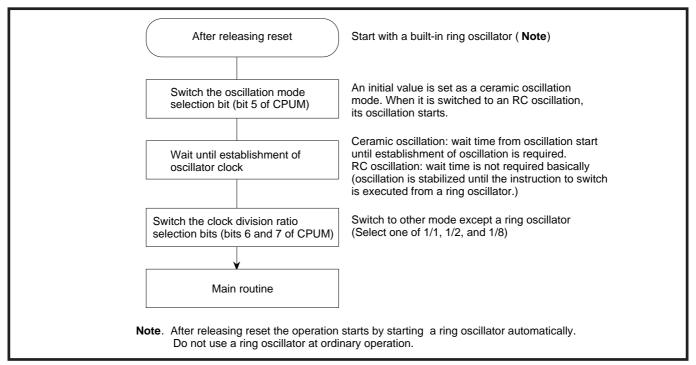


Fig. 3.3.10 Switching method of CPU mode register

(2) Oscillation mode selection bit and clock division ratio selection bits

The oscillation mode selection bit can be rewritten only once after releasing reset. However, after rewriting it is disable to write any value to the bit.

When a ceramic oscillation is selected, a double-speed mode of the clock division ratio selection bits can be used. Do not use it when an RC oscillation is selected.

3.3.11 Notes on using 32-pin version

- Do not change the P35, P36 pull-up control bit of the pull-up control register from the initial value "1".
- Do not write to "1" to the serial I/O1 or INT1 interrupt selection bit of the interrupt edge selection register.

3.4 Countermeasures against noise

3.4.1 Shortest wiring length

(1) Package

Select the smallest possible package to make the total wiring length short.

Reason

The wiring length depends on a microcomputer package. Use of a small package, for example QFP and not DIP, makes the total wiring length short to reduce influence of noise.

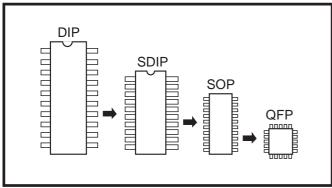


Fig. 3.4.1 Selection of packages

(2) Wiring for RESET pin

Make the length of wiring which is connected to the $\overline{\mathsf{RESET}}$ pin as short as possible. Especially, connect a capacitor across the $\overline{\mathsf{RESET}}$ pin and the Vss pin with the shortest possible wiring (within 20mm).

Reason

The width of a pulse input into the RESET pin is determined by the timing necessary conditions. If noise having a shorter pulse width than the standard is input to the RESET pin, the reset is released before the internal state of the microcomputer is completely initialized. This may cause a program runaway.

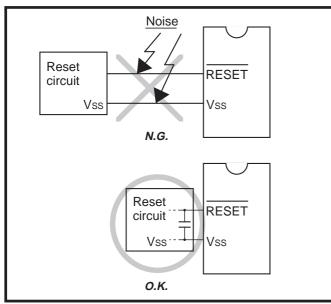


Fig. 3.4.2 Wiring for the RESET pin

3.4 Countermeasures against noise

(3) Wiring for clock input/output pins

- Make the length of wiring which is connected to clock I/O pins as short as possible.
- Make the length of wiring (within 20mm) across the grounding lead of a capacitor which is connected to an oscillator and the Vss pin of a microcomputer as short as possible.
- Separate the Vss pattern only for oscillation from other Vss patterns.

Reason

If noise enters clock I/O pins, clock waveforms may be deformed. This may cause a program failure or program runaway. Also, if a potential difference is caused by the noise between the Vss level of a microcomputer and the Vss level of an oscillator, the correct clock will not be input in the microcomputer.

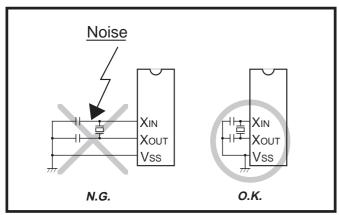


Fig. 3.4.3 Wiring for clock I/O pins

(4) Wiring to CNVss pin

Connect the CNVss pin to the Vss pin with the shortest possible wiring.

Reason

The processor mode of a microcomputer is influenced by a potential at the CNVss pin. If a potential difference is caused by the noise between pins CNVss and Vss, the processor mode may become unstable. This may cause a microcomputer malfunction or a program runaway.

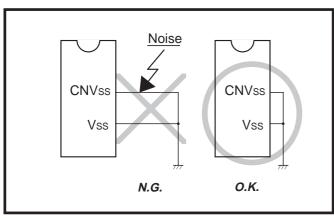


Fig. 3.4.4 Wiring for CNVss pin

(5) Wiring to VPP pin of One Time PROM version and EPROM version

Connect an approximately 5 $k\Omega$ resistor to the VPP pin the shortest possible in series and also to the Vss pin. When not connecting the resistor, make the length of wiring between the VPP pin and the Vss pin the shortest possible.

Note: Even when a circuit which included an approximately 5 k Ω resistor is used in the Mask ROM version, the microcomputer operates correctly.

Reason

The VPP pin of the One Time PROM and the EPROM version is the power source input pin for the built-in PROM. When programming in the built-in PROM, the impedance of the VPP pin is low to allow the electric current for writing flow into the PROM. Because of this, noise can enter easily. If noise enters the VPP pin, abnormal instruction codes or data are read from the built-in PROM, which may cause a program runaway.

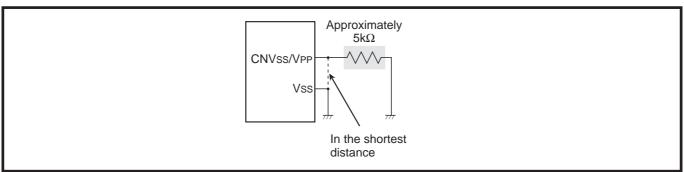


Fig. 3.4.5 Wiring for the VPP pin of the One Time PROM and the EPROM version

3.4.2 Connection of bypass capacitor across Vss line and Vcc line

Connect an approximately 0.1 μ F bypass capacitor across the Vss line and the Vcc line as follows:

- Connect a bypass capacitor across the Vss pin and the Vcc pin at equal length.
- Connect a bypass capacitor across the Vss pin and the Vcc pin with the shortest possible wiring.
- Use lines with a larger diameter than other signal lines for Vss line and Vcc line.
- Connect the power source wiring via a bypass capacitor to the Vss pin and the Vcc pin.

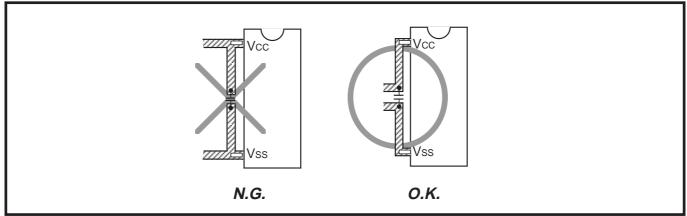


Fig. 3.4.6 Bypass capacitor across the Vss line and the Vcc line

3.4 Countermeasures against noise

3.4.3 Wiring to analog input pins

- Connect an approximately 100 Ω to 1 k Ω resistor to an analog signal line which is connected to an analog input pin in series. Besides, connect the resistor to the microcomputer as close as possible.
- Connect an approximately 1000 pF capacitor across the Vss pin and the analog input pin. Besides, connect the capacitor to the Vss pin as close as possible. Also, connect the capacitor across the analog input pin and the Vss pin at equal length.

Reason

Signals which is input in an analog input pin (such as an A-D converter/comparator input pin) are usually output signals from sensor. The sensor which detects a change of event is installed far from the printed circuit board with a microcomputer, the wiring to an analog input pin is longer necessarily. This long wiring functions as an antenna which feeds noise into the microcomputer, which causes noise to an analog input pin.

If a capacitor between an analog input pin and the Vss pin is grounded at a position far away from the Vss pin, noise on the GND line may enter a microcomputer through the capacitor.

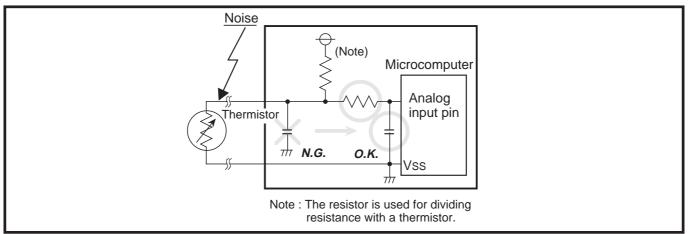


Fig. 3.4.7 Analog signal line and a resistor and a capacitor

3.4.4 Oscillator concerns

Take care to prevent an oscillator that generates clocks for a microcomputer operation from being affected by other signals.

(1) Keeping oscillator away from large current signal lines

Install a microcomputer (and especially an oscillator) as far as possible from signal lines where a current larger than the tolerance of current value flows.

Reason

In the system using a microcomputer, there are signal lines for controlling motors, LEDs, and thermal heads or others. When a large current flows through those signal lines, strong noise occurs because of mutual inductance.

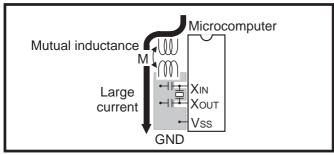


Fig. 3.4.8 Wiring for a large current signal line

(2) Installing oscillator away from signal lines where potential levels change frequently

Install an oscillator and a connecting pattern of an oscillator away from signal lines where potential levels change frequently. Also, do not cross such signal lines over the clock lines or the signal lines which are sensitive to noise.

Reason

Signal lines where potential levels change frequently (such as the CNTR pin signal line) may affect other lines at signal rising edge or falling edge. If such lines cross over a clock line, clock waveforms may be deformed, which causes a microcomputer failure or a program runaway.

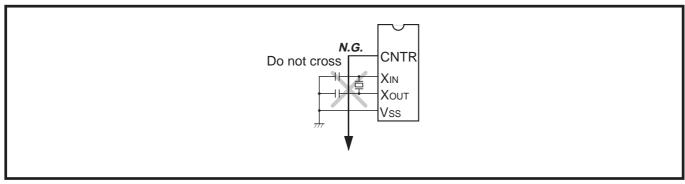


Fig. 3.4.9 Wiring of signal lines where potential levels change frequently

(3) Oscillator protection using Vss pattern

As for a two-sided printed circuit board, print a Vss pattern on the underside (soldering side) of the position (on the component side) where an oscillator is mounted.

Connect the Vss pattern to the microcomputer Vss pin with the shortest possible wiring. Besides, separate this Vss pattern from other Vss patterns.

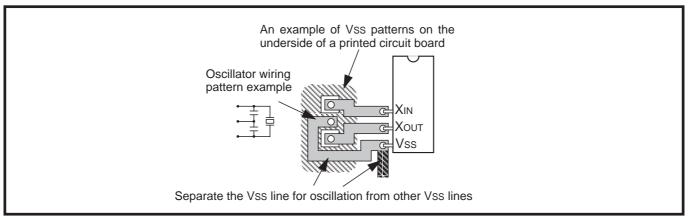


Fig. 3.4.10 Vss pattern on the underside of an oscillator

3.4 Countermeasures against noise

3.4.5 Setup for I/O ports

Setup I/O ports using hardware and software as follows:

<Hardware>

• Connect a resistor of 100 Ω or more to an I/O port in series.

<Software>

- As for an input port, read data several times by a program for checking whether input levels are equal or not.
- As for an output port, since the output data may reverse because of noise, rewrite data to its port latch at fixed periods.
- Rewrite data to direction registers and pull-up control registers at fixed periods.

Note: When a direction register is set for <u>input port</u> again at fixed periods, a several-nanosecond short pulse may be output from this port. If this is undesirable, connect a capacitor to this port to remove the noise pulse.

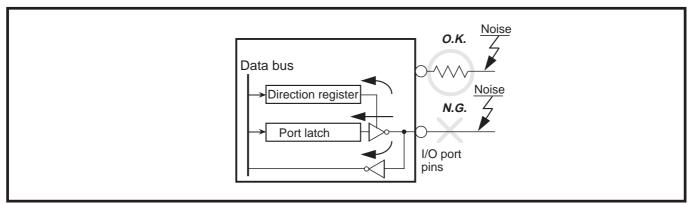


Fig. 3.4.11 Setup for I/O ports

3.4.6 Providing of watchdog timer function by software

If a microcomputer runs away because of noise or others, it can be detected by a software watchdog timer and the microcomputer can be reset to normal operation. This is equal to or more effective than program runaway detection by a hardware watchdog timer. The following shows an example of a watchdog timer provided by software.

In the following example, to reset a microcomputer to normal operation, the main routine detects errors of the interrupt processing routine and the interrupt processing routine detects errors of the main routine. This example assumes that interrupt processing is repeated multiple times in a single main routine processing.

<The main routine>

- Assigns a single byte of RAM to a software watchdog timer (SWDT) and writes the initial value N in the SWDT once at each execution of the main routine. The initial value N should satisfy the following condition:
 - $N+1 \ge$ (Counts of interrupt processing executed in each main routine)
 - As the main routine execution cycle may change because of an interrupt processing or others, the initial value N should have a margin.
- Watches the operation of the interrupt processing routine by comparing the SWDT contents with counts of interrupt processing after the initial value N has been set.
- Detects that the interrupt processing routine has failed and determines to branch to the program initialization routine for recovery processing in the following case:
 If the SWDT contents do not change after interrupt processing.

<The interrupt processing routine>

- Decrements the SWDT contents by 1 at each interrupt processing.
- Determines that the main routine operates normally when the SWDT contents are reset to the initial value N at almost fixed cycles (at the fixed interrupt processing count).
- Detects that the main routine has failed and determines to branch to the program initialization routine for recovery processing in the following case:

 If the SWDT contents are not initialized to the initial value N but continued to decrement and if

If the SWDT contents are not initialized to the initial value N but continued to decrement and if they reach 0 or less.

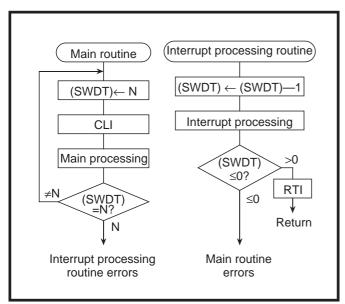


Fig. 3.4.12 Watchdog timer by software

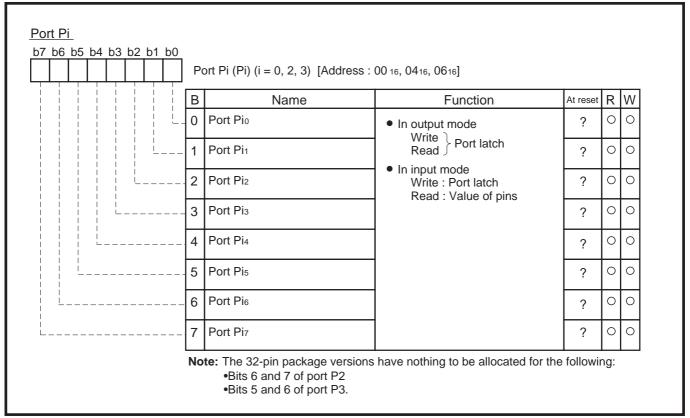


Fig. 3.5.1 Structure of Port Pi (i = 0, 2, 3)

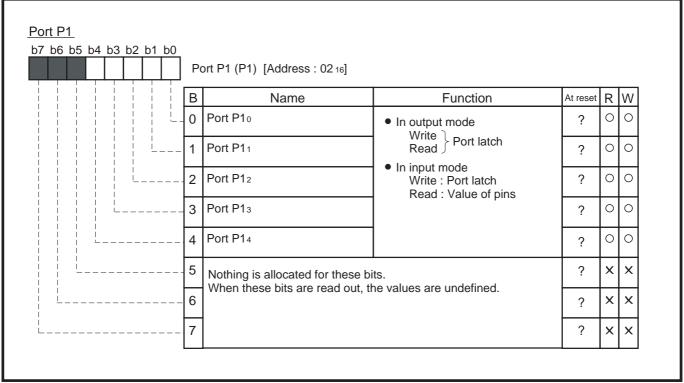


Fig. 3.5.2 Structure of Port P1

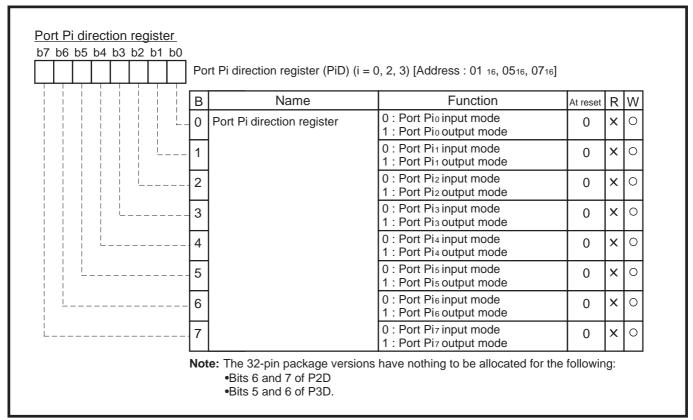


Fig. 3.5.3 Structure of Port Pi direction register (i = 0, 2, 3)

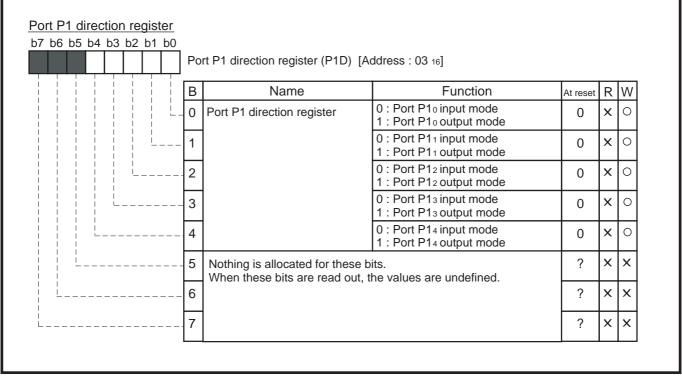


Fig. 3.5.4 Structure of Port P1 direction register

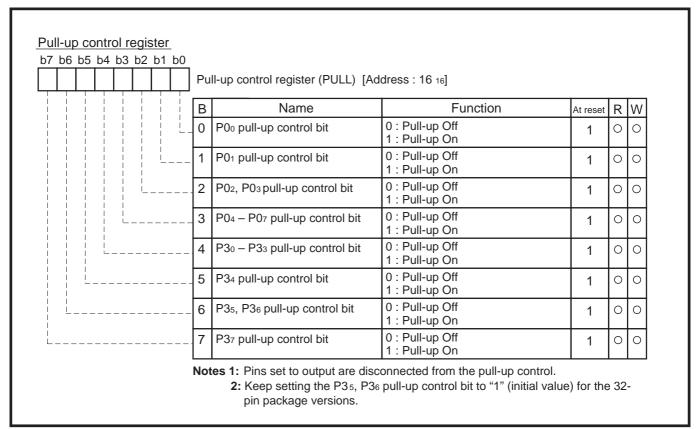


Fig. 3.5.5 Structure of Pull-up control register

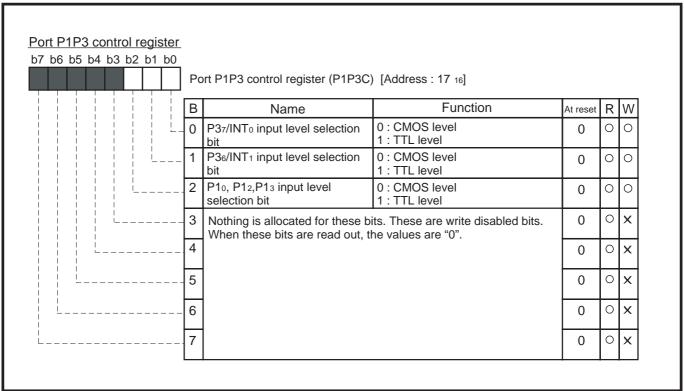


Fig. 3.5.6 Structure of Port P1P3 control register

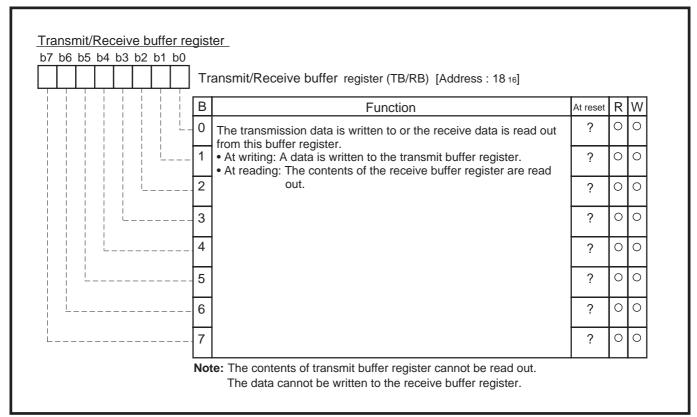


Fig. 3.5.7 Structure of Transmit/Receive buffer register

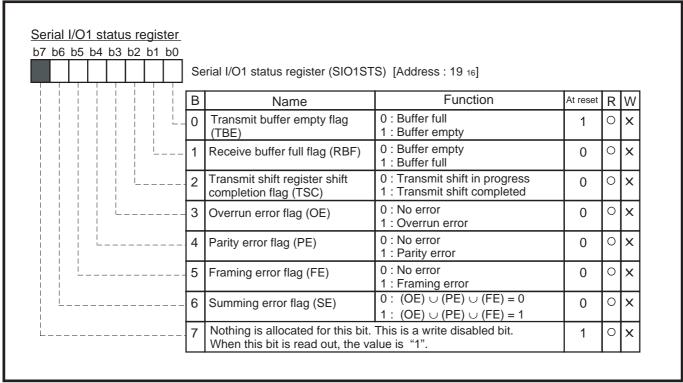


Fig. 3.5.8 Structure of Serial I/O1 status register

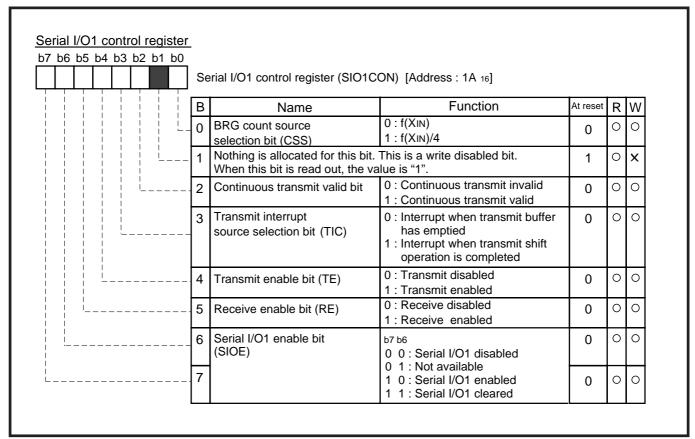


Fig. 3.5.9 Structure of Serial I/O1 control register

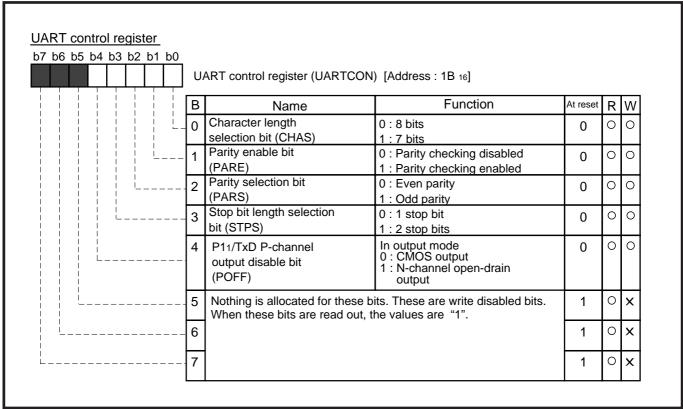


Fig. 3.5.10 Structure of UART control register

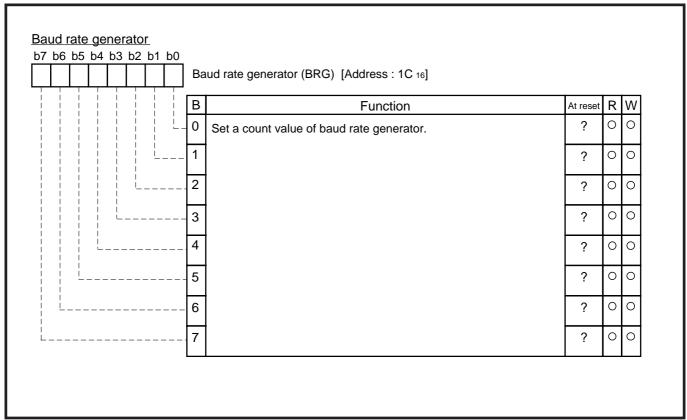


Fig. 3.5.11 Structure of Baud rate generator

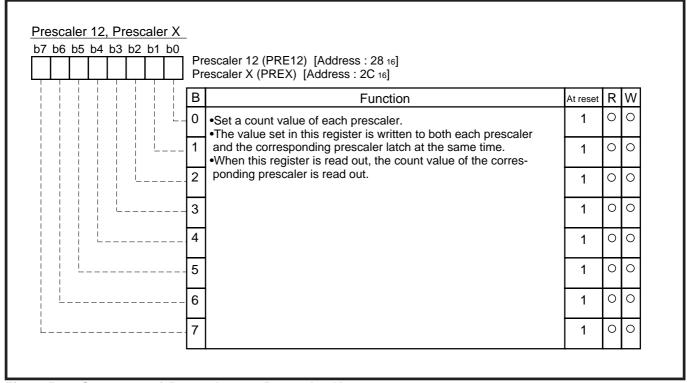


Fig. 3.5.12 Structure of Prescaler 12, Prescaler X

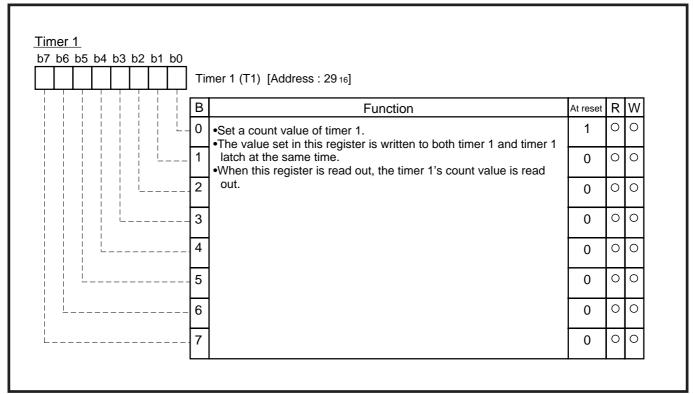


Fig. 3.5.13 Structure of Timer 1

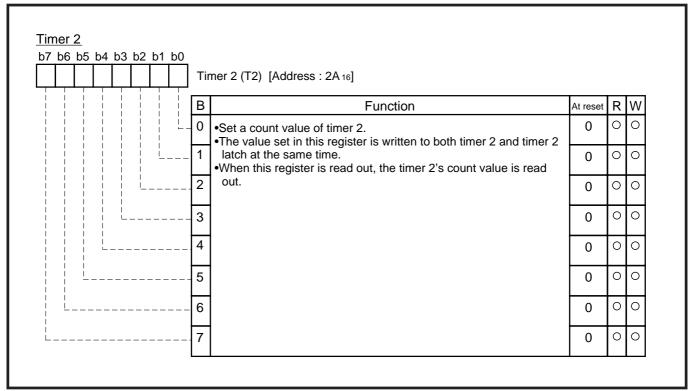


Fig. 3.5.14 Structure of Timer 2

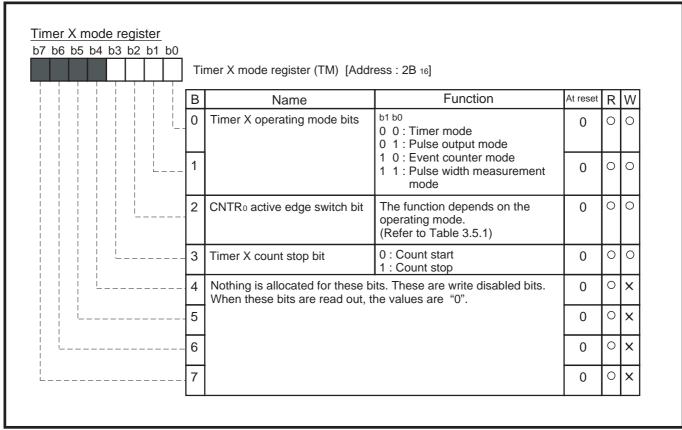


Fig. 3.5.15 Structure of Timer X mode register

Table 3.5.1 CNTR₀ active edge switch bit function

Timer X operation modes	CNTR ₀ active edge switch bit (bit 2 of address 2B ₁₆) contents	
Timer mode	"0"	CNTR₀ interrupt request occurrence: Falling edge
		; No influence to timer count
	"1"	CNTR ₀ interrupt request occurrence: Rising edge
		; No influence to timer count
Pulse output mode	"0"	Pulse output start: Beginning at "H" level
		CNTR₀ interrupt request occurrence: Falling edge
	"1"	Pulse output start: Beginning at "L" level
		CNTR₀ interrupt request occurrence: Rising edge
Event counter mode	"0"	Timer X: Rising edge count
		CNTR₀ interrupt request occurrence: Falling edge
	"1"	Timer X: Falling edge count
		CNTR₀ interrupt request occurrence: Rising edge
Pulse width measurement mode	"0"	Timer X: "H" level width measurement
		CNTR₀ interrupt request occurrence: Falling edge
	"1"	Timer X: "L" level width measurement
		CNTR ₀ interrupt request occurrence: Rising edge

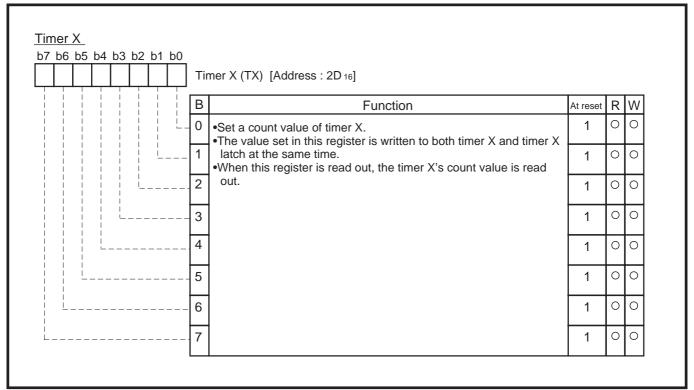


Fig. 3.5.16 Structure of Timer X

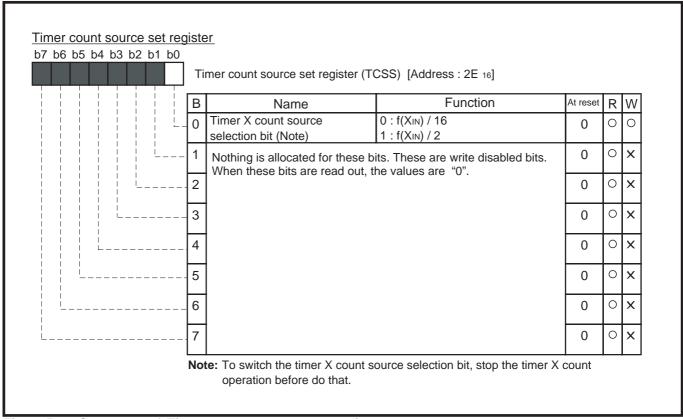


Fig. 3.5.17 Structure of Timer count source set register

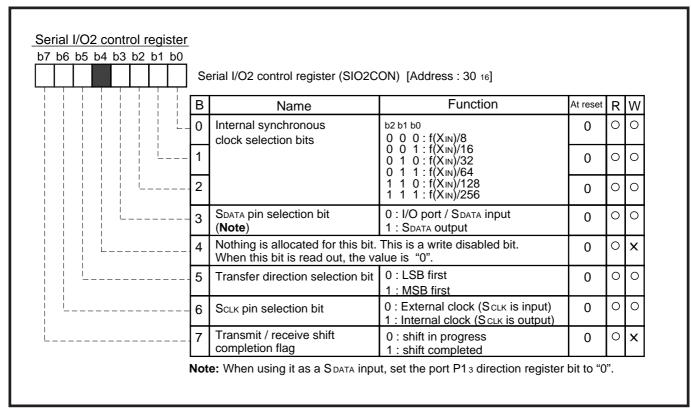


Fig. 3.5.18 Structure of Serial I/O2 control register

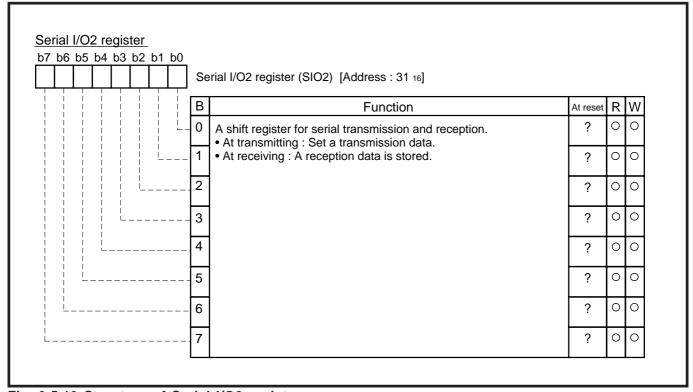


Fig. 3.5.19 Structure of Serial I/O2 register

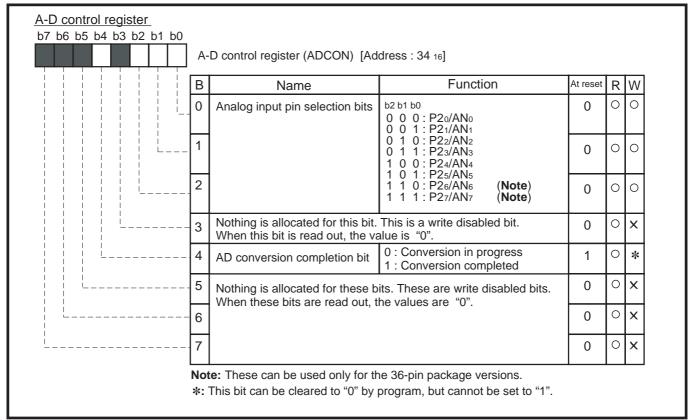


Fig. 3.5.20 Structure of A-D control register

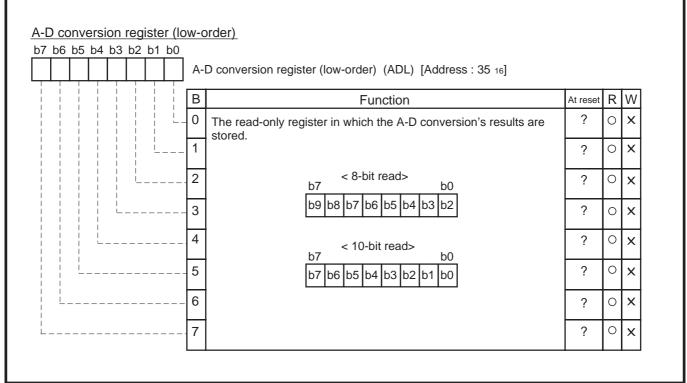


Fig. 3.5.21 Structure of A-D conversion register (low-order)

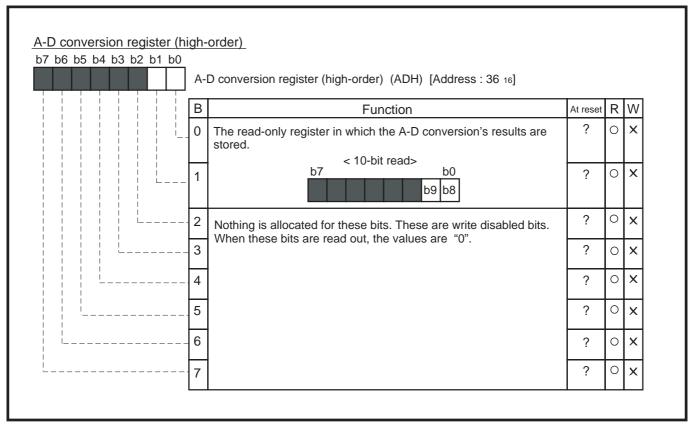


Fig. 3.5.22 Structure of A-D conversion register (high-order)

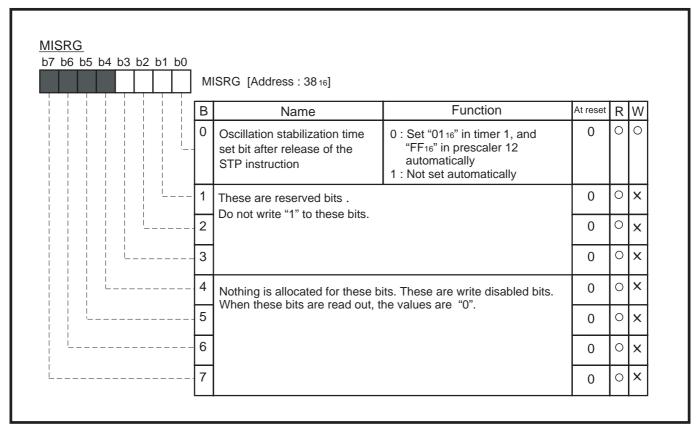


Fig. 3.5.23 Structure of MISRG

3.5 List of registers

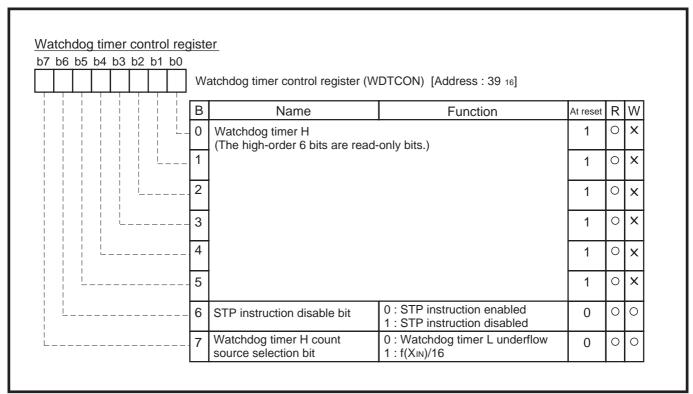


Fig. 3.5.24 Structure of Watchdog timer control register

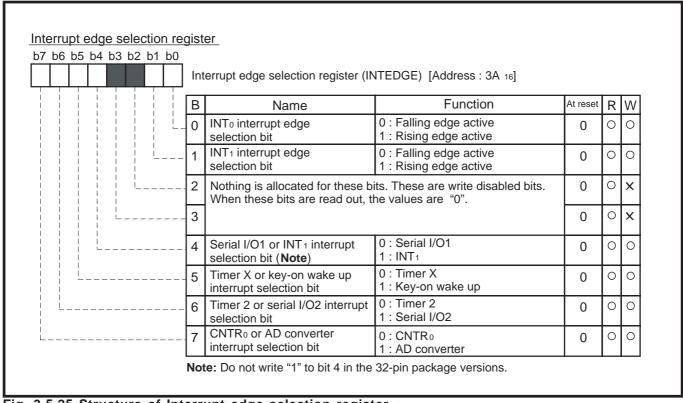


Fig. 3.5.25 Structure of Interrupt edge selection register

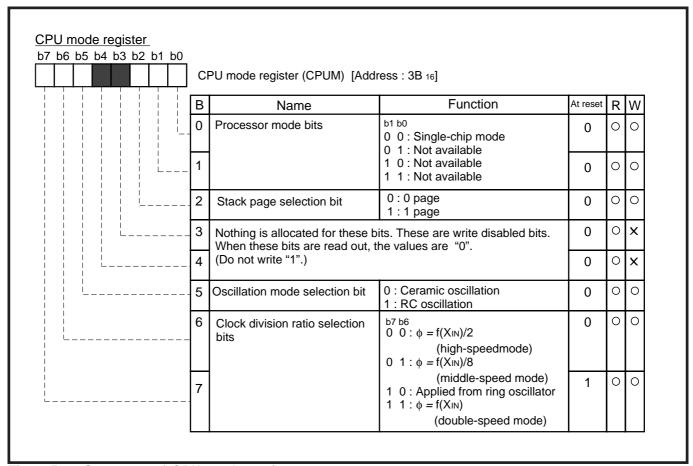


Fig. 3.5.26 Structure of CPU mode register

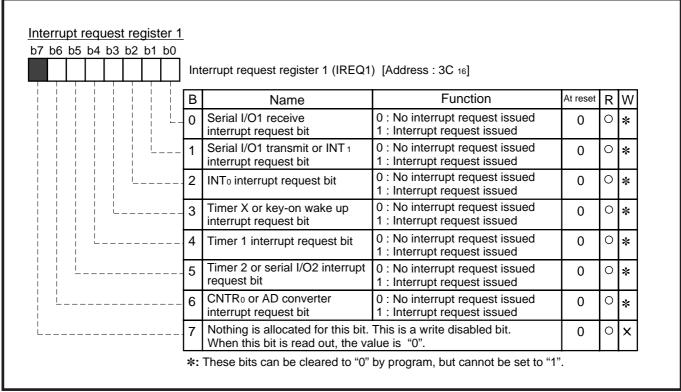


Fig. 3.5.27 Structure of Interrupt request register 1

3.5 List of registers

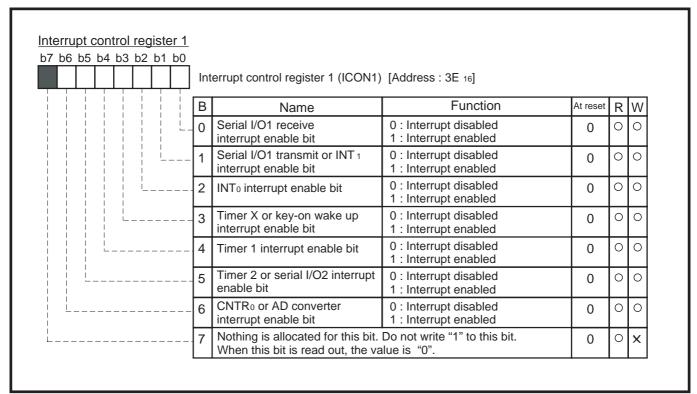


Fig. 3.5.28 Structure of Interrupt control register 1

3.6 Mask ROM confirmation form

GZZ-SH52-89B<85B0>

Mask ROM number

740 FAMILY MASK ROM CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531M4-XXXFP/GP/SP MITSUBISHI ELECTRIC

	Date:	
eipt	Section head signature	Supervisor signature
Receipt		

Note: Please fill in all items marked *.

		Company		TEL		Ф Ф	Submitted by	Supervisor
*	Customer	name		()	Jano Jatur		
		Date issued	Date:			Issu sigr		

* 1. Confirmation

Specify the name of the product being ordered and the type of EPROMs submitted.

Three EPROMs are required for each pattern (Check @ in the appropriate box).

If at least two of the three sets of EPROMs submitted contain identical data, we will produce masks based on this data. We shall assume the responsibility for errors only if the mask ROM data on the products we produce differs from this data. Thus, extreme care must be taken to verify the data in the submitted EPROMs.

Microcomputer name :	☐ M37531M4-XXXFP	☐ M37531M4-XXXGP	☐ M37531M4-XXXSP

			1
Checksum code for entire EPROM			(hexadecima

EPROM type (indicate the type used)

	27C256		27C512
EPROM ac	ddress	EPROM ad	ddress
0000 ₁₆ 000F ₁₆ 0010 ₁₆	Area for ASCII codes of the name of the product 'M37531M4-'	0000 ₁₆ 000F ₁₆ 0010 ₁₆	Area for ASCII codes of the name of the product 'M37531M4-'
607F ₁₆ 6080 ₁₆ 7FFD ₁₆ 7FFE ₁₆ 7FFF ₁₆	Data ROM (8K–130) bytes	E07F16 E08016 FFFD16 FFFE16 FFFF16	Data ROM (8K–130) bytes

In the address space of the microcomputer, the internal ROM area is from addresses E08016 to FFFD16. The reset vector is stored in addresses FFFC16 and FFFD16.

- (1) Set "FF16" in the shaded area.
- (2) Write the ASCII codes that indicates the name of the product 'M37531M4-' to addresses 000016 to 000F16. ASCII codes 'M37531M4-' are listed on the right. The addresses and data are in hexadecimal notation.

Address		Address	
000016	'M' = 4D ₁₆	000816	' – ' = 2D ₁₆
000116	'3' = 33 ₁₆	000916	FF ₁₆
000216	'7' = 37 ₁₆	000A16	FF ₁₆
000316	'5' = 35 ₁₆	000B ₁₆	FF ₁₆
000416	'3' = 33 ₁₆	000C ₁₆	FF ₁₆
000516	'1' = 31 ₁₆	000D16	FF ₁₆
000616	'M' = 4D ₁₆	000E16	FF ₁₆
000716	'4' = 34 ₁₆	000F16	FF ₁₆

3.6 Mask ROM confirmation form

GZZ-SH52-8	39B<85B0>
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Mask ROM number

740 FAMILY MASK ROM CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531M4-XXXFP/GP/SP MITSUBISHI ELECTRIC

Recommend to writing the following pseudo-command to the assembler source file:

EPROM type	27C256	27C512
The pseudo-command	△ * =△\$8000 △.BYTE △'M37531M4-'	△ * =△\$0000 △.BYTE △'M37531M4-'

ASCII codes, that indicates the name of the product, are written in addresses 000016 to 000816 of the EPROM by programming the above pseudo-command, which depends on a type of EPROM to be written, at beginning of the source program.

Note: If the name of the product written to the EPROMs does not match the name of the mask confirmation, the ROM processing is disabled. Write the data correctly.

* 2. Mark specification

Mark specification must be submitted using the correct form for the package being ordered fill out the appropriate mark specification form (36P2R for M37531M4-XXXFP, 32P6B for M37531M4-XXXGP, 32P4B for M37531M4-XXXSP) and attach to the mask ROM confirmation form.

# 3. Usage co Please a	onditions nswer the following questions	about usage for use in	our product inspection :
(1) How will y	ou use the XIN-XOUT oscillator	?	
	Ceramic resonator		
	External clock input	Other ()
At what fre	equency?	f(XIN) =	MHz

4. Comments

GZZ-SH52-90B<85C0>

740 FAMILY MASK ROM CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531M4T-XXXSP/FP/GP MITSUBISHI ELECTRIC

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	Date:	
eipt	Section head signature	Supervisor signature
Receipt		

Note: Please fill in all items marked *.

		Company		TEL		Ф Ф	Submitted by	Supervisor
*	Customer	name		()	uanc natur		
		Date issued	Date:			Issı sigr		

1. Confirmation

Specify the name of the product being ordered and the type of EPROMs submitted.

Three EPROMs are required for each pattern (Check @ in the appropriate box).

If at least two of the three sets of EPROMs submitted contain identical data, we will produce masks based on this data. We shall assume the responsibility for errors only if the mask ROM data on the products we produce differs from this data. Thus, extreme care must be taken to verify the data in the submitted EPROMs.

Microcomputer name: M37531M4T-XXXSP	M37531M	14T-X	XXFP	M3	7531M4T-XXXGP
Checksum code for en	ntire EPROM				(hexadecimal notation)

EPROM type (indicate the type used)

	27C256	□ 27C512			
EPROM a	ddress		EPROM ac	ddress	
000016 000F16	Area for ASCII codes of the name of the product 'M37531M4T-'		0000 ₁₆	Area for ASCII codes of the name of the product 'M37531M4T-'	
001016			001016		
607F ₁₆			E07F ₁₆		
608016	Data ROM (8K–130)		E080 ₁₆	Data ROM (8K-130)	
7FFD ₁₆ 7FFE ₁₆ 7FFF ₁₆	bytes		FFFD ₁₆ FFFF ₁₆	bytes	

In the address space of the microcomputer, the internal ROM area is from addresses E08016 to FFFD16. The reset vector is stored in addresses FFFC16 and FFFD16.

- (1) Set "FF16" in the shaded area.
- (2) Write the ASCII codes that indicates the name of the product 'M37531M4T-' to addresses 000016 to 000F16. ASCII codes 'M37531M4T-' are listed on the right. The addresses and data are in hexadecimal notation.

6
6
6
6
6
6
6
6

Address	
000816	'T' = 54 ₁₆
000916	' – ' = 2D ₁₆
000A ₁₆	FF ₁₆
000B ₁₆	FF ₁₆
000C ₁₆	FF ₁₆
000D ₁₆	FF ₁₆
000E ₁₆	FF ₁₆
000F ₁₆	FF16

3.6 Mask ROM confirmation form

Mask ROM number	

740 FAMILY MASK ROM CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531M4T-XXXSP/FP/GP MITSUBISHI ELECTRIC

Recommend to writing the following pseudo-command to the assembler source file:

EPROM type	27C256	27C512
The pseudo-command	△ * =△\$8000 △.BYTE △'M37531M4T-'	∆ ≭= △\$0000 △.BYTE △'M37531M4T-'

ASCII codes, that indicates the name of the product, are written in addresses 000016 to 000816 of the EPROM by programming the above pseudo-command, which depends on the type of EPROM to be written, at beginning of the source program.

Note: If the name of the product written to the EPROMs does not match the name of the mask confirmation, the ROM processing is disabled. Write the data correctly.

* 2. Mark specification

Mark specification must be submitted using the correct form for the package being ordered fill out the appropriate mark specification form (32P4B for M37531M4T-XXXSP, 36P2R for M37531M4T-XXXFP, 32P6B for M37531M4T-XXXGP) and attach to the mask ROM confirmation form.

* 3. Usage c		ions about usage for use	e in our product inspection :
(1) How will y	ou use the XIN-XOUT oscill	lator?	
	Ceramic resonator		
	External clock input	☐ Other ()
At what from	equency?	f(XIN) =	MHz

4. Comments

GZZ-SH56-95B<98A0>

740 FAMILY MASK ROM CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531M4V-XXXGP MITSUBISHI ELECTRIC

|--|

	Date:	
Receipt	Section head signature	Supervisor signature
R _e		

Note: Please fill in all items marked *.

		Company		TEL		Ф Ф	Submitted by	Supervisor
*	Customer	name		()	uanc natur		
		Date issued	Date:			Issı sigr		

* 1. Confirmation

Specify the type of EPROMs submitted.

Three EPROMs are required for each pattern (Check @ in the appropriate box).

If at least two of the three sets of EPROMs submitted contain identical data, we will produce masks based on this data. We shall assume the responsibility for errors only if the mask ROM data on the products we produce differs from this data. Thus, extreme care must be taken to verify the data in the submitted EPROMs.

hecksum code for entire EPROM			(hexadecimal notation)

EPROM type (indicate the type used)

	27C256		27C512
EPROM a	ddress	EPROM a	ddress
0000 ₁₆	Area for ASCII codes of the name of the product 'M37531M4V-'	000016 000F16	Area for ASCII codes of the name of the product 'M37531M4V-'
001016		001016	
607F ₁₆		E07F ₁₆	
608016	Data ROM (8K–130)	E080 ₁₆	Data ROM (8K–130)
7FFD ₁₆	bytes	FFFD ₁₆	bytes
7FFE ₁₆ 7FFF ₁₆		FFFE ₁₆ FFFF ₁₆	

In the address space of the microcomputer, the internal ROM area is from addresses E08016 to FFFD16. The reset vector is stored in addresses FFFC16 and FFFD16.

- (1) Set "FF16" in the shaded area.
- (2) Write the ASCII codes that indicates the name of the product 'M37531M4V-' to addresses 000016 to 000F16. ASCII codes 'M37531M4V-' are listed on the right. The addresses and data are in hexadecimal notation.

'M' = 4D ₁₆
'3' = 33 ₁₆
'7' = 37 ₁₆
'5' = 35 ₁₆
'3' = 33 16
'1' = 31 ₁₆
'M' = 4D ₁₆
'4' = 34 ₁₆

Address	
000816	'V' = 56 ₁₆
000916	' – ' = 2D ₁₆
000A ₁₆	FF ₁₆
000B ₁₆	FF16
000C ₁₆	FF ₁₆
000D ₁₆	FF ₁₆
000E ₁₆	FF ₁₆
000F ₁₆	FF ₁₆

3.6 Mask ROM confirmation form

GZZ-SH56-	95B<98A	.0>
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Mask ROM number	

740 FAMILY MASK ROM CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531M4V-XXXGP MITSUBISHI ELECTRIC

Recommend to writing the following pseudo-command to the assembler source file :

EPROM type	27C256	27C512
The pseudo-command	△ * =△\$8000 △.BYTE △'M37531M4V-'	△ * =△\$0000 △.BYTE △'M37531M4V-'

ASCII codes, that indicates the name of the product, are written in addresses 000016 to 000816 of the EPROM by programming the above pseudo-command, which depends on a type of EPROM to be written, at beginning of the source program.

Note: If the name of the product written to the EPROMs does not match the name of the mask confirmation, the ROM processing is disabled. Write the data correctly.

* 2. Mark specification

Mark specification must be submitted using the correct form for the package being ordered fill out the appropriate mark specification form (32P6B for M37531M4V-XXXGP) and attach to the mask ROM confirmation form.

* 3. Usage conditions Please answer the following questions	about usage for use in our product inspect	ion :
(1) How will you use the XIN-XOUT oscillator	?	
Ceramic resonator		
External clock input	☐ Other ()	
At what frequency?	f(XIN) = MHz	

4. Comments

GZZ-SH53-64B<87B0>

Mask ROM number

740 FAMILY MASK ROM CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531M8-XXXFP/GP/SP MITSUBISHI ELECTRIC

	Date:	
eipt	Section head signature	Supervisor signature
Receipt		

Note: Please fill in all items marked *.

		Company		TEL		υФ	Submitted by	Supervisor
*	Customer	name		()	uance		
		Date issued	Date:			Iss sigi		

* 1. Confirmation

Specify the name of the product being ordered and the type of EPROMs submitted.

Three EPROMs are required for each pattern (Check @ in the appropriate box).

If at least two of the three sets of EPROMs submitted contain identical data, we will produce masks based on this data. We shall assume the responsibility for errors only if the mask ROM data on the products we produce differs from this data. Thus, extreme care must be taken to verify the data in the submitted EPROMs.

Microcomputer name : ☐ M37531M8-XXXFP ☐ M37531M8-XXXGP ☐ M37531M8-XXXSP

Checksum code for entire EPROM (hexadecimal notation)

EPROM type (indicate the type used)

	27C256		27C512
EPROM a	ddress	EPROM ac	ddress
000016 000F16	Area for ASCII codes of the name of the product 'M37531M8-'	0000 ₁₆	Area for ASCII codes of the name of the product 'M37531M8-'
0010 ₁₆ 407F ₁₆ 4080 ₁₆	Data POM (46)(420)	0010 ₁₆ C07F ₁₆ C080 ₁₆	Data ROM (16K–130)
7FFD ₁₆ 7FFE ₁₆ 7FFF ₁₆	ROM (16K–130) bytes	FFFD16 FFFE16 FFFF16	bytes

In the address space of the microcomputer, the internal ROM area is from addresses C08016 to FFFD16. The reset vector is stored in addresses FFFC16 and FFFD16.

- (1) Set "FF16" in the shaded area.
- (2) Write the ASCII codes that indicates the name of the product 'M37531M8-' to addresses 000016 to 000F16. ASCII codes 'M37531M8-' are listed on the right. The addresses and data are in hexadecimal notation.

Address		Address	
000016	'M' = 4D ₁₆	000816	' – ' = 2D ₁₆
000116	'3' = 33 ₁₆	000916	FF ₁₆
000216	'7' = 37 ₁₆	000A16	FF ₁₆
000316	'5' = 35 ₁₆	000B ₁₆	FF ₁₆
000416	'3' = 33 ₁₆	000C ₁₆	FF ₁₆
000516	'1' = 31 ₁₆	000D16	FF ₁₆
000616	'M' = 4D ₁₆	000E16	FF ₁₆
000716	'8' = 38 ₁₆	000F ₁₆	FF ₁₆

3.6 Mask ROM confirmation form

Mask ROM number	

740 FAMILY MASK ROM CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531M8-XXXFP/GP/SP MITSUBISHI ELECTRIC

Recommend to writing the following pseudo-command to the assembler source file:

EPROM type	27C256	27C512
The pseudo-command	△ * =△\$8000 △.BYTE △'M37531M8-'	△ * =△\$0000 △.BYTE △'M37531M8-'

ASCII codes, that indicates the name of the product, are written in addresses 000016 to 000F16 of the EPROM by programming the above pseudo-command, which depends on a type of EPROM to be written, at beginning of the source program.

Note: If the name of the product written to the EPROMs does not match the name of the mask confirmation, the ROM processing is disabled. Write the data correctly.

* 2. Mark specification

Mark specification must be submitted using the correct form for the package being ordered fill out the appropriate mark specification form (36P2R for M37531M8-XXXFP, 32P6B for M37531M8-XXXGP, 32P4B for M37531M8-XXXSP) and attach to the mask ROM confirmation form.

# 3. Usage co Please a	onditions nswer the following questions	about usage for use in	our product inspection :
(1) How will y	ou use the XIN-XOUT oscillator	?	
	Ceramic resonator		
	External clock input	Other ()
At what fre	equency?	f(XIN) =	MHz

4. Comments

3.7 ROM programming confirmation form

GZZ-SH54-78B<91A0>

ROM number

740 FAMILY ROM PROGRAMMING CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531E4T-XXXGP MITSUBISHI ELECTRIC

	Date:	
eipt	Section head signature	Supervisor signature
Receipt		

Note: Please fill in all items marked *.

		Company		TEL		Ф Ф	Submitted by	Supervisor
*	Customer	name		()	Janc Jatur		
		Date issued	Date:			Issı sigr		

* 1. Confirmation

Specify the name of the product being ordered and the type of EPROMs submitted.

Three EPROMs are required for each pattern (Check @ in the appropriate box).

If at least two of the three sets of EPROMs submitted contain identical data, we will produce ROM data based on this data. We shall assume the responsibility for errors only if the mask ROM data on the products we produce differs from this data. Thus, extreme care must be taken to verify the data in the submitted EPROMs.

	 		1
Checksum code for entire EPROM			(hexadecimal notation)

EPROM type (indicate the type used)

=: : : : : : : : : : : : : : : : : : :	po (maioato tric	71		
	27C256			27C512
EPROM a	ddress		EPROM a	ddress
000016	Area for ASCII codes of the name of the product		000016	Area for ASCII codes of the name of the product
000F ₁₆ 0010 ₁₆	'M37531E4T-'		000F ₁₆	'M37531E4T-'
607F ₁₆			E07F ₁₆	
608016	Data ROM (8K–130)		E080 ₁₆	Data ROM (8K–130)
7FFD ₁₆ 7FFE ₁₆	bytes		FFFD ₁₆ FFFE ₁₆	bytes
7FFF ₁₆	<u> </u>		FFFF ₁₆	V////////

In the address space of the microcomputer, the internal ROM area is from addresses E08016 to FFFD16. The reset vector is stored in addresses FFFC16 and FFFD16.

- (1) Set "FF16" in the shaded area.
- (2) Write the ASCII codes that indicates the name of the product 'M37531E4T-' to addresses 000016 to 000F16. ASCII codes 'M37531E4T-' are listed on the right. The addresses and data are in hexadecimal notation.

Address		Address	
000016	'M' = 4D ₁₆	000816	'T'=5416
000116	'3' = 33 ₁₆	000916	' – ' = 2D ₁₆
000216	'7' = 37 ₁₆	000A16	FF ₁₆
000316	'5' = 35 ₁₆	000B ₁₆	FF ₁₆
000416	'3' = 33 ₁₆	000C ₁₆	FF ₁₆
000516	'1' = 31 ₁₆	000D16	FF ₁₆
000616	'E' = 4516	000E16	FF ₁₆
000716	'4' = 34 ₁₆	000F ₁₆	FF ₁₆

3.7 ROM programming confirmation form

GZZ-SH54-78B<91A0>	ROM number	

740 FAMILY ROM PROGRAMMING CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531E4T-XXXGP MITSUBISHI ELECTRIC

Recommend to writing the following pseudo-command to the assembler source file :

EPROM type	27C256	27C512
The pseudo-command	△ * =△\$8000 △.BYTE △'M37531E4T-'	△ * =△\$0000 △.BYTE △'M37531E4T-'

ASCII codes, that indicates the name of the product, are written in addresses 000016 to 000816 of the EPROM by programming the above pseudo-command, which depends on a type of EPROM to be written, at beginning of the source program.

Note: If the name of the product written to the EPROMs does not match the name of the ROM programming confirmation form, the ROM processing is disabled. Write the data correctly.

2. Mark specification

Mark specification must be submitted using the correct form for the package being ordered fill out the appropriate mark specification form (32P6B for M37531E4T-XXXGP) and attach to the ROM programming confirmation form.

# 3. Usage conditions Please answer the following question	ns about usage for us	se in our product inspection :	
(1) How will you use the XIN-XOUT oscillated Ceramic resonator	tor?		
External clock input	☐ Other ()	
At what frequency?	f(XIN) =	MHz	
* 4. Comments			

(2/2)

GZZ-SH54-79B<91A0>

ROM number

740 FAMILY ROM PROGRAMMING CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531E4V-XXXGP MITSUBISHI ELECTRIC

	Date:	
eipt	Section head signature	Supervisor signature
Receipt		

Note: Please fill in all items marked *.

		Company		TEL		Ф Ф	Submitted by	Supervisor
*	Customer	name		()	Janc Jatur		
		Date issued	Date:			Issı sigr		

* 1. Confirmation

Specify the name of the product being ordered and the type of EPROMs submitted.

Three EPROMs are required for each pattern (Check @ in the appropriate box).

If at least two of the three sets of EPROMs submitted contain identical data, we will produce ROM data based on this data. We shall assume the responsibility for errors only if the mask ROM data on the products we produce differs from this data. Thus, extreme care must be taken to verify the data in the submitted EPROMs.

			1
Checksum code for entire EPROM			(hexadecimal notation)

EPROM type (indicate the type used)

	po (maioato tin	71	/	
□ 27C256			27C512	
EPROM a	ddress		EPROM a	ddress
000016	Area for ASCII codes of the name of the product		000016	Area for ASCII codes of the name of the product
000F ₁₆	'M37531E4V–'		000F ₁₆	'M37531E4V–'
001016			001016	
607F ₁₆			E07F ₁₆	
608016	Data		E080 ₁₆	Data ROM (8K–130)
7FFD ₁₆	ROM (8K–130) bytes		FFFD ₁₆	bytes
7FFE ₁₆			FFFE ₁₆	
7FFF ₁₆	V/////////////////////////////////////		FFFF ₁₆	V///////

In the address space of the microcomputer, the internal ROM area is from addresses E08016 to FFFD16. The reset vector is stored in addresses FFFC16 and FFFD16.

- (1) Set "FF16" in the shaded area.
- (2) Write the ASCII codes that indicates the name of the product 'M37531E4V-' to addresses 000016 to 000F16. ASCII codes 'M37531E4V-' are listed on the right. The addresses and data are in hexadecimal notation.

Address		Address	
000016	'M' = 4D ₁₆	000816	' V ' = 56 ₁₆
000116	'3' = 33 ₁₆	000916	' – ' = 2D ₁₆
000216	'7' = 37 ₁₆	000A16	FF ₁₆
000316	'5' = 35 ₁₆	000B ₁₆	FF ₁₆
000416	'3' = 33 ₁₆	000C ₁₆	FF ₁₆
000516	'1' = 31 ₁₆	000D16	FF ₁₆
000616	'E' = 4516	000E16	FF ₁₆
000716	'4' = 34 ₁₆	000F ₁₆	FF ₁₆

3.7 ROM programming confirmation form

GZZ-SH54-79B<91A0>	ROM number	

740 FAMILY ROM PROGRAMMING CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531E4V-XXXGP MITSUBISHI ELECTRIC

Recommend to writing the following pseudo-command to the assembler source file :

EPROM type	27C256	27C512
The pseudo-command	△ * =△\$8000 △.BYTE △'M37531E4V-'	△ *= △\$0000 △.BYTE △'M37531E4V-'

ASCII codes, that indicates the name of the product, are written in addresses 000016 to 000816 of the EPROM by programming the above pseudo-command, which depends on a type of EPROM to be written, at beginning of the source program.

Note: If the name of the product written to the EPROMs does not match the name of the ROM programming confirmation form, the ROM processing is disabled. Write the data correctly.

2. Mark specification

Mark specification must be submitted using the correct form for the package being ordered fill out the appropriate mark specification form (32P6B for M37531E4V-XXXGP) and attach to the ROM programming confirmation form.

3. Usage conditionsPlease answer the following quest	ions about usage for use in our product inspection :	
(1) How will you use the XIN-XOUT oscil Ceramic resonator External clock input	lator?	
At what frequency?	f(XIN) = MHz	
* 4. Comments		

(2/2)

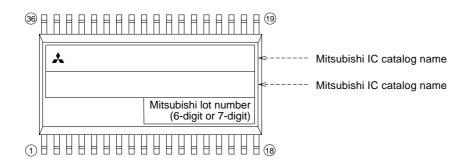
3.8 Mark specification form

36P2R-A (36-PIN SHRINK SOP) MARK SPECIFICATION FORM

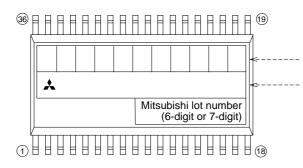
Mitsubishi IC catalog name	
	l

Please choose one of the marking types below (A, B, C), and enter the Mitsubishi catalog name and the special mark (if needed).

A. Standard Mitsubishi Mark



B. Customer's Parts Number + Mitsubishi catalog name



Customer's Parts Number

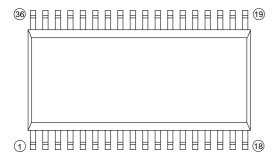
Note : The fonts and size of characters are standard Mitsubishi type. Mitsubishi IC catalog name

Note1: The mark field should be written right aligned.

- 2: The fonts and size of characters are standard Mitsubishi type.
- 3 : Customer's Parts Number can be up to 11 characters : Only 0 \sim 9, A \sim Z, +, -, /, (,), &, \odot , (periods), (commas) are usable.
- 4: If the Mitsubishi logo 🙏 is not required, check the box below.

A Mitsubishi logo is not required

C. Special Mark Required



Note1: If the Special Mark is to be Printed, indicate the desired layout of the mark in the left figure. The layout will be duplicated as close as possible.

Mitsubishi lot number (6-digit or 7-digit) and Mask ROM number (3-digit) are always marked.

2: If the customer's trade mark logo must be used in the Special Mark, check the box below.

Please submit a clean original of the logo.

For the new special character fonts a clean font original (ideally logo drawing) must be submitted.

Special logo	requ	uired

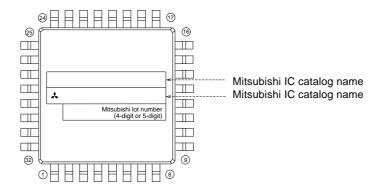
3: The standard Mitsubishi font is used for all characters except for a logo.

32P6B (32-PIN LQFP) MARK SPECIFICATION FORM

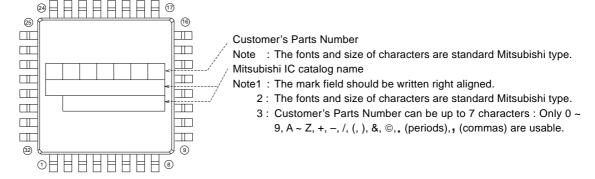
Mitsubishi IC catalog name	
----------------------------	--

Please choose one of the marking types below (A, B), and enter the Mitsubishi catalog name and the special mark (if needed).

A. Standard Mitsubishi Mark



B. Customer's Parts Number + Mitsubishi catalog name



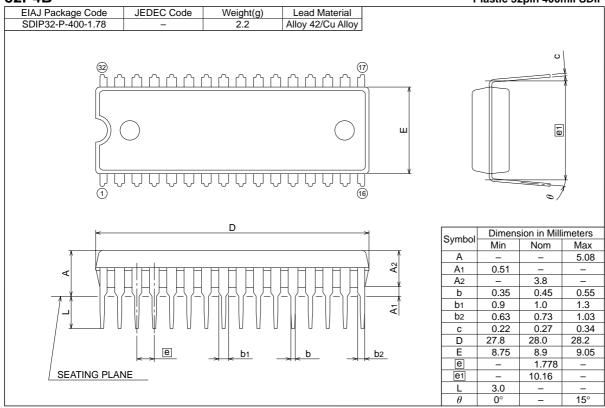
32P4B (32-PIN SHRINK DIP) MARK SPECIFICATION FORM

Mitsubishi IC catalog name
Please choose one of the marking types below (A, B, C), and enter the Mitsubishi IC catalog name and the special mark (if needed).
A. Standard Mitsubishi Mark
$^{(2)}$
Mitsubishi lot number
(6-digit or 7-digit)
A Mitsubishi IC catalog name
B. Customer's Parts Number + Mitsubishi catalog name
32 \cap
Customer's Parts Number Note: The fonts and size of characters
are standard Mitsubishi type. A Mitsubishi IC catalog name
Mitsubishi lot number Mitsubishi lot number
(6-digit or 7-digit)
$\bigcirc \bigcirc $
Note1: The mark field should be written right aligned.
2: The fonts and size of characters are standard Mitsubishi type. 3: Customer's Parts Number can be up to 16 characters: Only 0 ~ 9, A ~ Z, +, -, /, (,), &, ©, (periods), and, (commas) are usable
4: If the Mitsubishi logo ★ is not required, check the box on the right. ★ Mitsubishi logo is not required
C. Special Mark Required
Note1: If the Special Mark is to be Printed, indicate the desired layout of the mark in the upper figure. The layout will be duplicated as close as possible. Mitsubishi lot number (6-digit or 7-digit) and Mask ROM number (3-digit) are always marked.
2 : If the customer's trade mark logo must be used in the Special Mark, check the
box on the right. Please submit a clean original of the logo. For the new special Special logo required character fonts a clean font original (ideally logo drawing) must be submitted.
3 : The standard Mitsubishi font is used for all characters except for a logo.

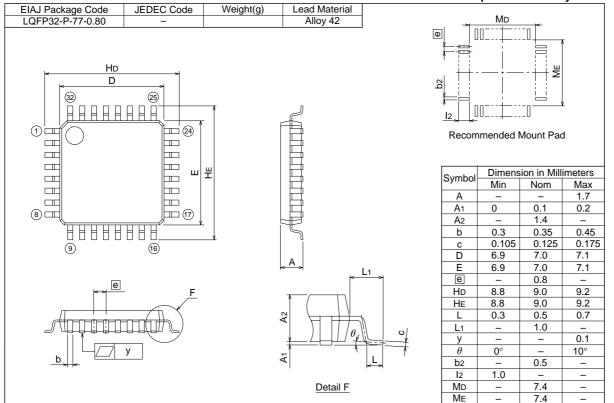
3.9 Package outline

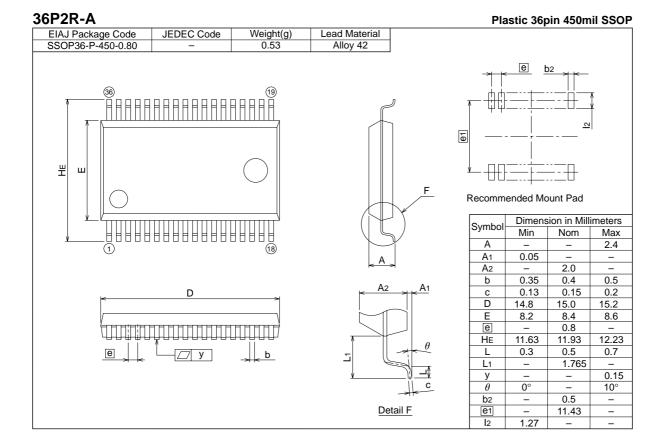
3.9 Package outline

32P4B Plastic 32pin 400mil SDIP









3.10 Machine instructions

									Α	Addr	essi	ing ı	mod	le	_					
Symbol	Function	Details		IMP	,		IMN	1		Α		BI ⁻	Т, А	, R		ZP		віт	, ZP	', F
			OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#
ADC (Note 1) (Note 5)	When T = 0 $A \leftarrow A + M + C$ When T = 1 $M(X) \leftarrow M(X) + M + C$	When T = 0, this instruction adds the contents M, C, and A; and stores the results in A and C. When T = 1, this instruction adds the contents of M(X), M and C; and stores the results in M(X) and C. When T=1, the contents of A remain unchanged, but the contents of status flags are changed. M(X) represents the contents of memory where is indicated by X.				69	2	2							65	3	2			
AND (Note 1)	When T = 0 $A \leftarrow A \land M$ When T = 1 $M(X) \leftarrow M(X) \land M$	When T = 0, this instruction transfers the contents of A and M to the ALU which performs a bit-wise AND operation and stores the result back in A. When T = 1, this instruction transfers the contents M(X) and M to the ALU which performs a bit-wise AND operation and stores the results back in M(X). When T = 1, the contents of A remain unchanged, but status flags are changed. M(X) represents the contents of memory where is indicated by X.				29	2	2							25	3	2			
ASL	7 0 ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○	This instruction shifts the content of A or M by one bit to the left, with bit 0 always being set to 0 and bit 7 of A or M always being contained in C.							0A	2	1				06	5	2			
BBC (Note 4)	Ai or Mi = 0?	This instruction tests the designated bit i of M or A and takes a branch if the bit is 0. The branch address is specified by a relative address. If the bit is 1, next instruction is executed.										1 <u>,</u> 3 20i	4	2				1 <u>7</u> 20i	5	3
BBS (Note 4)	Ai or Mi = 1?	This instruction tests the designated bit i of the M or A and takes a branch if the bit is 1. The branch address is specified by a relative address. If the bit is 0, next instruction is executed.										0 <u>3</u> 20i	4	2				0 ₄ 7 20i	5	3
BCC (Note 4)	C = 0?	This instruction takes a branch to the appointed address if C is 0. The branch address is specified by a relative address. If C is 1, the next instruction is executed.																		
BCS (Note 4)	C = 1?	This instruction takes a branch to the appointed address if C is 1. The branch address is specified by a relative address. If C is 0, the next instruction is executed.																		
BEQ (Note 4)	Z = 1?	This instruction takes a branch to the appointed address when Z is 1. The branch address is specified by a relative address. If Z is 0, the next instruction is executed.																		
BIT	AAM	This instruction takes a bit-wise logical AND of A and M contents; however, the contents of A and M are not modified. The contents of N, V, Z are changed, but the contents of A, M remain unchanged.													24	3	2			
BMI (Note 4)	N = 1?	This instruction takes a branch to the appointed address when N is 1. The branch address is specified by a relative address. If N is 0, the next instruction is executed.																		
BNE (Note 4)	Z = 0?	This instruction takes a branch to the appointed address if Z is 0. The branch address is specified by a relative address. If Z is 1, the next instruction is executed.																		

															Ad	ldre	ssin	g m	ode															F	Proc	ess	or st	atu	s re	giste	er
Z	ΖP, Σ	X	- 2	ZP	, Y		,	ABS	3	А	BS,	Х	A	BS,	Υ		INE)	Z	P, II	ND	II	ND,	X	11	ND,	Υ		REL			SP		7	6	5	4	3	2	1	0
OP	n	#	OP	r	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	N	٧	Т	В	D	ı	Z	С
75	4	2					6D	4	3	7D	5	3	79	5	3							61	6	2	71	6	2							N	V	•	•	•	•	Z	С
35	4	2					2D	4	3	3D	5	3	39	5	3							21	6	2	31	6	2							N	•	•	•	•	•	Z	•
16	6	2					0E	6	3	1E	7	3																						N	•	•	•	•	•	Z	С
																																		•	•	•	•	•	•	•	•
																																		•	•	•	•	•	•	•	•
																												90	2	2				•	•	•	•	•	•	•	•
																												В0	2	2				•	•	•	•	•	•	•	•
																												F0	2	2				•	•	•	•	•	•	•	•
							2C	4	3																									M7	M6	•	•	•	•	Z	•
																												30	2	2				•	•	•	•	•	•	•	•
																												D0	2	2				•	•	•	•	•	•	•	•

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									-	Addr	ess	ing	mod	le						
Symbol	Function	Details		IMP	•		IMN	_		Α		E	BIT,	_	<u> </u>	ΖP		ВІ	IT, Z	ΈP
			OP	n	#	OF	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#
BPL (Note 4)	N = 0?	This instruction takes a branch to the appointed address if N is 0. The branch address is specified by a relative address. If N is 1, the next instruction is executed.																		
BRA	$PC \leftarrow PC \pm offset$	This instruction branches to the appointed address. The branch address is specified by a relative address.																		
BRK	$\begin{split} B \leftarrow 1 \\ (PC) \leftarrow (PC) + 2 \\ M(S) \leftarrow PCH \\ S \leftarrow S - 1 \\ M(S) \leftarrow PCL \\ S \leftarrow S - 1 \\ M(S) \leftarrow PS \\ S \leftarrow S - 1 \\ \leftarrow 1 \\ \leftarrow 1 \\ \leftarrow 1 \\ \rightarrow CL \leftarrow ADL \\ PCH \leftarrow ADH \end{split}$	When the BRK instruction is executed, the CPU pushes the current PC contents onto the stack. The BADRS designated in the interrupt vector table is stored into the PC.	00	7	1															
BVC (Note 4)	V = 0?	This instruction takes a branch to the appointed address if V is 0. The branch address is specified by a relative address. If V is 1, the next instruction is executed.																		
BVS (Note 4)	V = 1?	This instruction takes a branch to the appointed address when V is 1. The branch address is specified by a relative address. When V is 0, the next instruction is executed.																		
CLB	Ai or Mi ← 0	This instruction clears the designated bit i of A or M.										1В 20і	2	1				1F 20i	5	2
CLC	C ← 0	This instruction clears C.	18	2	1															
CLD	D ← 0	This instruction clears D.	D8	2	1															
CLI	I ← 0	This instruction clears I.	58	2	1															
CLT	T ← 0	This instruction clears T.	12	2	1															
CLV	V ← 0	This instruction clears V.	B8	2	1															
CMP (Note 3)	When T = 0 A - M When T = 1 M(X) - M	When T = 0, this instruction subtracts the contents of M from the contents of A. The result is not stored and the contents of A or M are not modified. When T = 1, the CMP subtracts the contents of M from the contents of M(X). The result is not stored and the contents of X, M, and A are not modified. M(X) represents the contents of memory where is indicated by X.				C9	2	2							C5	3	2			
СОМ	$M \leftarrow \overline{M}$	This instruction takes the one's complement of the contents of M and stores the result in M.													44	5	2			
CPX	X – M	This instruction subtracts the contents of M from the contents of X. The result is not stored and the contents of X and M are not modified.				E0	2	2							E4	3	2			
CPY	Y – M	This instruction subtracts the contents of M from the contents of Y. The result is not stored and the contents of Y and M are not modified.				C0	2	2							C4	3	2			
DEC	A ← A − 1 or M ← M − 1	This instruction subtracts 1 from the contents of A or M.							1A	2	1				C6	5	2			

													Ad	dres	sing	g mo	ode															T	Proc	ess	or st	atus	reg	giste	er
ZP, X		Z	Έ, \	<u> </u>		ABS		А	BS,	Х	А	BS,		_	IND		_	P, IN	ID	IN	ND,	X	IN	ND,	Y		REL			SP		7	6	1	4	3	2	1	0
	-		n		OP		_	OP	_	1	OP			_			OP			OP			OP		_	OP			OP	_	_	+	V		В		ı	Z	С
																										10	2	2				•	•	•	•	•	•	•	•
																										80	4	2				•	•	•	•	•	•	•	•
																																•	•	•	1	•	1	•	•
																										50	2	2				•	•	•	•	•	•	•	•
																										70	2	2				•	•	•	•	•	•	•	•
																																•	•	•	•	•	•	•	٠
																																•	•	•	•	•	•	•	0
																																•	•	•	•	0	•	•	
																																•	•	0	•	•	0	•	•
																																•	0	•	•	•	•	•	•
D5 4	2				CD	4	3	חח	5	3	D9	5	3							C1	6	2	D1	6	2							N	•		•	•	•	Z	С
																								,														_	
																																N	•	•	•	•	•	Z	•
					EC	4	3																									N	•	•	•	•	•	Z	С
					СС	4	3																									N	•	•	•	•	•	Z	С
D6 6	2				CE	6	3	DE	7	3																						N	•	•	•	•	•	Z	•

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						_			A	ddre	essi	ng ı	mod	е						
Symbol	Function	Details		IMP			IMM			Α		В	SIT,	A		ZP		BI	T, Z	P
			OP		#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#
DEX	X ← X − 1	This instruction subtracts one from the current contents of X.	CA	2	1															
DEY	Y ← Y − 1	This instruction subtracts one from the current contents of Y.	88	2	1															
EOR (Note 1)	When T = 0 $A \leftarrow A \forall M$ When T = 1 $M(X) \leftarrow M(X) \forall M$	When T = 0, this instruction transfers the contents of the M and A to the ALU which performs a bit-wise Exclusive OR, and stores the result in A. When T = 1, the contents of M(X) and M are transferred to the ALU, which performs a bit-wise Exclusive OR and stores the results in M(X). The contents of A remain unchanged, but status flags are changed. M(X) represents the contents of memory where is indicated by X.				49	2	2							45	3	2			
INC	A ← A + 1 or M ← M + 1	This instruction adds one to the contents of A or M.							3A	2	1				E6	5	2			L
INX	X ← X + 1	This instruction adds one to the contents of X.	E8	2	1															
INY	Y ← Y + 1	This instruction adds one to the contents of Y.	C8	2	1															
JMP	$\begin{array}{l} \text{If addressing mode is ABS} \\ \text{PCL} \leftarrow \text{ADL} \\ \text{PCH} \leftarrow \text{ADH} \\ \text{If addressing mode is IND} \\ \text{PCL} \leftarrow \text{M (ADH, ADL)} \\ \text{PCH} \leftarrow \text{M (ADH, ADL + 1)} \\ \text{If addressing mode is ZP, IND} \\ \text{PCL} \leftarrow \text{M(00, ADL)} \\ \text{PCH} \leftarrow \text{M(00, ADL)} \\ \text{PCH} \leftarrow \text{M(00, ADL + 1)} \end{array}$	This instruction jumps to the address designated by the following three addressing modes: Absolute Indirect Absolute Zero Page Indirect Absolute																		
JSR	$\begin{array}{l} M(S) \leftarrow PCH \\ S \leftarrow S-1 \\ M(S) \leftarrow PCL \\ S \leftarrow S-1 \\ After executing the above, if addressing mode is ABS, \\ PCL \leftarrow ADL \\ PCH \leftarrow ADH \\ if addressing mode is SP, \\ PCL \leftarrow ADL \\ PCH \leftarrow FF \\ If addressing mode is ZP, IND, \\ PCL \leftarrow M(00, ADL) \\ PCH \leftarrow M(00, ADL) \\ PCH \leftarrow M(00, ADL + 1) \end{array}$	This instruction stores the contents of the PC in the stack, then jumps to the address designated by the following addressing modes: Absolute Special Page Zero Page Indirect Absolute																		
LDA (Note 2)	When T = 0 $A \leftarrow M$ When T = 1 $M(X) \leftarrow M$	When T = 0, this instruction transfers the contents of M to A. When T = 1, this instruction transfers the contents of M to $(M(X))$. The contents of A remain unchanged, but status flags are changed. $M(X)$ represents the contents of memory where is indicated by X.				A9	2	2							A5	3	2			
LDM	M ← nn	This instruction loads the immediate value in M.													зС	4	3			
LDX	$X \leftarrow M$	This instruction loads the contents of M in X.				A2	2	2							A6	3	2			
LDY	$Y \leftarrow M$	This instruction loads the contents of M in Y.				A0	2	2							A4	3	2			

														Ad	dres	sing	g mo	ode															F	roc	esso	or sta	atus	reg	giste	r
Z	ZP,)	X	Z	ZP,	Y		ABS	3	А	BS,	Х	A	BS,	Υ		IND		ZF	P, IN	ID	١N	ND,	X	١N	۱D,	Υ	ı	REL			SP		7	6	5	4	3	2	1	0
OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	N	V	Т	В	D	ı	Z	С
																																	N	•	•	•	•	٠	Z	•
																																	N	•	•	•	•	•	Z	•
55	4	2				4D	4	3	5D	5	3	59	5	3							41	6	2	51	6	2							Z	•	•	•	•	•	Z	•
F6	6	2				EE	6	3	FE	7	3																						N	•	•	•	•	•	Z	•
																																	N	•	•	•	•	•	Z	•
																																	N	•	•	•	•	•	Z	•
						4C	3	3							6C	5	3	B2	4	2													•	•	•	•	•	•	•	•
						20	6	3										02	7	2										22	5	2	•	•	•	•	•	•	•	•
B5	4	2				AD	4	3	BD	5	3	В9	5	3							A1	6	2	B1	6	2							N	•	•	•	•	•	Z	•
																																	•	•	•	•	•	•	•	•
			В6	4	2	ΑE	4	3				BE	5	3																			N	•	•	•	•	•	Z	•
B4	4	2				AC	4	3	вс	5	3																						Z	•	•	•	•	•	Z	•

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									P	Addr	essi	ng	mod	le						
Symbol	Function	Details		IMF	,		IMN	1		Α		E	BIT,	A		ZP		ВІ	T, Z	P.
			ОР	n	#	ОР	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#
LSR	7 0 0→□→□	This instruction shifts either A or M one bit to the right such that bit 7 of the result always is set to 0, and the bit 0 is stored in C.							4A	2	1				46	5	2			
NOP	PC ← PC + 1	This instruction adds one to the PC but does no otheroperation.	EA	2	1															
ORA (Note 1)	When T = 0 $A \leftarrow A \lor M$ $When T = 1$ $M(X) \leftarrow M(X) \lor M$	When T = 0, this instruction transfers the contents of A and M to the ALU which performs a bit-wise "OR", and stores the result in A. When T = 1, this instruction transfers the contents of M(X) and the M to the ALU which performs a bit-wise OR, and stores the result in M(X). The contents of A remain unchanged, but status flags are changed. M(X) represents the contents of memory where is indicated by X.				09	2	2							05	3	2			
PHA	S ← S − 1	This instruction pushes the contents of A to the memory location designated by S, and decrements the contents of S by one.	48	3	1															
PHP	$\begin{array}{c} M(S) \leftarrow PS \\ S \leftarrow S - 1 \end{array}$	This instruction pushes the contents of PS to the memory location designated by S and decrements the contents of S by one.	08	3	1															
PLA	$\begin{array}{c} S \leftarrow S+1 \\ A \leftarrow M(S) \end{array}$	This instruction increments S by one and stores the contents of the memory designated by S in A.	68	4	1															
PLP	$\begin{array}{c} S \leftarrow S+1 \\ PS \leftarrow M(S) \end{array}$	This instruction increments S by one and stores the contents of the memory location designated by S in PS.	28	4	1															
ROL	7 0 ← C←	This instruction shifts either A or M one bit left through C. C is stored in bit 0 and bit 7 is stored in C.							2A	2	1				26	5	2			
ROR	7 0 C	This instruction shifts either A or M one bit right through C. C is stored in bit 7 and bit 0 is stored in C.							6A	2	1				66	5	2			
RRF	7 0	This instruction rotates 4 bits of the M content to the right.													82	8	2			
RTI	$\begin{split} S \leftarrow S + 1 \\ PS \leftarrow M(S) \\ S \leftarrow S + 1 \\ PCL \leftarrow M(S) \\ S \leftarrow S + 1 \\ PCH \leftarrow M(S) \end{split}$	This instruction increments S by one, and stores the contents of the memory location designated by S in PS. S is again incremented by one and stores the contents of the memory location designated by S in PCL. S is again incremented by one and stores the contents of memory location designated by S in PCH.	40	6	1															
RTS	$S \leftarrow S + 1$ $PCL \leftarrow M(S)$ $S \leftarrow S + 1$ $PCH \leftarrow M(S)$ $(PC) \leftarrow (PC) + 1$	This instruction increments S by one and stores the contents of the memory location designated by S in PCL. S is again incremented by one and the contents of the memory location is stored in PCH. PC is incremented by 1.	60	6	1															

						_								Ad	dres	ssin	g m	ode			_			_			_			_			-	roc	ess	or st	atus	re	gist
_	Έ, λ		-	ZP,	_	+	AB:	1	-	BS,	1	-	BS,	_		IND		\vdash	P, IN		-	ND,	_	_	ND,			REL		⊢	SP	_	7	6	5	4	3	2	1
DP 56	6	2	OP	n	#	OP 4E	+	+	OP 5E			OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	OP	n	#	0	•	•	•	D •	•	Z
																																	•	•	•	•	•	•	•
15	4	2				00	0 4	3	1D	5	3	19	5	3							01	6	2	11	6	2							N	•	•	•	•	•	Z
																																	•	•	•	•	•	•	•
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																																	N	•	•	•	•	•	Z
																																		(Va	lue	save	ed ir	n sta	ack)
36	6	2				2E	6	3	3E	7	3																						N	•	•	•	•	•	Z
'6	6	2				6E	6	3	7E	7	3																						N	•	•	•	•	•	Z
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																																		(Va	lue	save	ed ir	n sta	ack)
																																	•	•	•	•	•	•	•

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									Α	ddr	essi	ing r	nod	е						
Symbol	Function	Details		IMP)		IMN	1		Α		В	IT,	A		ΖP		ВІ	T, Z	Р
			ОР	n	#	OF	n	#	OP	n	#	ОР	n	#	OP	n	#	OP	n	#
SBC (Note 1) (Note 5)	When T = 0 $A \leftarrow A - M - \overline{C}$ When T = 1 $M(X) \leftarrow M(X) - M - \overline{C}$	When T = 0, this instruction subtracts the value of M and the complement of C from A, and stores the results in A and C. When T = 1, the instruction subtracts the contents of M and the complement of C from the contents of M(X), and stores the results in M(X) and C. A remain unchanged, but status flag are changed. M(X) represents the contents of memory where is indicated by X.				E9	2	2							E5	3	2			
SEB	Ai or Mi ← 1	This instruction sets the designated bit i of A or M.										0 <u>В</u> 20і	2	1				0F 20i	5	2
SEC	C ← 1	This instruction sets C.	38	2	1															
SED	D ← 1	This instruction set D.	F8	2	1															
SEI	I ← 1	This instruction set I.	78	2	1															
SET	T ← 1	This instruction set T.	32	2	1															
STA	$M \leftarrow A$	This instruction stores the contents of A in M. The contents of A does not change.													85	4	2			
STP		This instruction resets the oscillation control F/F and the oscillation stops. Reset or interrupt input is needed to wake up from this mode.	42	2	1															
STX	$M \leftarrow X$	This instruction stores the contents of X in M. The contents of X does not change.													86	4	2			
STY	$M \leftarrow Y$	This instruction stores the contents of Y in M. The contents of Y does not change.													84	4	2			
TAX	$X \leftarrow A$	This instruction stores the contents of A in X. The contents of A does not change.	AA	2	1															
TAY	$Y \leftarrow A$	This instruction stores the contents of A in Y. The contents of A does not change.	A8	2	1															
TST	M = 0?	This instruction tests whether the contents of M are "0" or not and modifies the N and Z.													64	3	2			
TSX	X←S	This instruction transfers the contents of S in X.	ВА	2	1															
TXA	$A \leftarrow X$	This instruction stores the contents of X in A.	8A	2	1															
TXS	$S \leftarrow X$	This instruction stores the contents of X in S.	9A	2	1															
TYA	$A \leftarrow Y$	This instruction stores the contents of Y in A.	98	2	1															
WIT		The WIT instruction stops the internal clock but not the oscillation of the oscillation circuit is not stopped. CPU starts its function after the Timer X over flows (comes to the terminal count). All registers or internal memory contents except Timer X will not change during this mode. (Of course needs VDD).	C2	2	1															

Г														Ad	dres	ssino	g me	ode													F	Proc	esso	or st	atus	s rec	iste	er
	 Έ, λ		7	ZP,	Υ	Г	ABS	 S	I A	BS,	X	A	BS,		_	IND		_	P, IN	ND	I IN	ND,	X	I IN	ND,	Y		REL		SP	7	6	1	4	3	2	1	0
OP	n		OP	Т	_	OP	1	1	ОР	т —	1	OP		т —	OP		_	OP	1	Г	OP	т —		OP			OP	n	OP	1	N	V	Т	В	D	1	Z	С
F5	4	2				ED	-	-	FD	_	_	F9	5	3	-					-	E1	_	_	F1	6	2	-				N	V	•	•	•	•	 Z	С
																															•	•	•	•	•	•	•	•
																															•	•	•	•	•	•	•	1
																															٠	•	•	•	1	•	•	•
																															•	•	•	•	•	1	•	•
																									_						•	•	1	•	•	•	•	•
95	5	2				8D	5	3	9D	6	3	99	6	3							81	7	2	91	7	2					•	•	•	•	•	•	•	•
																															•	•	Ŀ	•	•	•	•	•
			96	5	2	8E	5	3																							•	•	•	•	•	•	•	•
94	5	2				8C	5	3																							•	•	•	•	•	•	•	•
																															N	•	•	•	•	•	Z	•
																															N N	•	•	•	•	•	Z Z	•
																															N	•	•	•	•	•	Z	•
																															N	•		•	•	•	Z	•
																															•	•	•	•	•	•	•	•
																															N	•	•	•	•	•	Z	•
																															•	•	•	•	•	•	•	•

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Notes 1: The number of cycles "n" is increased by 3 when T is 1.
2: The number of cycles "n" is increased by 2 when T is 1.
3: The number of cycles "n" is increased by 1 when T is 1.
4: The number of cycles "n" is increased by 2 when branching has occurred.
5: N, V, and Z flags are invalid in decimal operation mode.

3.10 Machine instructions

Symbol	Contents	Symbol	Contents
IMP	Implied addressing mode	+	Addition
IMM	Immediate addressing mode	_	Subtraction
A	Accumulator or Accumulator addressing mode	Λ	Logical OR
BIT, A	Accumulator bit addressing mode	V	Logical AND
BIT, A, R	Accumulator bit relative addressing mode	¥	Logical exclusive OR
ZP	Zero page addressing mode	_	Negation
BIT, ZP	Zero page bit addressing mode	←	Shows direction of data flow
BIT, ZP, R	Zero page bit relative addressing mode	X	Index register X
ZP, X	Zero page X addressing mode	Y	Index register Y
ZP, Y	Zero page Y addressing mode	S	Stack pointer
ABS	Absolute addressing mode	PC	Program counter
ABS, X	Absolute X addressing mode	PS	Processor status register
ABS, Y	Absolute Y addressing mode	РСн	8 high-order bits of program counter
IND	Indirect absolute addressing mode	PCL	8 low-order bits of program counter
		ADH	8 high-order bits of address
ZP, IND	Zero page indirect absolute addressing mode	ADL	8 low-order bits of address
		FF	FF in Hexadecimal notation
IND, X	Indirect X addressing mode	nn	Immediate value
IND, Y	Indirect Y addressing mode	ZZ	Zero page address
REL	Relative addressing mode	M	Memory specified by address designation of any ad-
SP	Special page addressing mode		dressing mode
С	Carry flag	M(X)	Memory of address indicated by contents of index
Z	Zero flag		register X
1	Interrupt disable flag	M(S)	Memory of address indicated by contents of stack
D	Decimal mode flag		pointer
В	Break flag	M(ADH, ADL)	Contents of memory at address indicated by ADH and
T	X-modified arithmetic mode flag		ADL, in ADH is 8 high-order bits and ADL is 8 low-or-
V	Overflow flag		der bits.
N	Negative flag	M(00, ADL)	Contents of address indicated by zero page ADL
		Ai	Bit i (i = 0 to 7) of accumulator
		Mi	Bit i (i = 0 to 7) of memory
		OP	Opcode
		n	Number of cycles
		#	Number of bytes

3.11 List of instruction code

	D3 - D0	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1 110	1111
D7 – D4	Hexadecimal notation	0	1	2	3	4	5	6	7	8	9	А	В	С	D	E	F
0000	0	BRK	ORA IND, X	JSR ZP, IND	BBS 0, A	_	ORA ZP	ASL ZP	BBS 0, ZP	PHP	ORA IMM	ASL A	SEB 0, A	_	ORA ABS	ASL ABS	SEB 0, ZP
0001	1	BPL	ORA IND, Y	CLT	BBC 0, A	_	ORA ZP, X	ASL ZP, X	BBC 0, ZP	CLC	ORA ABS, Y	DEC A	CLB 0, A	_	ORA ABS, X	ASL ABS, X	CLB 0, ZP
0010	2	JSR ABS	AND IND, X	JSR SP	BBS 1, A	BIT ZP	AND ZP	ROL ZP	BBS 1, ZP	PLP	AND IMM	ROL A	SEB 1, A	BIT ABS	AND ABS	ROL ABS	SEB 1, ZP
0011	3	ВМІ	AND IND, Y	SET	BBC 1, A	_	AND ZP, X	ROL ZP, X	BBC 1, ZP	SEC	AND ABS, Y	INC A	CLB 1, A	LDM ZP	AND ABS, X	ROL ABS, X	CLB 1, ZP
0100	4	RTI	EOR IND, X	STP	BBS 2, A	COM ZP	EOR ZP	LSR ZP	BBS 2, ZP	РНА	EOR IMM	LSR A	SEB 2, A	JMP ABS	EOR ABS	LSR ABS	SEB 2, ZP
0101	5	BVC	EOR IND, Y	_	BBC 2, A	_	EOR ZP, X	LSR ZP, X	BBC 2, ZP	CLI	EOR ABS, Y	_	CLB 2, A	_	EOR ABS, X	LSR ABS, X	CLB 2, ZP
0110	6	RTS	ADC IND, X	_	BBS 3, A	TST ZP	ADC ZP	ROR ZP	BBS 3, ZP	PLA	ADC IMM	ROR A	SEB 3, A	JMP IND	ADC ABS	ROR ABS	SEB 3, ZP
0111	7	BVS	ADC IND, Y	_	BBC 3, A	_	ADC ZP, X	ROR ZP, X	BBC 3, ZP	SEI	ADC ABS, Y	_	CLB 3, A	_	ADC ABS, X	ROR ABS, X	CLB 3, ZP
1000	8	BRA	STA IND, X	RRF ZP	BBS 4, A	STY ZP	STA ZP	STX ZP	BBS 4, ZP	DEY	_	TXA	SEB 4, A	STY ABS	STA ABS	STX ABS	SEB 4, ZP
1001	9	всс	STA IND, Y	_	BBC 4, A	STY ZP, X	STA ZP, X	STX ZP, Y	BBC 4, ZP	TYA	STA ABS, Y	TXS	CLB 4, A	_	STA ABS, X	1	CLB 4, ZP
1010	А	LDY IMM	LDA IND, X	LDX IMM	BBS 5, A	LDY ZP	LDA ZP	LDX ZP	BBS 5, ZP	TAY	LDA IMM	TAX	SEB 5, A	LDY ABS	LDA ABS	LDX ABS	SEB 5, ZP
1011	В	BCS	LDA IND, Y	JMP ZP, IND	BBC 5, A	LDY ZP, X	LDA ZP, X	LDX ZP, Y	BBC 5, ZP	CLV	LDA ABS, Y	TSX	CLB 5, A	LDY ABS, X	LDA ABS, X	LDX ABS, Y	CLB 5, ZP
1100	С	CPY	CMP IND, X	WIT	BBS 6, A	CPY ZP	CMP ZP	DEC ZP	BBS 6, ZP	INY	CMP IMM	DEX	SEB 6, A	CPY ABS	CMP ABS	DEC ABS	SEB 6, ZP
1101	D	BNE	CMP IND, Y	_	BBC 6, A	_	CMP ZP, X	DEC ZP, X	BBC 6, ZP	CLD	CMP ABS, Y	_	CLB 6, A	_	CMP ABS, X	DEC ABS, X	CLB 6, ZP
1110	Е	CPX IMM	SBC IND, X	_	BBS 7, A	CPX ZP	SBC ZP	INC ZP	BBS 7, ZP	INX	SBC IMM	NOP	SEB 7, A	CPX ABS	SBC ABS	INC ABS	SEB 7, ZP
1111	F	BEQ	SBC IND, Y	_	BBC 7, A	_	SBC ZP, X	INC ZP, X	BBC 7, ZP	SED	SBC ABS, Y	_	CLB 7, A	_	SBC ABS, X	INC ABS, X	CLB 7, ZP

	: 3-byte	instruction
--	----------	-------------

: 2-byte instruction

: 1-byte instruction

3.12 SFR memory map

000016	Port P0 (P0)	002016	
000116	Port P0 direction register (P0D)	002116	
000216	Port P1 (P1)	002216	
000316	Port P1 direction register (P1D)	002316	
000416	Port P2 (P2)	002416	
000516	Port P2 direction register (P2D)	002516	
000616	Port P3 (P3)	002616	
000716	Port P3 direction register (P3D)	002716	
000816		002816	Prescaler 12 (PRE12)
000916		002916	Timer 1 (T1)
000A16		002A16	Timer 2 (T2)
000B16		002B ₁₆	Timer X mode register (TM)
000C16		002C16	Prescaler X (PREX)
000D16		002D16	Timer X (TX)
000E16		002E16	Timer count source setting register (TCSS)
000F16		002F16	
001016		003016	Serial I/O2 control register (SIO2CON)
001116		003116	Serial I/O2 register (SIO2)
001216		003216	
001316		003316	
001416		003416	A-D control register (ADCON)
001516		003516	A-D conversion register (low-order) (ADL)
001616	Pull-up control register (PULL)	003616	A-D conversion register (high-order) (ADH)
001716	Port P1P3 control register (P1P3C)	003716	
001816	Transmit/Receive buffer register (TB/RB)	003816	MISRG
001916	Serial I/O1 status register (SIO1STS)	003916	Watchdog timer control register (WDTCON)
001A16	Serial I/O1 control register (SIO1CON)	003A16	Interrupt edge selection register (INTEDGE)
001B ₁₆	UART control register (UARTCON)	003B ₁₆	CPU mode register (CPUM)
001C ₁₆	Baud rate generator (BRG)	003C16	Interrupt request register 1 (IREQ1)
001D ₁₆		003D16	
001E16		003E16	Interrupt control register 1 (ICON1)
001F16		003F16	
	<u> </u>		

3.13 Pin configurations

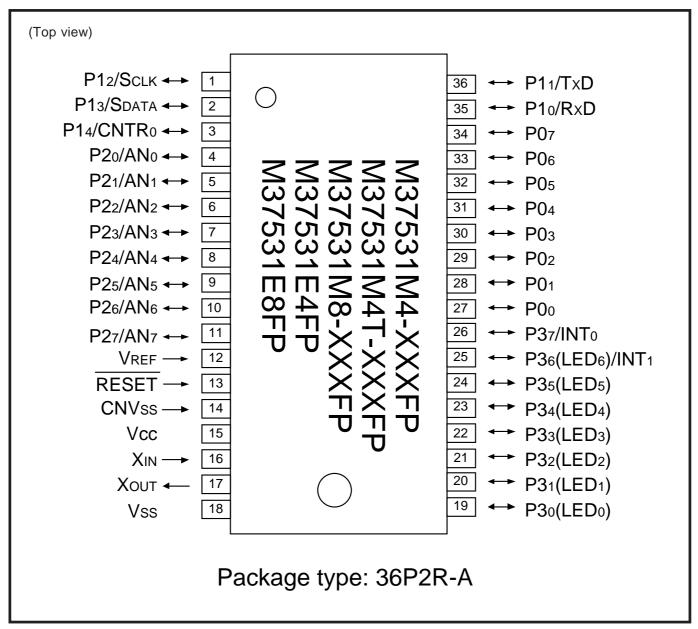


Fig. 3.13.1 Pin configuration (36P2R package type)

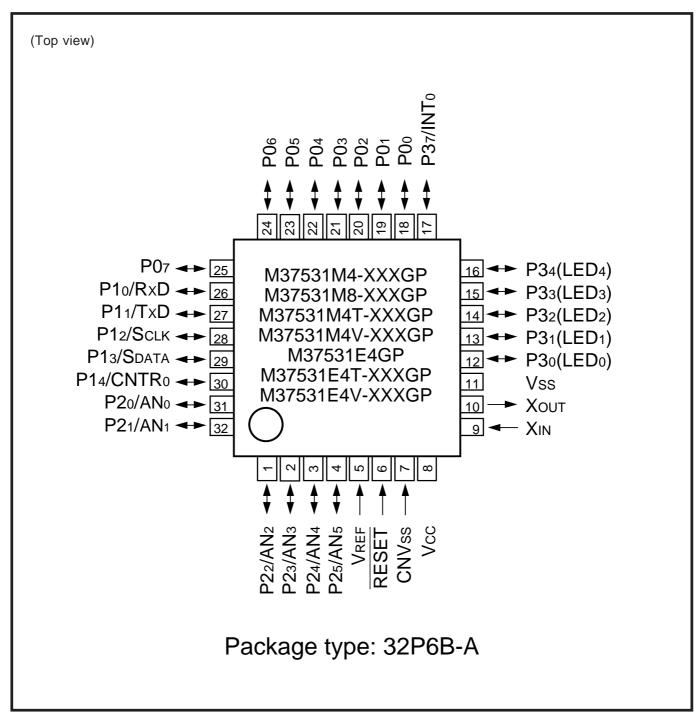


Fig. 3.13.2 Pin configuration (32P6B package type)

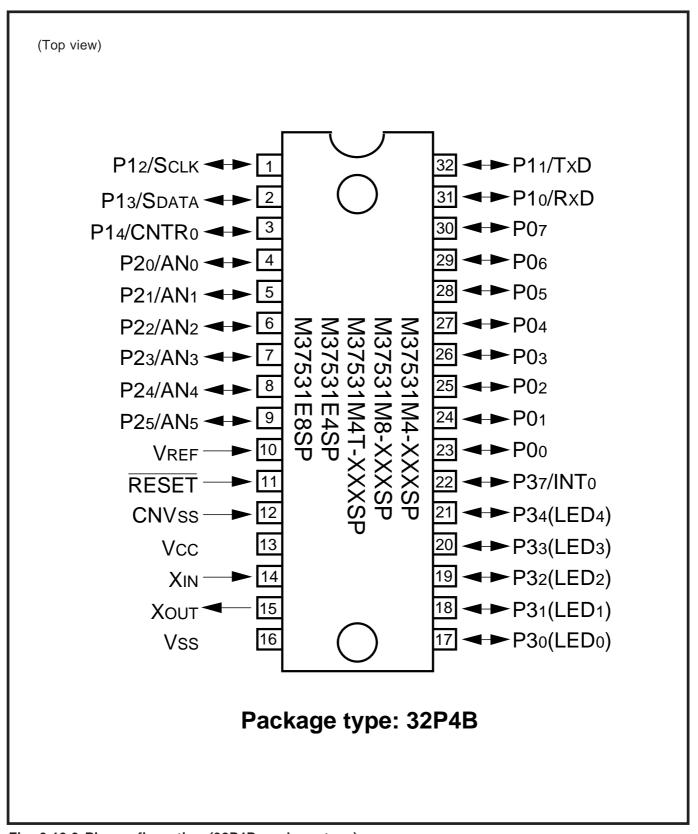


Fig. 3.13.3 Pin configuration (32P4B package type)

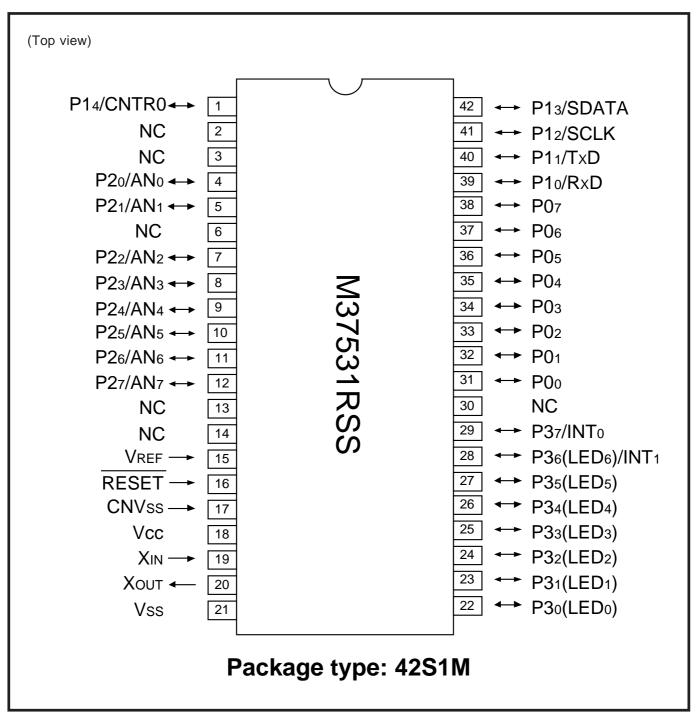


Fig. 3.13.4 M37531RSS pin configuration

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